Research Faculty Summit 2018

Systems | Fueling future disruptions

RowHammer and Beyond

RowHammer and Other Issues We May Face as Memory Becomes Denser

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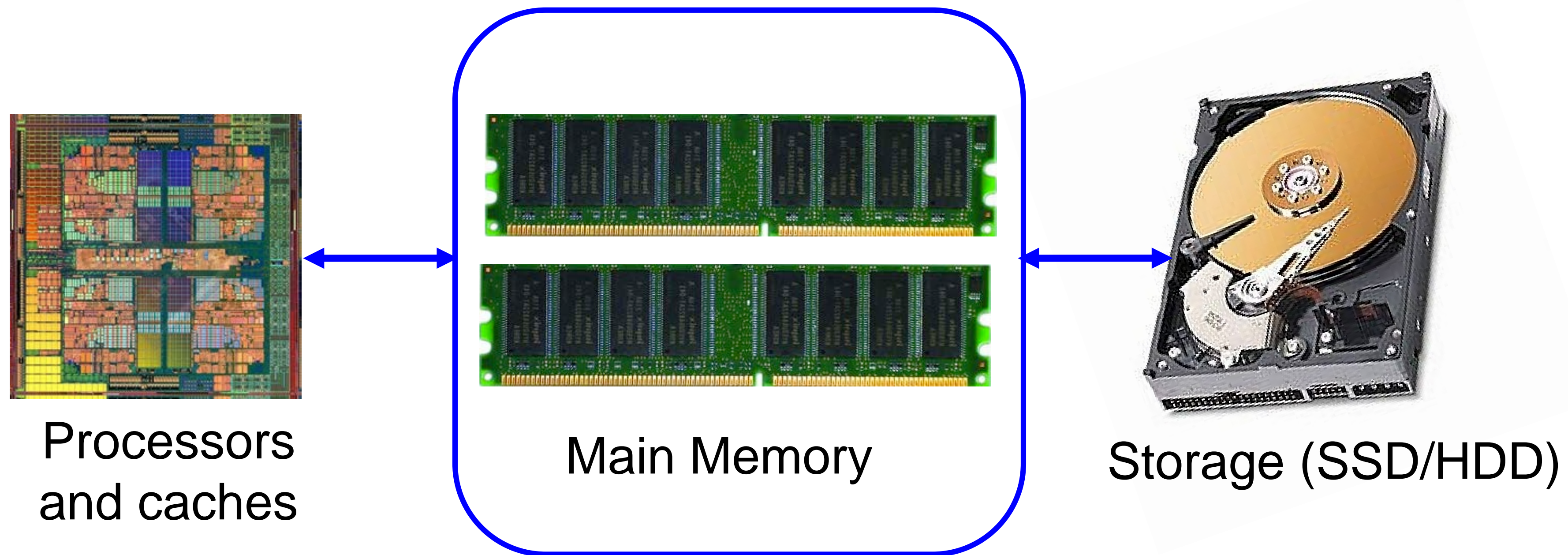
Carnegie Mellon

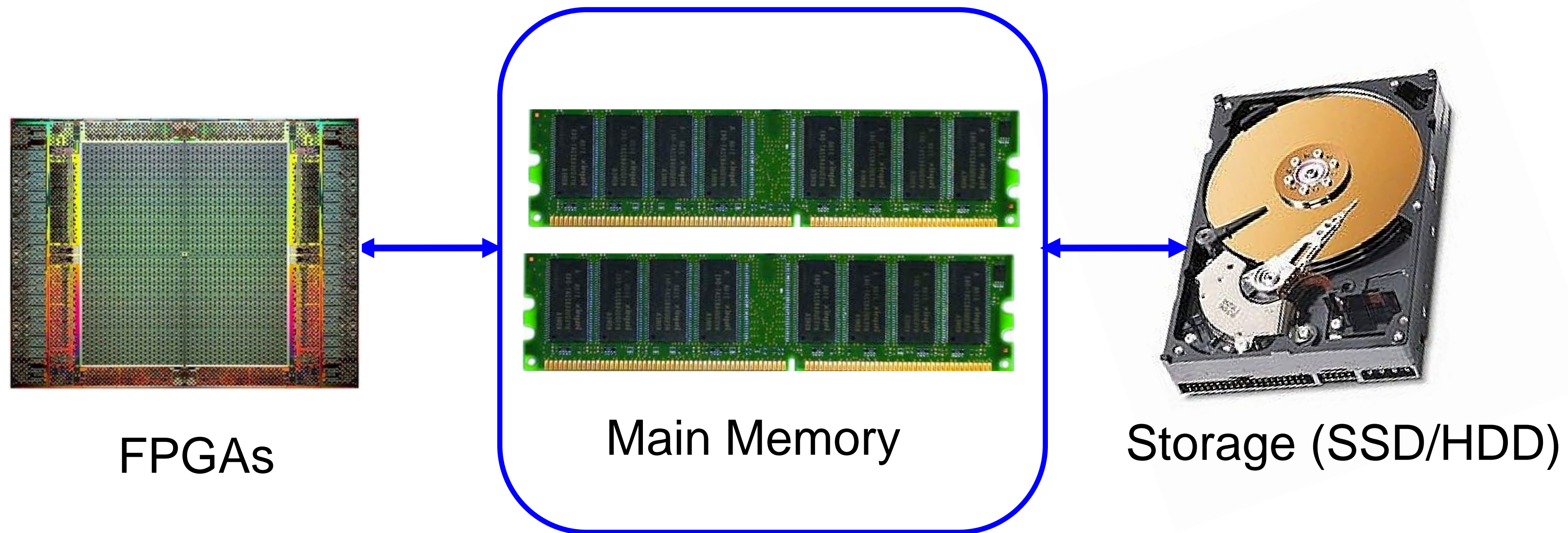
The Main Memory System



- Main memory is a critical component of all computing systems: server, mobile, embedded, desktop, sensor

- Main memory system must scale (in *size*, *technology*, *efficiency*, *cost*, and *management algorithms*) to maintain performance growth and technology scaling benefits

The Main Memory System



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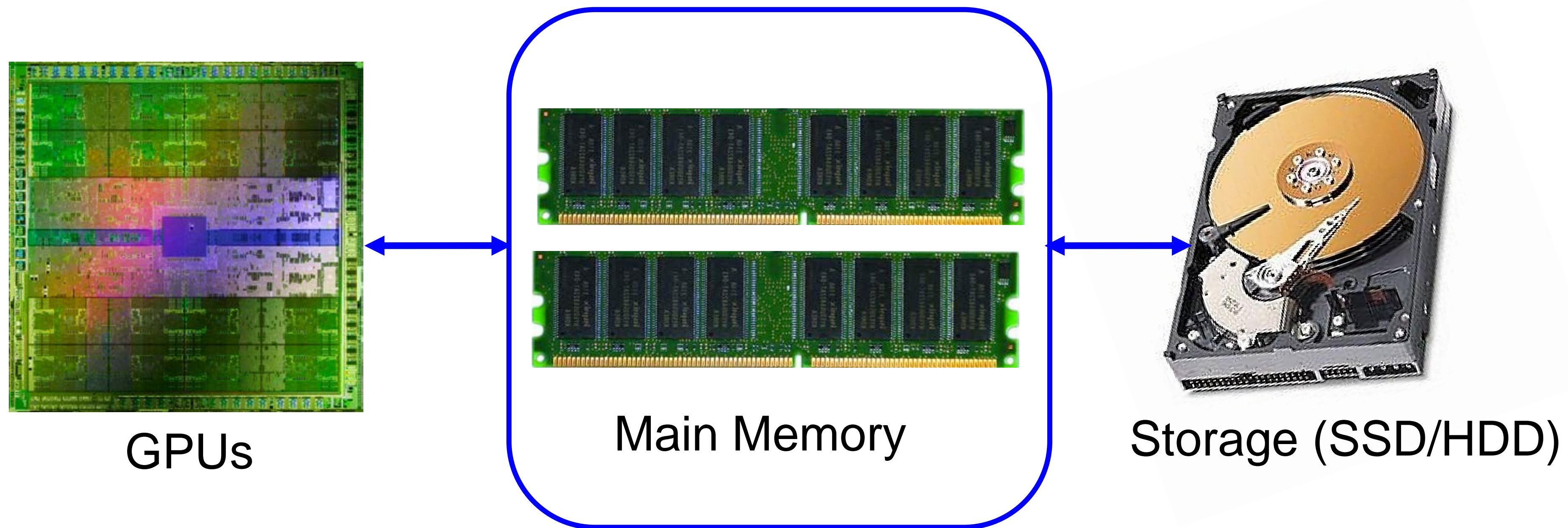

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Major Trends Affecting Main Memory (I)

- Need for main memory capacity, bandwidth, QoS increasing

- Main memory energy/power is a key system design concern

- DRAM technology scaling is ending

Major Trends Affecting Main Memory (II)

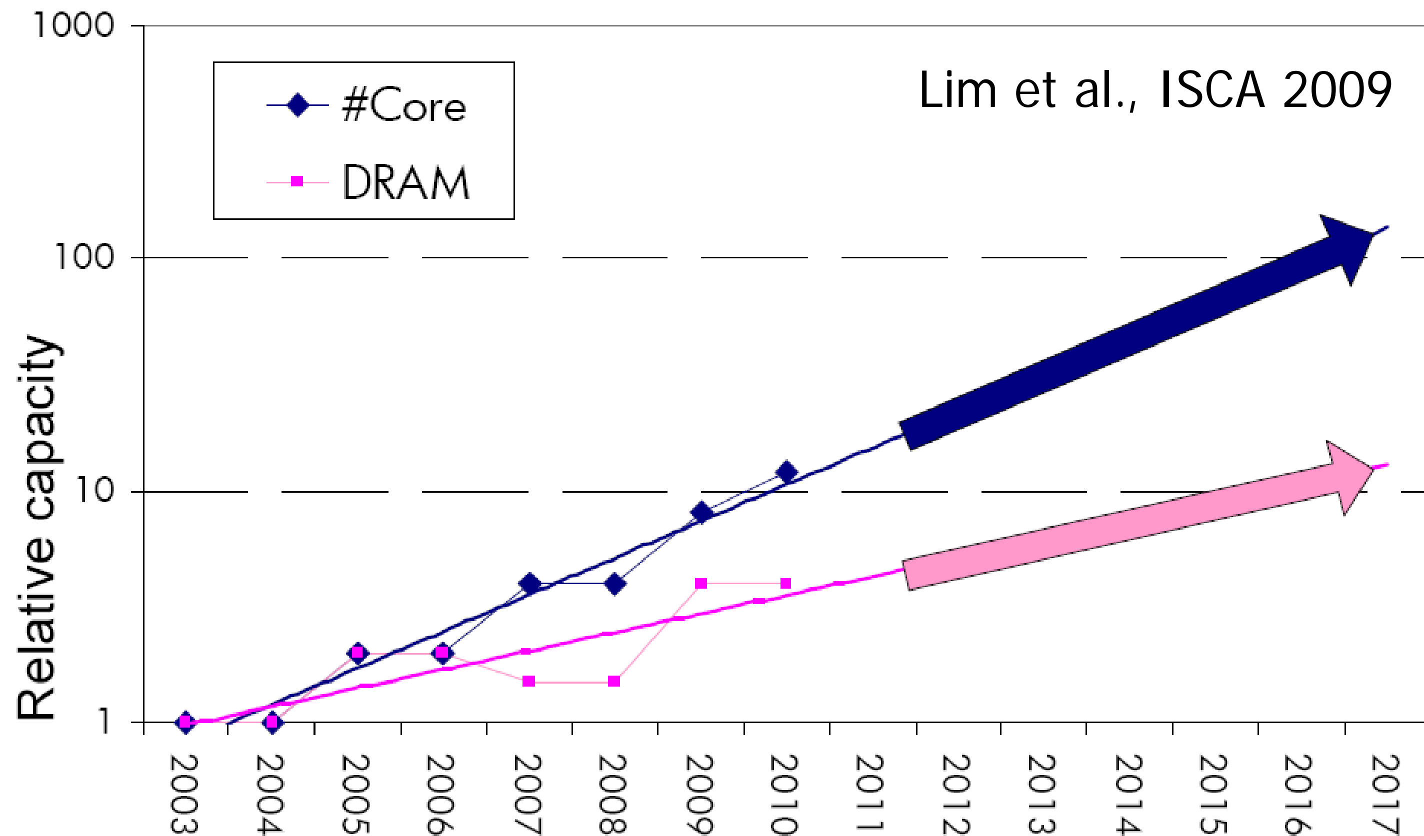
- Need for main memory capacity, bandwidth, QoS increasing
  - Multi-core: increasing number of cores/agents
  - Data-intensive applications: increasing demand/hunger for data
  - Consolidation: cloud computing, GPUs, mobile, heterogeneity

- Main memory energy/power is a key system design concern

- DRAM technology scaling is ending

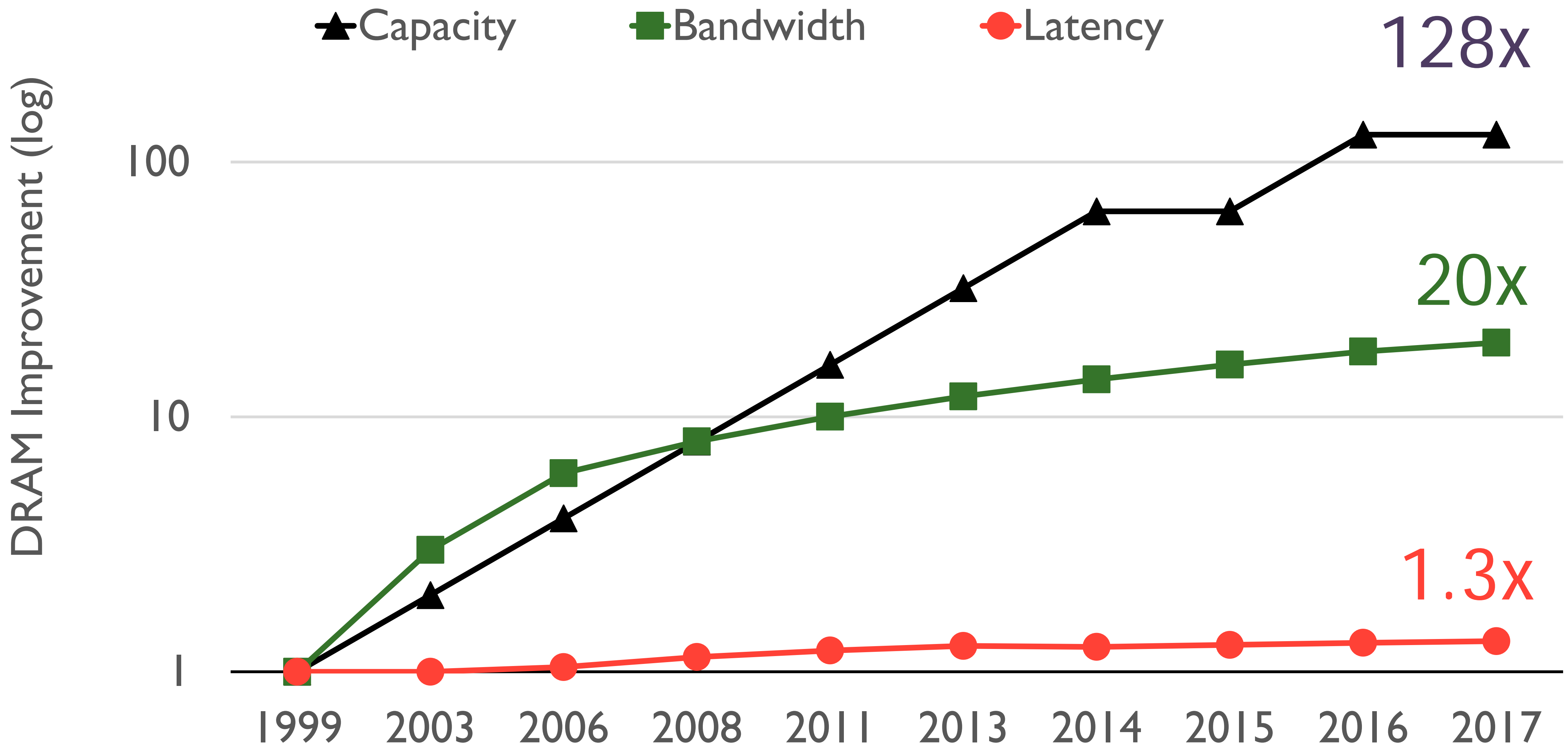
Consequence: The Memory Capacity Gap

Core count doubling ~ every 2 years
DRAM DIMM capacity doubling ~ every 3 years



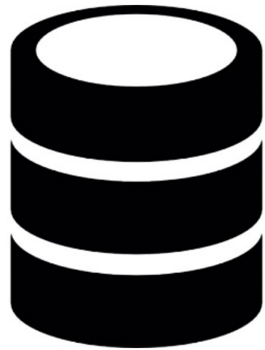
- *Memory capacity per core* expected to drop by 30% every two years
- Trends worse for *memory bandwidth per core*!

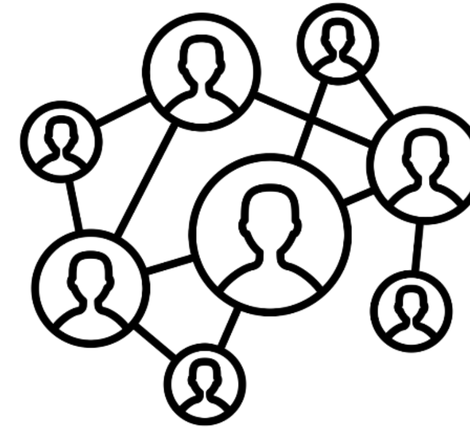
Example: Capacity, Bandwidth & Latency



Memory latency remains almost constant

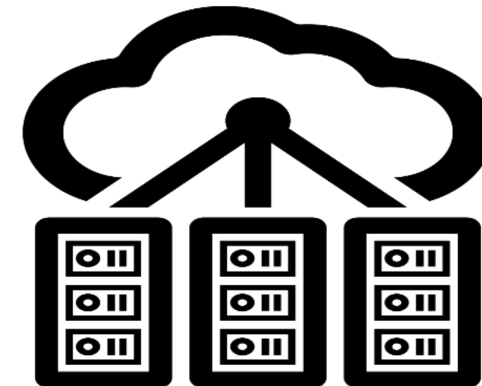
DRAM Is Critical for Performance





In-memory Databases
[Mao+, EuroSys'12;
Clapp+ (**Intel**), IISWC'15]

Graph/Tree Processing
[Xu+, IISWC'12; Umuroglu+, FPL'15]



In-Memory Data Analytics
[Clapp+ (**Intel**), IISWC'15;
Awan+, BDCloud'15]

Datacenter Workloads
[Kanev+ (**Google**), ISCA'15]

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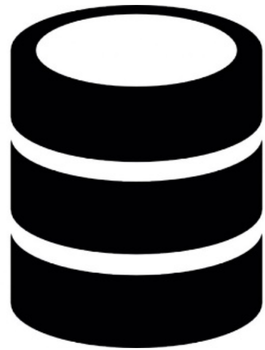

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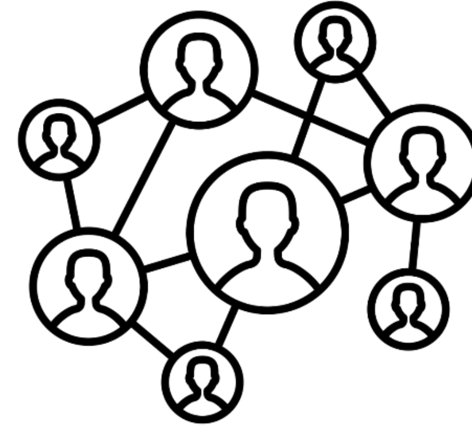

Graph/Tree Processing

Memory → performance bottleneck

In-Memory Data Analytics

[Clapp+ (**Intel**), IISWC'15;
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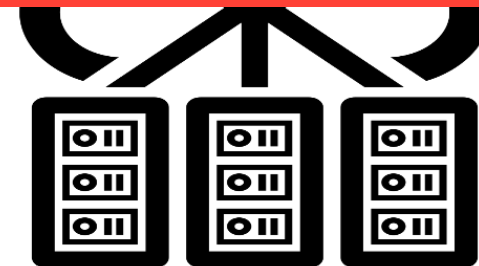


Datacenter Workloads

[Kanev+ (**Google**), ISCA'15]

Major Trends Affecting Main Memory (III)

- Need for main memory capacity, bandwidth, QoS increasing

- Main memory energy/power is a key system design concern
  - ~40-50% energy spent in off-chip memory hierarchy [Lefurgy, IEEE Computer'03] >40% power in DRAM [Ware, HPCA'10][Paul,ISCA'15]
  - DRAM consumes power even when not used (periodic refresh)

- DRAM technology scaling is ending

Major Trends Affecting Main Memory (IV)

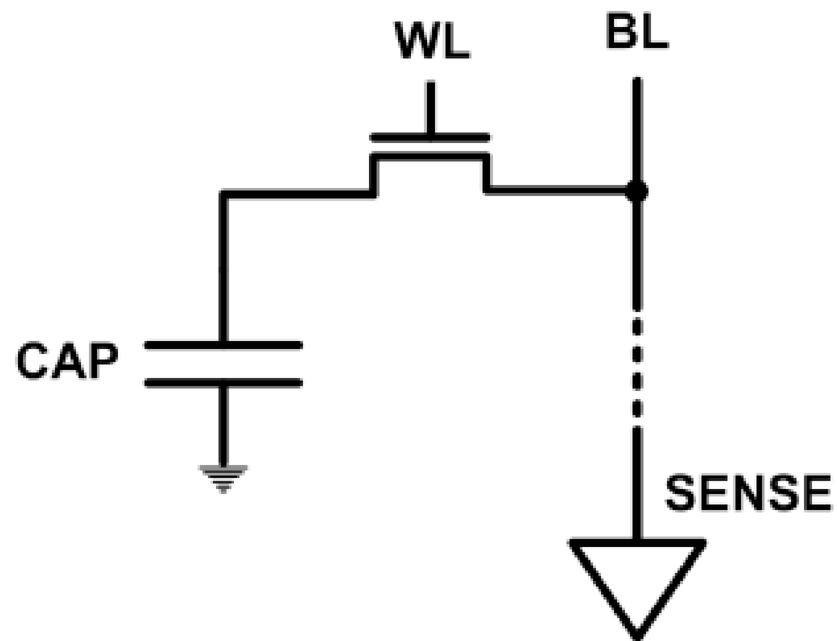
- Need for main memory capacity, bandwidth, QoS increasing

- Main memory energy/power is a key system design concern

- DRAM technology scaling is ending
  - ITRS projects DRAM will not scale easily below X nm
  - Scaling has provided many benefits:
    - higher capacity (density), lower cost, lower energy

The DRAM Scaling Problem

- DRAM stores charge in a capacitor (charge-based memory)
  - Capacitor must be large enough for reliable sensing
  - Access transistor should be large enough for low leakage and high retention time
  - Scaling beyond 40-35nm (2013) is challenging [ITRS, 2009]



- As DRAM cell becomes smaller, it becomes more vulnerable

Major Trends Affecting Main Memory (V)

- DRAM scaling has already become increasingly difficult
  - Increasing cell leakage current, reduced cell reliability, increasing manufacturing difficulties [Kim+ ISCA 2014], [Liu+ ISCA 2013], [Mutlu IMW 2013], [Mutlu DATE 2017]
  - **Difficult to significantly improve capacity, energy**

- **Emerging memory technologies** are promising

(e.g., RLDRAM, TL-DRAM)		
(e.g., LPDDR3, LPDDR4)		higher cost
(e.g., PCM, STTRAM, ReRAM, 3D Xpoint)		higher dynamic power lower endurance

Major Trends Affecting Main Memory (V)

- DRAM scaling has already become increasingly difficult
  - Increasing cell leakage current, reduced cell reliability, increasing manufacturing difficulties [Kim+ ISCA 2014], [Liu+ ISCA 2013], [Mutlu IMW 2013], [Mutlu DATE 2017]
  - **Difficult to significantly improve capacity, energy**
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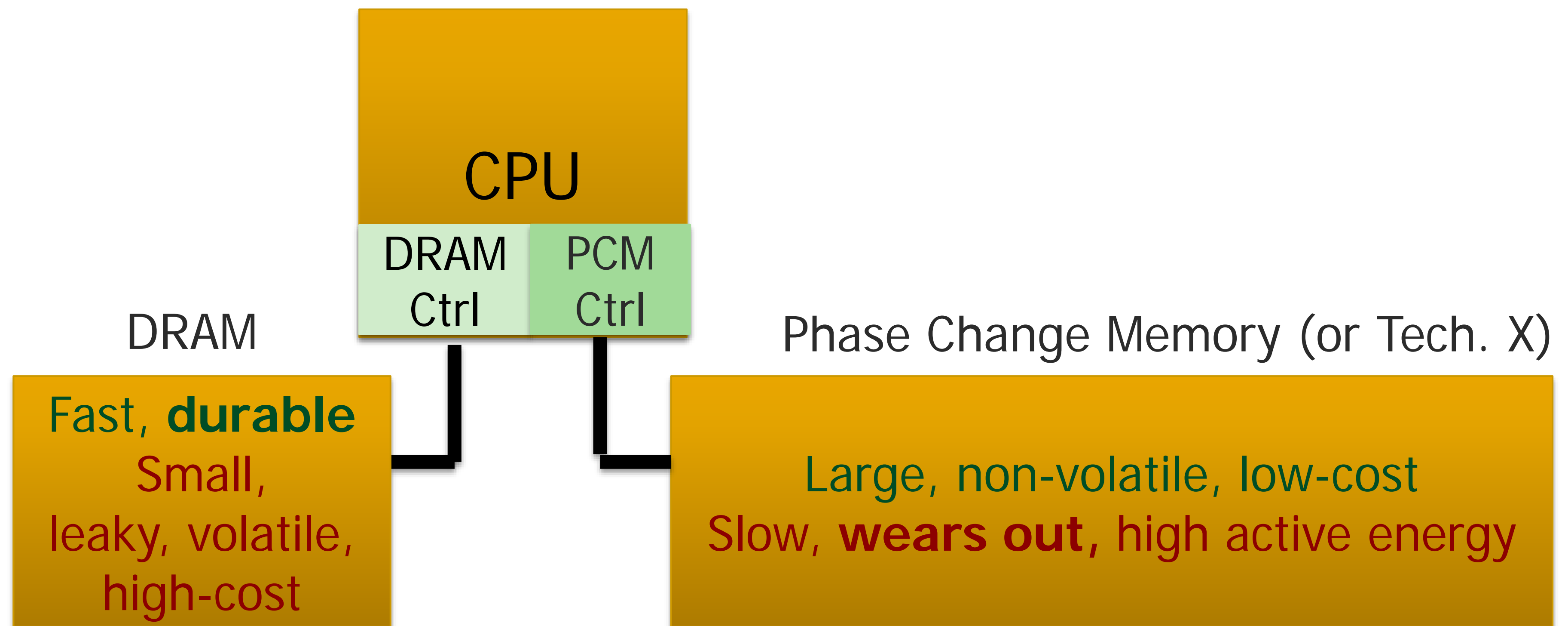
3D-Stacked DRAM	higher bandwidth	smaller capacity
Reduced-Latency DRAM (e.g., RL/TL-DRAM, FLY-RAM)	lower latency	higher cost
Low-Power DRAM (e.g., LPDDR3, LPDDR4, Voltron)	lower power	higher latency higher cost
Non-Volatile Memory (NVM) (e.g., PCM, STTRAM, ReRAM, 3D Xpoint)	larger capacity	higher latency higher dynamic power lower endurance

Major Trend: Hybrid Main Memory



Hardware/software manage data allocation and movement
to achieve the best of multiple technologies

Meza+, "Enabling Efficient and Scalable Hybrid Memories," IEEE Comp. Arch. Letters, 2012.

Yoon+, "Row Buffer Locality Aware Caching Policies for Hybrid Memories," ICCD 2012 Best Paper Award.

Agenda

- Major Trends Affecting Main Memory
- The Memory Scaling Problem, Its Consequences, Solutions
  - Rowhammer
  - Beyond Rowhammer: Future Reliability/Security Issues
  - Enabling Secure Systems
- Summary

Fixing the Memory Problem

- Secure/Reliable/Safe Architectures
- Energy-Efficient Architectures
  - Memory-centric (Data-centric) Architectures
- Low-Latency and QoS-Aware Architectures
- Specialized Architectures for Key Workloads

Maslow's (Human) Hierarchy of Needs

Maslow, "A Theory of Human Motivation," Psychological Review, 1943.

Maslow, "Motivation and Personality," Book, 1954-1970.

Self-actualization: achieving one's full potential, including creative activities

Esteem needs: prestige and feeling of accomplishment

Belongingness and love needs: intimate relationships, friends

Safety needs: security, safety

Physiological needs: food, water, warmth, rest

Self-fulfillment needs

Psychological needs

Basic needs

- We need to start with reliability and security…

Source: https://www.simplypsychology.org/maslow.html

Source: By User:Factoryjoe - Mazlow's Hierarchy of Needs.svg, CC BY-SA 3.0, https://commons.wikimedia.org/w/index.php?curid=7964065

How Reliable/Secure/Safe is This Bridge?

Source: http://www.technologystudent.com/struct1/tacom1.png

Collapse of the "Galloping Gertie"

Source: AP
http://www.wsdot.wa.gov/tnbhistory/connections/connections3.htm

How Secure Are These People?

Security is about preventing unforeseen consequences

Source: https://s-media-cache-ak0.pinimg.com/originals/48/09/54/4809543a9c7700246a0cf8acdae27abf.jpg

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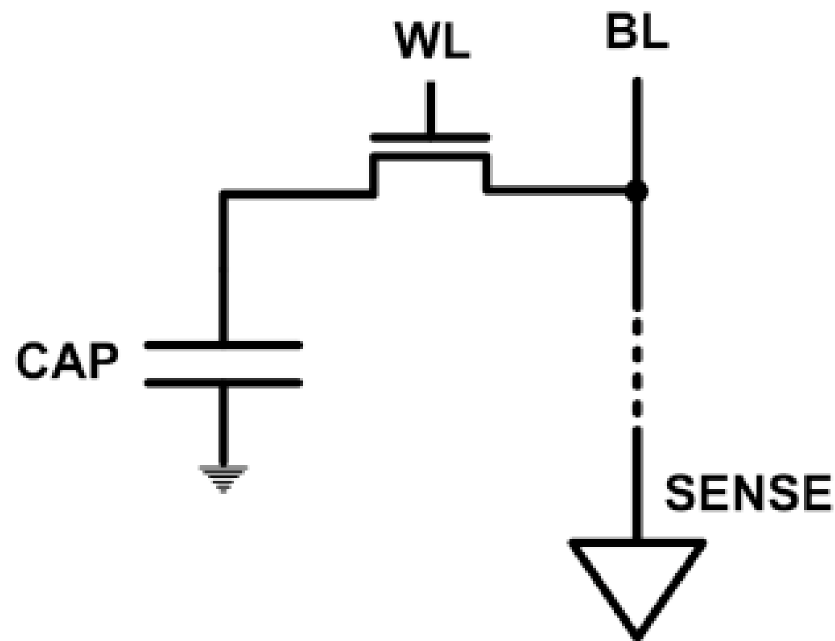
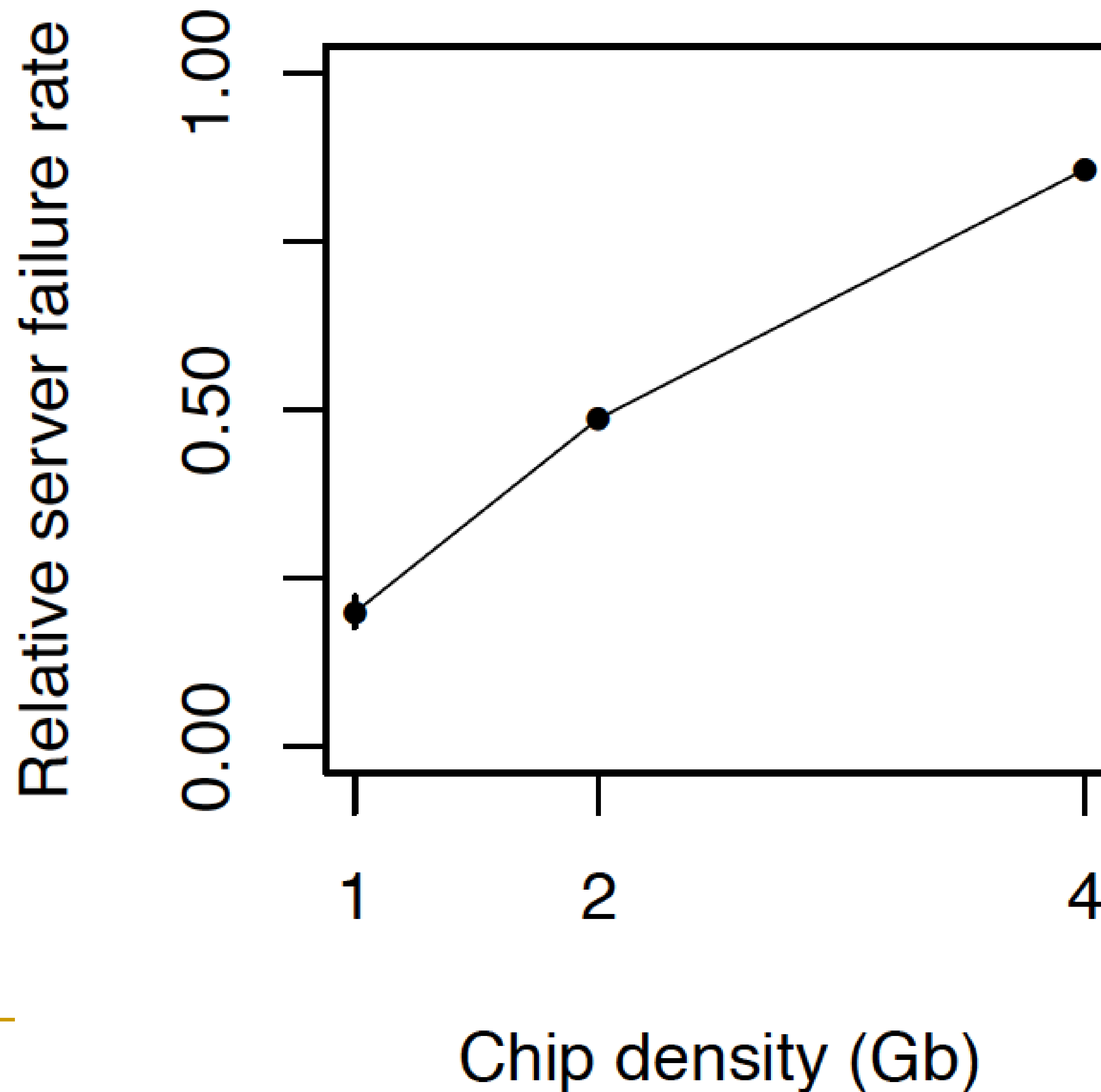


- DRAM capacity, cost, and energy/power hard to scale

As Memory Scales, It Becomes Unreliable

- Data from all of Facebook's servers worldwide
- Meza+, "Revisiting Memory Errors in Large-Scale Production Data Centers," DSN'15.



Intuition: quadratic increase in capacity

Large-Scale Failure Analysis of DRAM Chips

- Analysis and modeling of memory errors found in all of Facebook's server fleet

- Justin Meza, Qiang Wu, Sanjeev Kumar, and Onur Mutlu, **"Revisiting Memory Errors in Large-Scale Production Data Centers: Analysis and Modeling of New Trends from the Field"** *Proceedings of the 45th Annual IEEE/IFIP International Conference on Dependable Systems and Networks* ***(DSN)***, Rio de Janeiro, Brazil, June 2015.
[Slides (pptx) (pdf)] [DRAM Error Model]

Revisiting Memory Errors in Large-Scale Production Data Centers: Analysis and Modeling of New Trends from the Field

Justin Meza   Qiang Wu *   Sanjeev Kumar *   Onur Mutlu
Carnegie Mellon University   * Facebook, Inc.

Infrastructures to Understand Such Issues

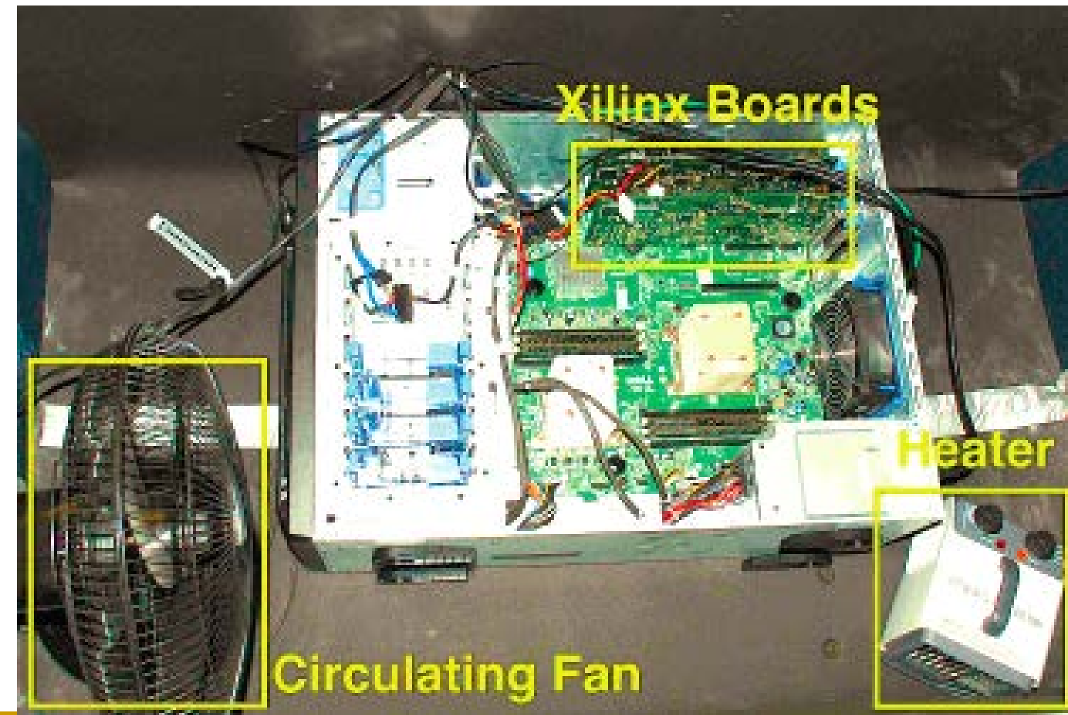
An Experimental Study of Data Retention Behavior in Modern DRAM Devices: Implications for Retention Time Profiling Mechanisms (Liu et al., ISCA 2013)

The Efficacy of Error Mitigation Techniques for DRAM Retention Failures: A Comparative Experimental Study (Khan et al., SIGMETRICS 2014)

Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors (Kim et al., ISCA 2014)

Adaptive-Latency DRAM: Optimizing DRAM Timing for the Common-Case (Lee et al., HPCA 2015)

AVATAR: A Variable-Retention-Time (VRT) Aware Refresh for DRAM Systems (Qureshi et al., DSN 2015)



Infrastructures to Understand Such Issues

Temperature Controller

FPGAs

Heater

FPGAs

PC

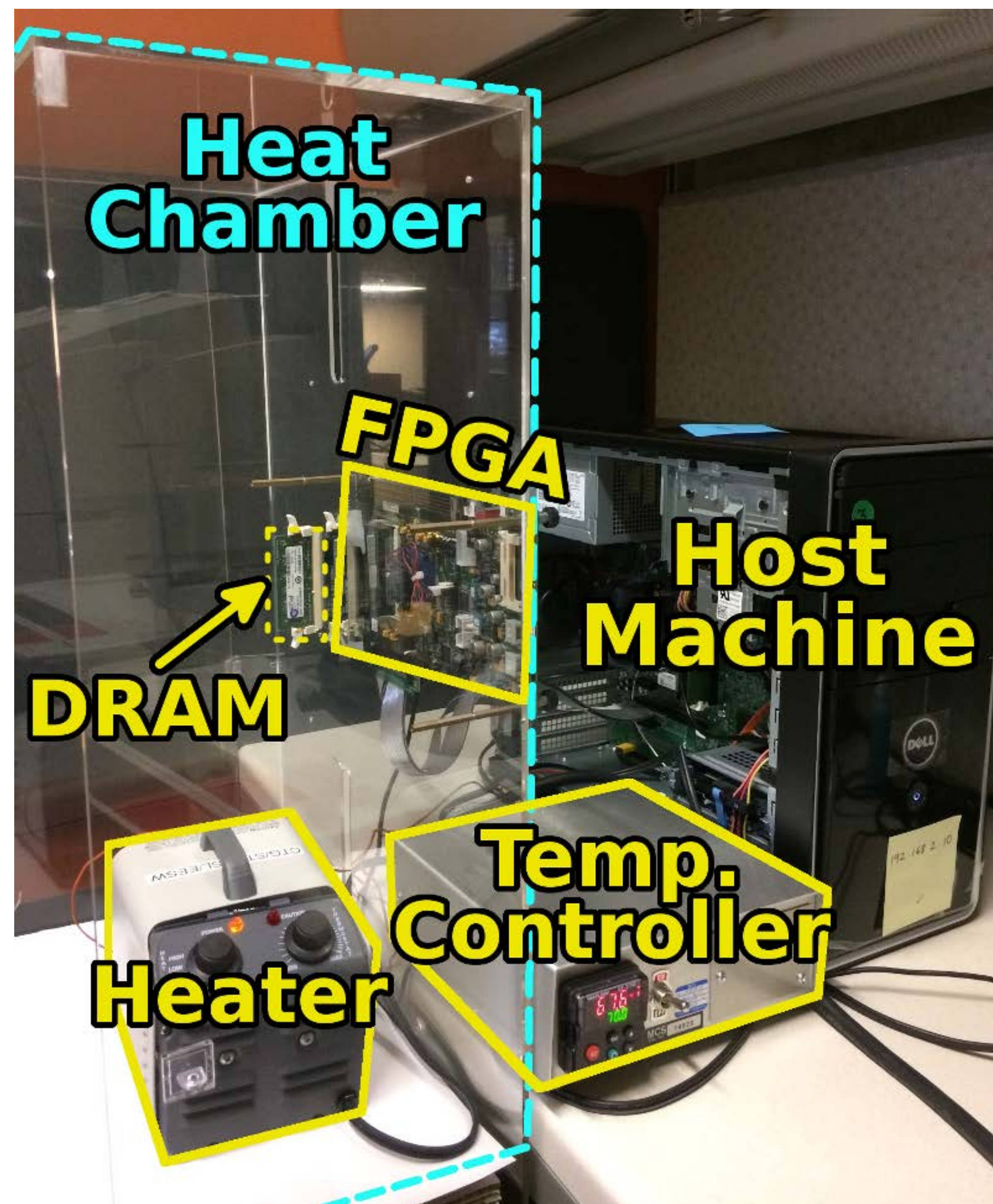
Kim+, "Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors," ISCA 2014.

SoftMC: Open Source DRAM Infrastructure

- Hasan Hassan et al., "**SoftMC: A Flexible and Practical Open-Source Infrastructure for Enabling Experimental DRAM Studies**," HPCA 2017.

- **Flexible**
- **Easy to Use (C++ API)**
- **Open-source**

  github.com/CMU-SAFARI/SoftMC



SoftMC

- https://github.com/CMU-SAFARI/SoftMC

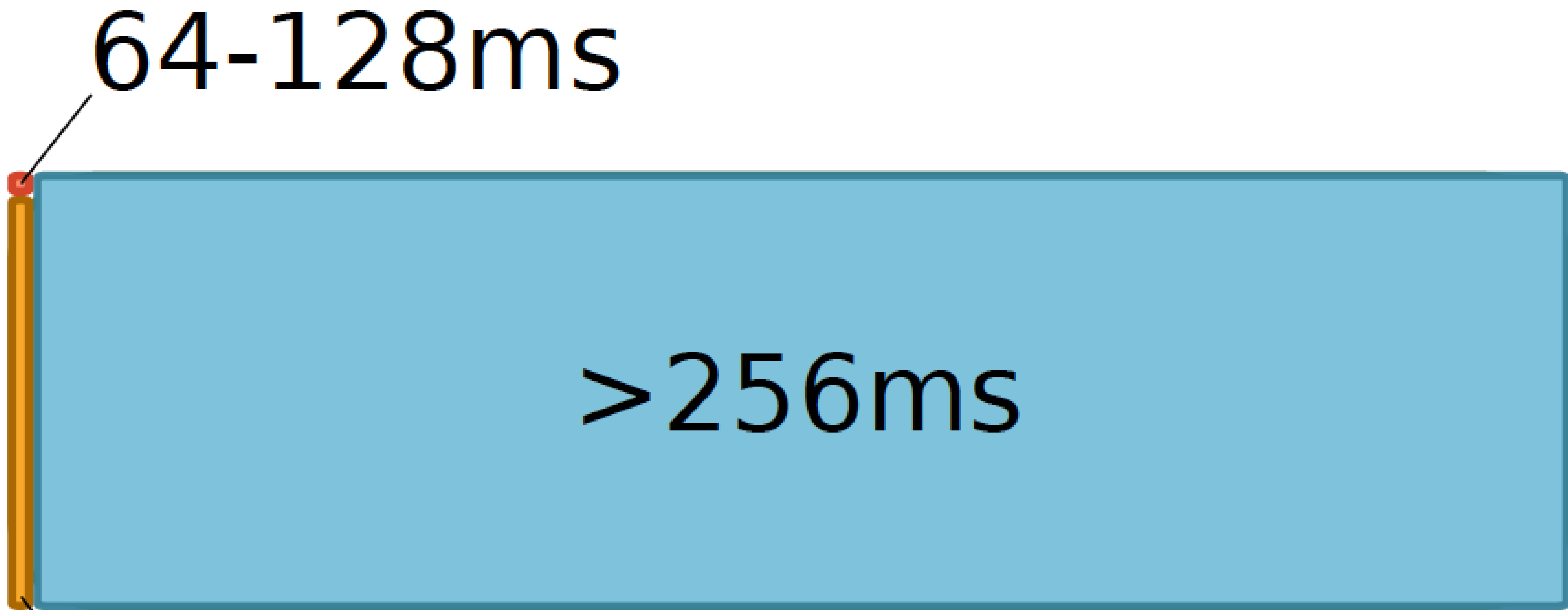
SoftMC: A Flexible and Practical Open-Source Infrastructure for Enabling Experimental DRAM Studies

Hasan Hassan[1,2,3] Nandita Vijaykumar[3] Samira Khan[4,3] Saugata Ghose[3] Kevin Chang[3]
Gennady Pekhimenko[5,3] Donghyuk Lee[6,3] Oguz Ergin[2] Onur Mutlu[1,3]

[1]*ETH Zürich* [2]*TOBB University of Economics & Technology* [3]*Carnegie Mellon University*
[4]*University of Virginia* [5]*Microsoft Research* [6]*NVIDIA Research*

Data Retention in Memory [Liu et al., ISCA 2013]

- Retention Time Profile of DRAM looks like this:



Location dependent
Stored value pattern dependent
Time dependent

A Curious Discovery **[Kim et al., ISCA 2014]**

One can

predictably induce errors

in most DRAM memory chips

DRAM RowHammer

A simple hardware failure mechanism
can create a widespread
system security vulnerability

WIRED Forget Software—Now Hackers Are Exploiting Physics

BUSINESS | CULTURE | DESIGN | GEAR | SCIENCE

ANDY GREENBERG SECURITY 08.31.16 7:00 AM

FORGET SOFTWARE—NOW HACKERS ARE EXPLOITING PHYSICS

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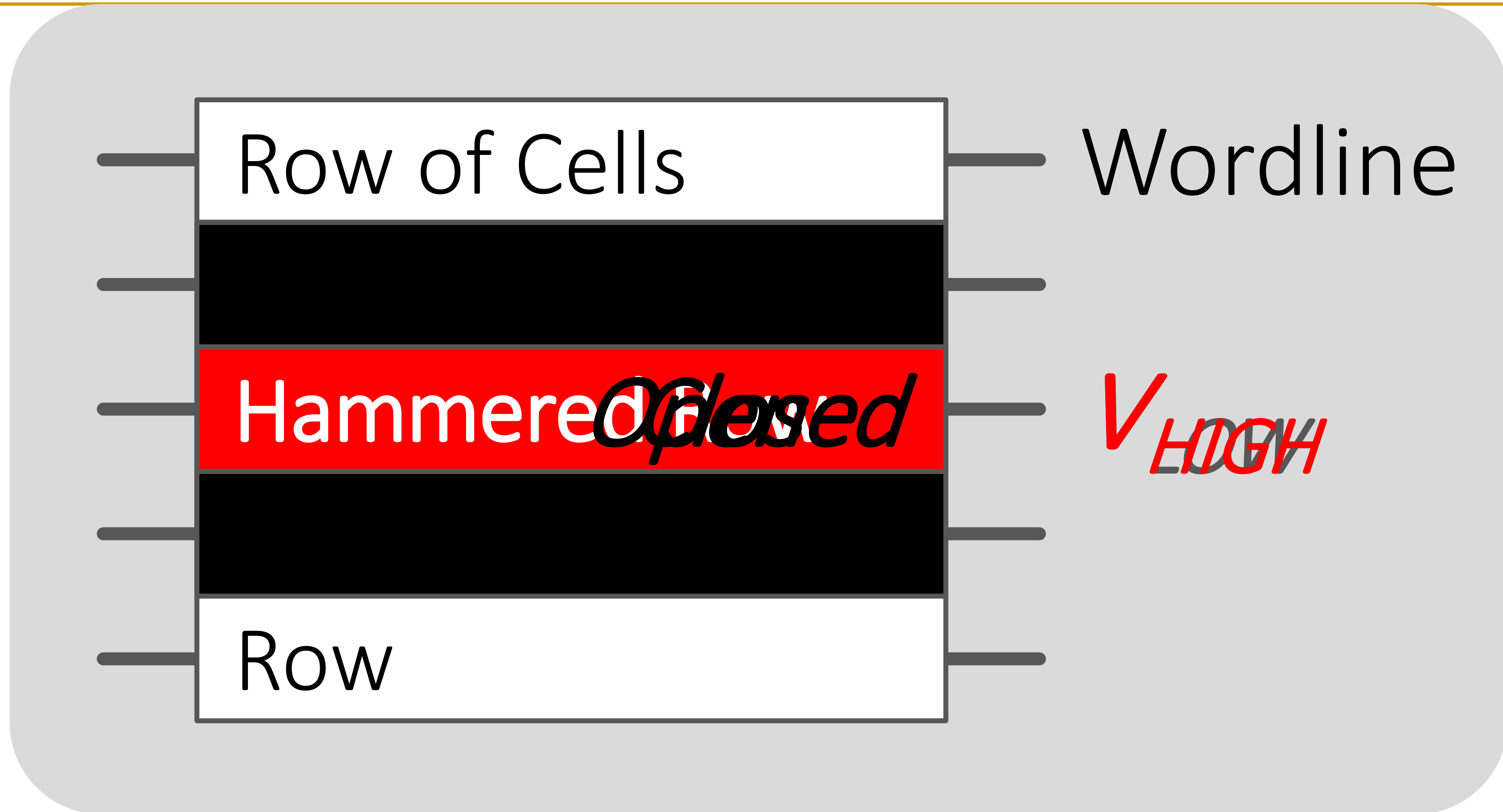
TWEET

Modern DRAM is Prone to Disturbance Errors

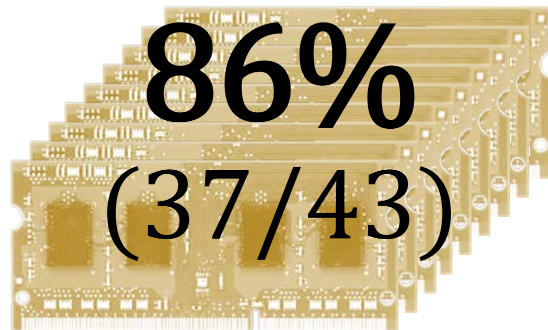


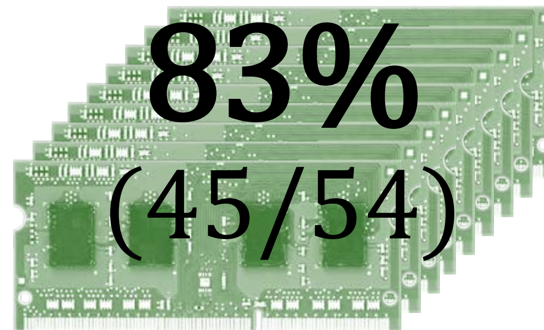
Repeatedly reading a row enough times (before memory gets refreshed) induces disturbance errors in **adjacent rows** in most real DRAM chips you can buy today

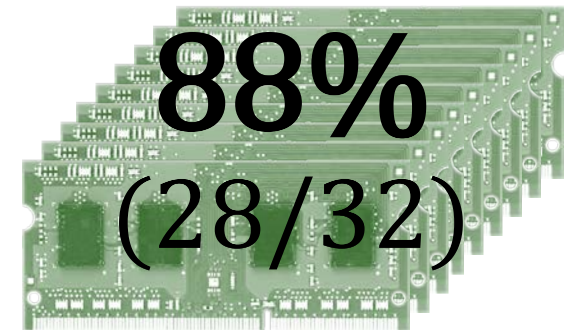
Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors, (Kim et al., ISCA 2014)

Most DRAM Modules Are Vulnerable

A company | B company | C company







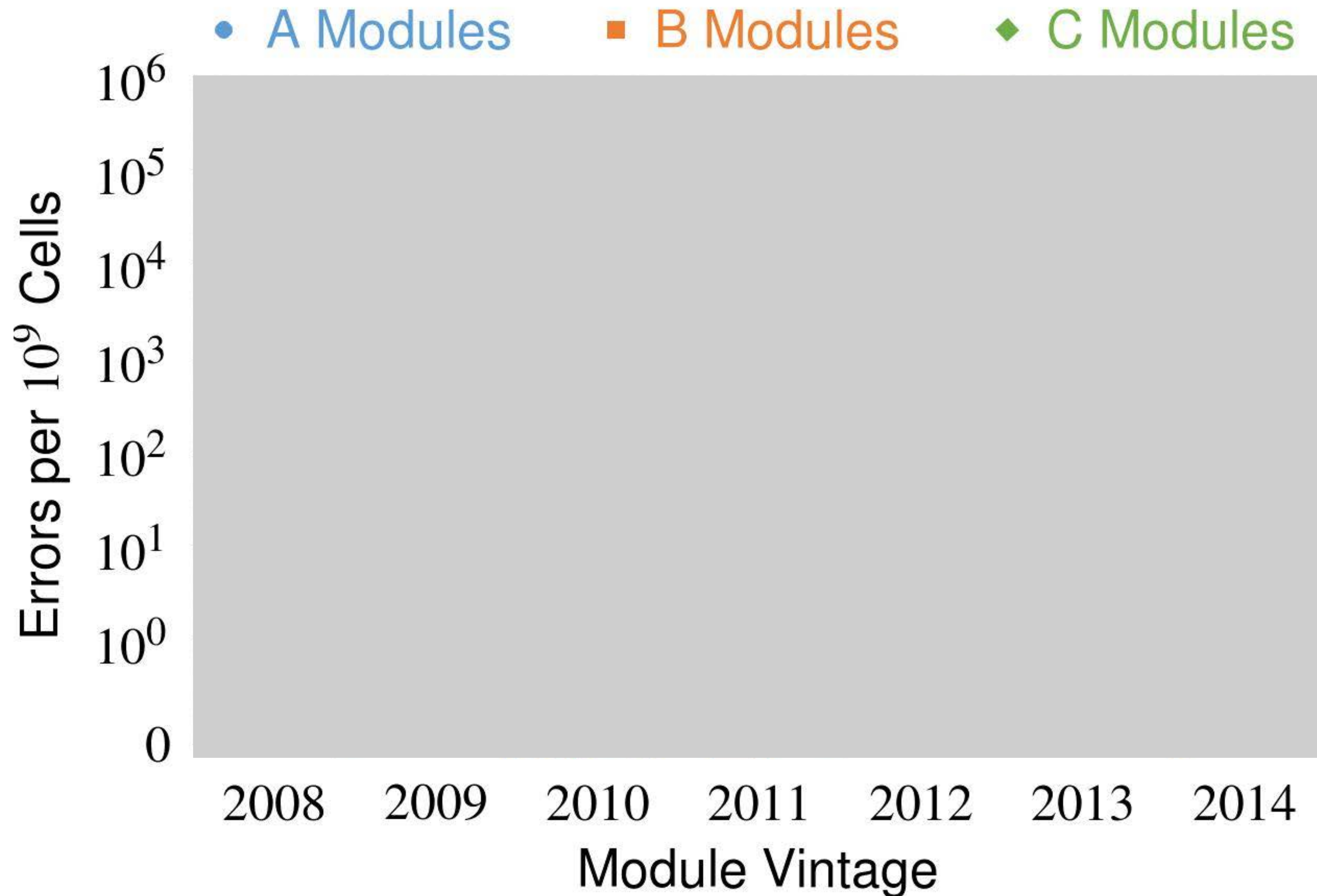
Up to **1.0×10^7** errors

Up to **2.7×10^6** errors

Up to **3.3×10^5** errors

Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors, (Kim et al., ISCA 2014)

Recent DRAM Is More Vulnerable



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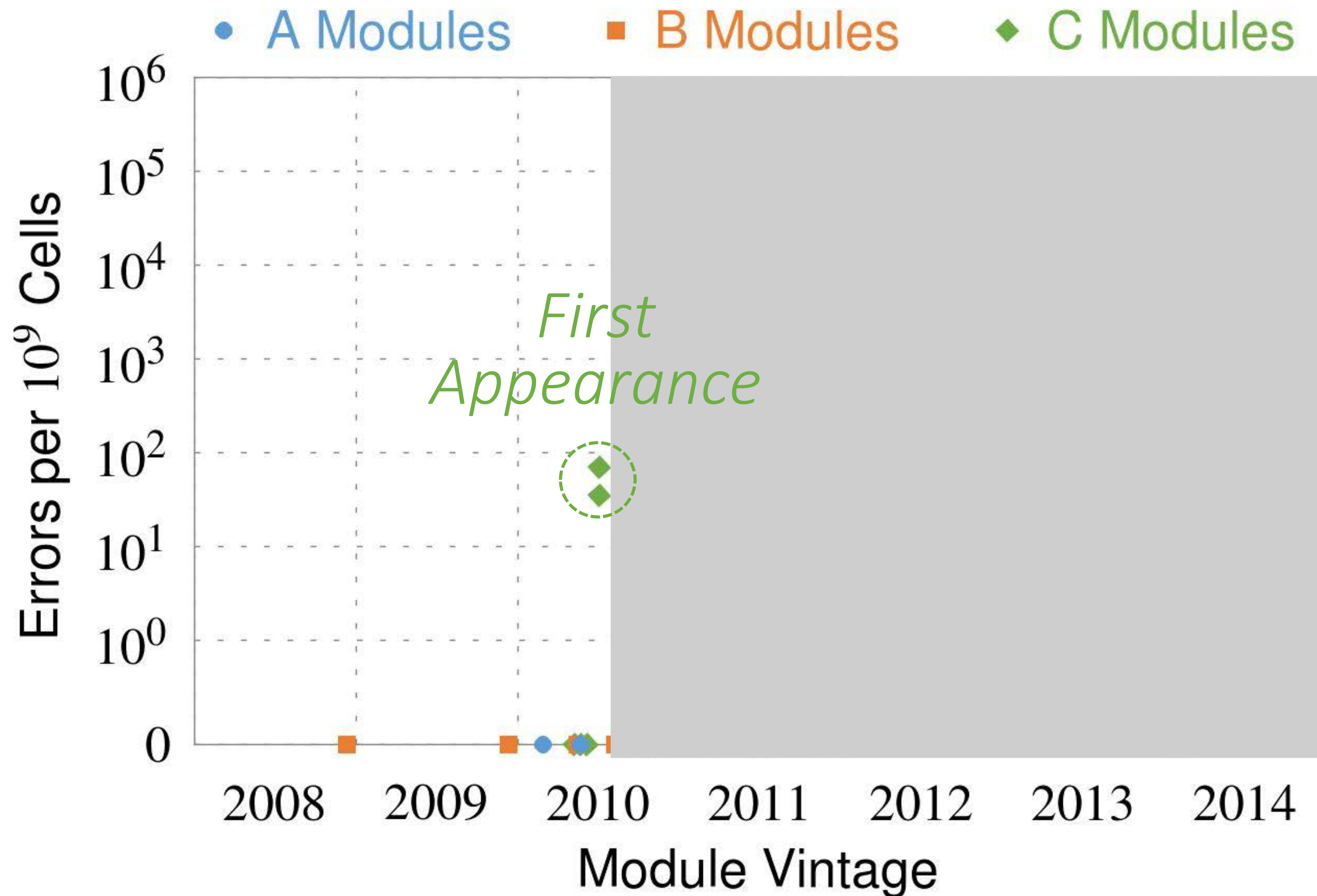

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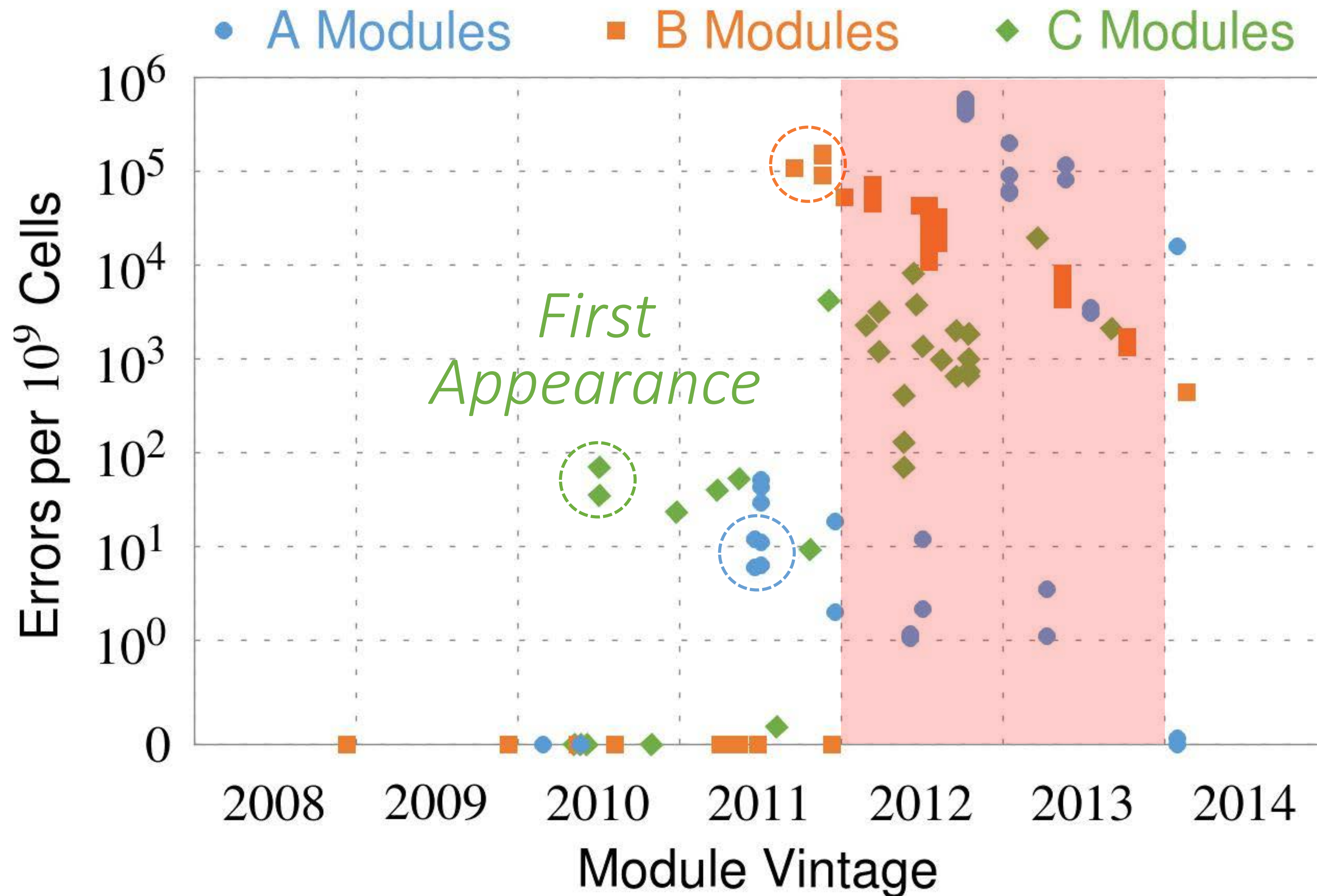
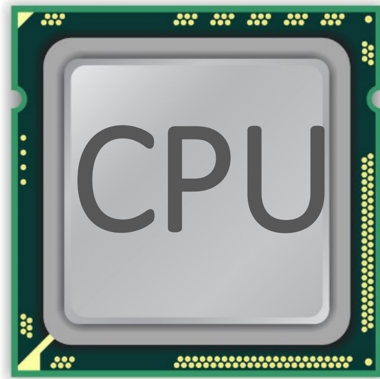
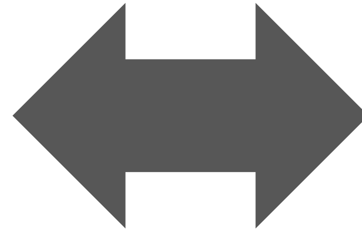
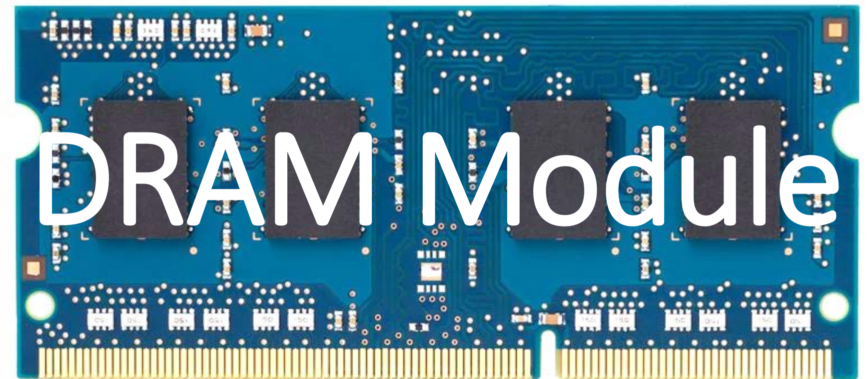


All modules from 2012–2013 are vulnerable

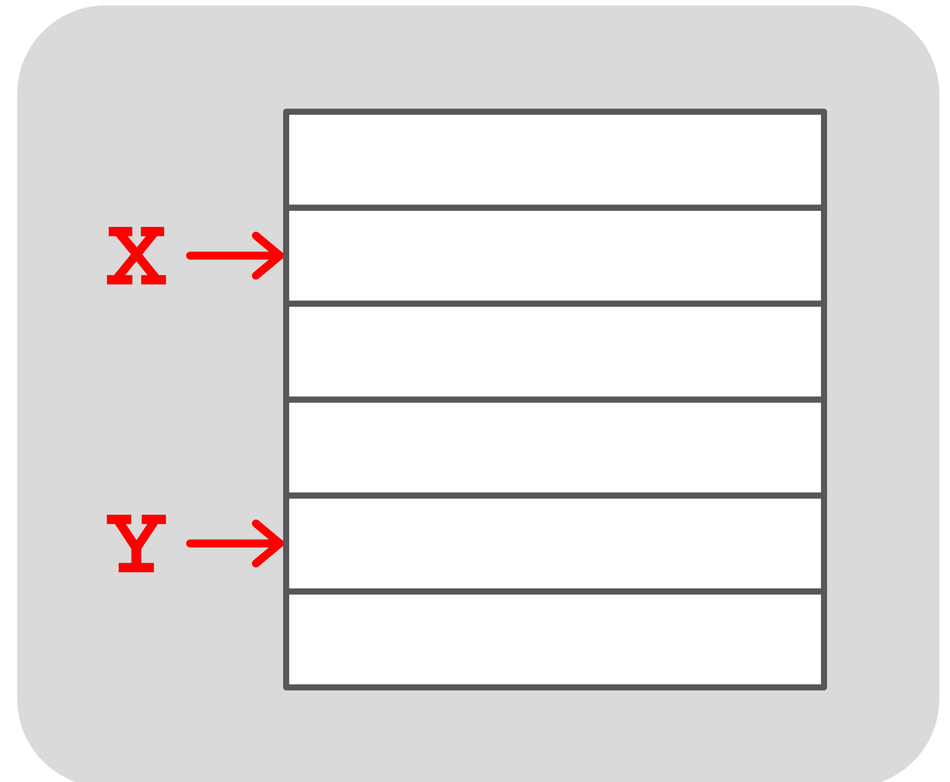
A Simple Program Can Induce Many Errors








```
loop:
   mov (X), %eax
   mov (Y), %ebx
   clflush (X)
   clflush (Y)
   mfence
   jmp loop
```



Download from: https://github.com/CMU-SAFARI/rowhammer

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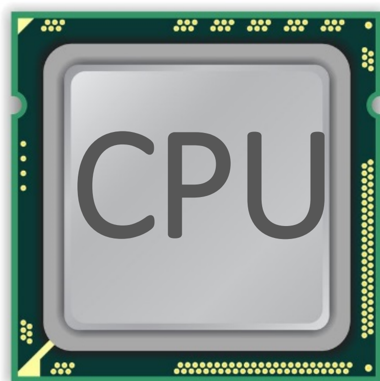
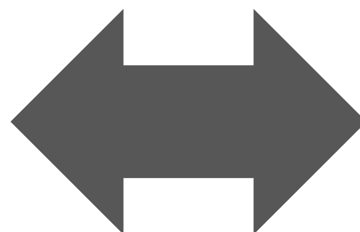
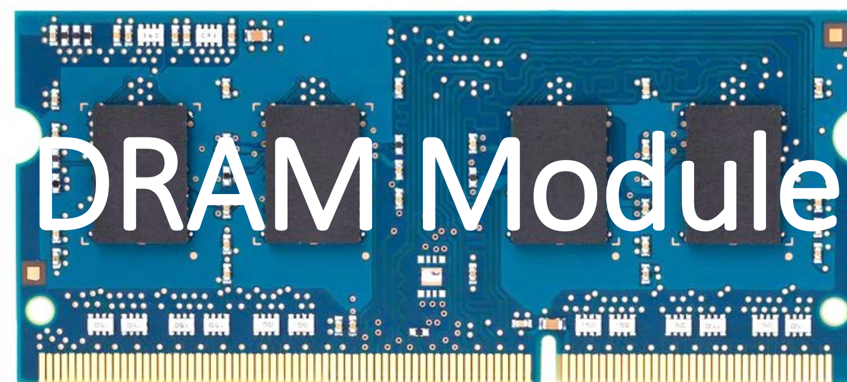
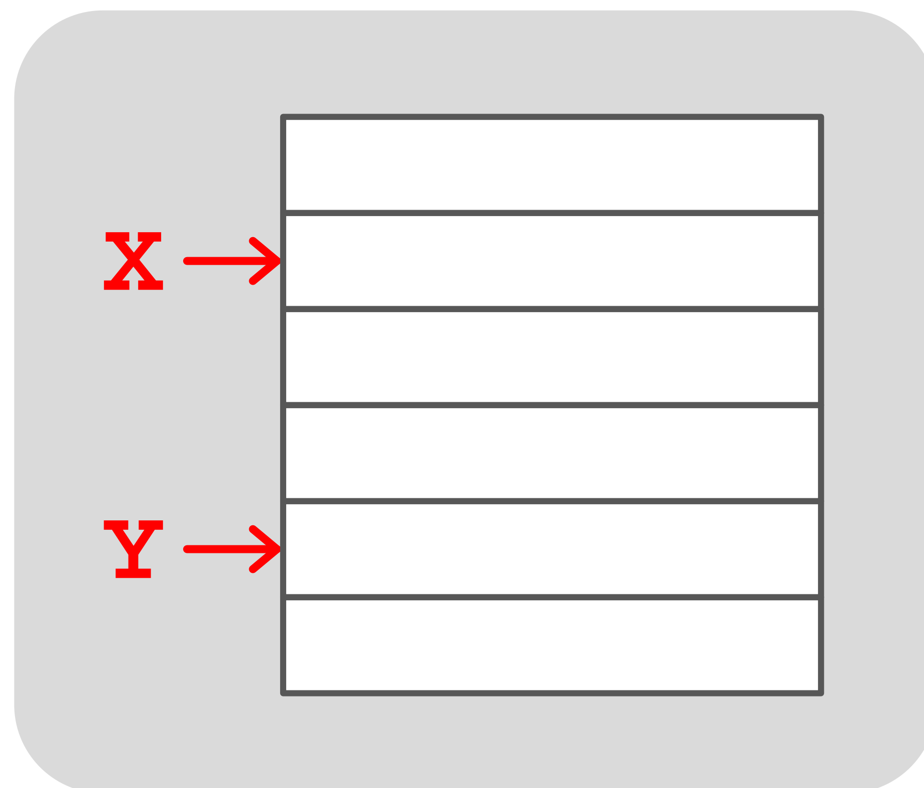






1. Avoid *cache hits*
   – Flush **X** from cache

2. Avoid *row hits* to **X**
   – Read **Y** in another row



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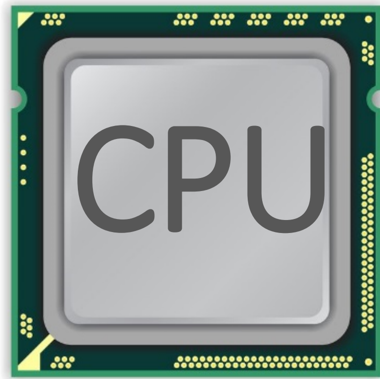

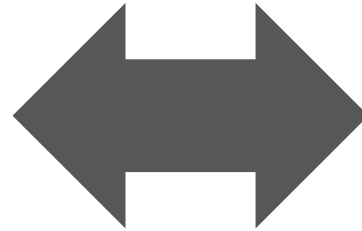

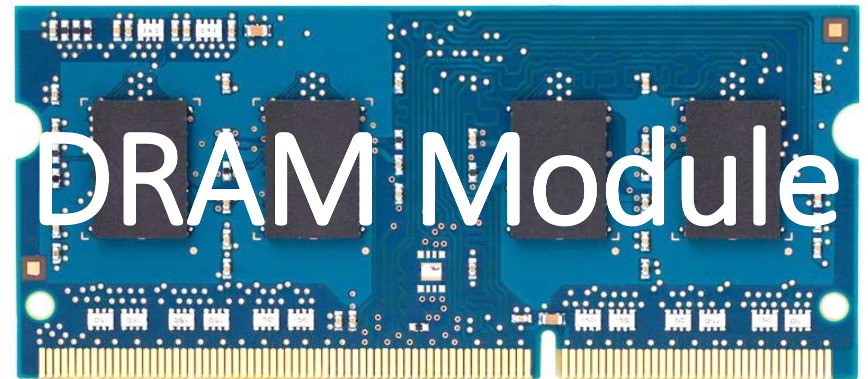


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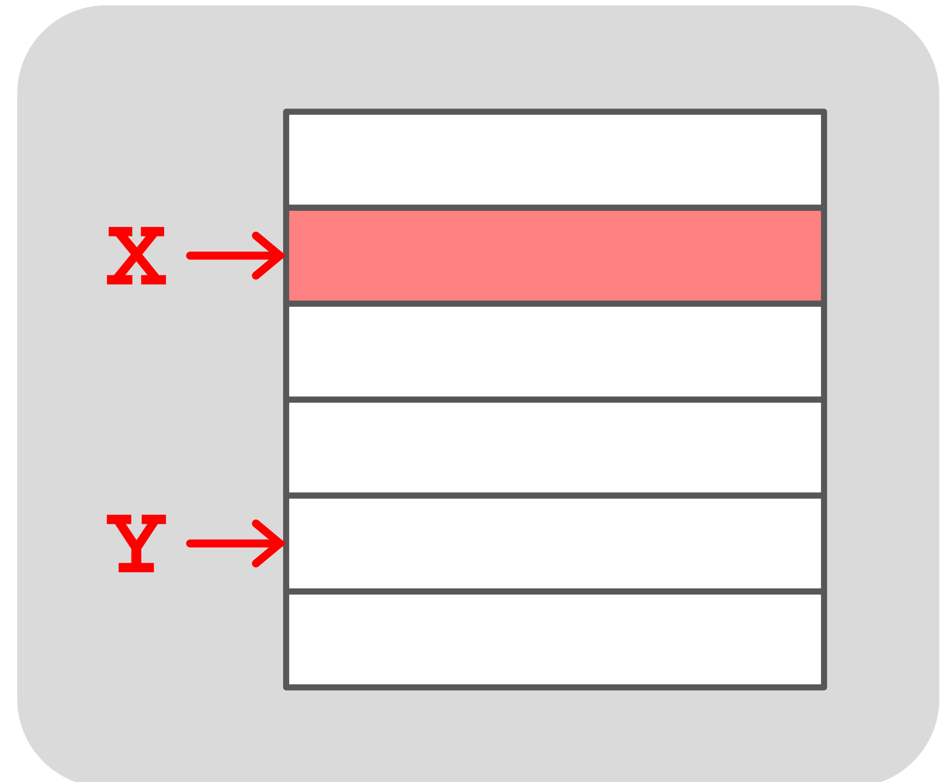

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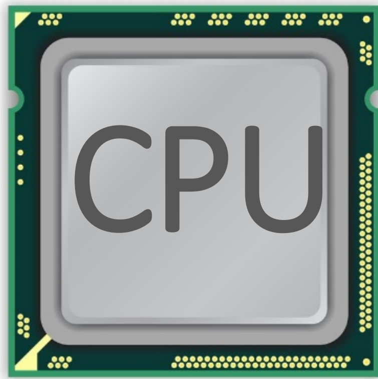

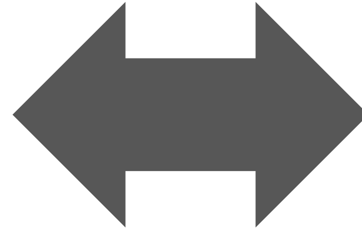

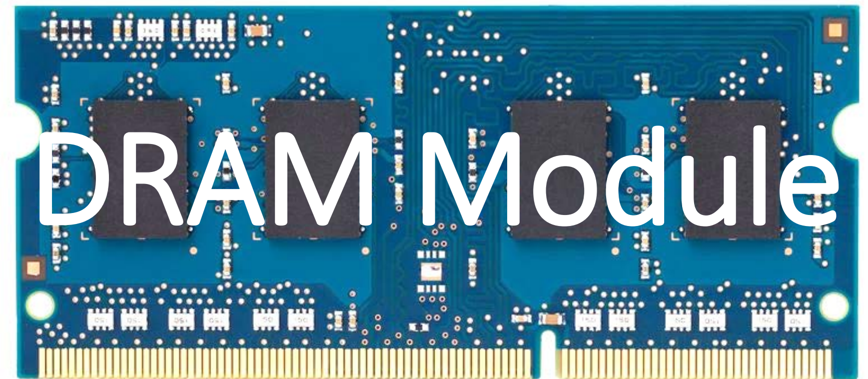


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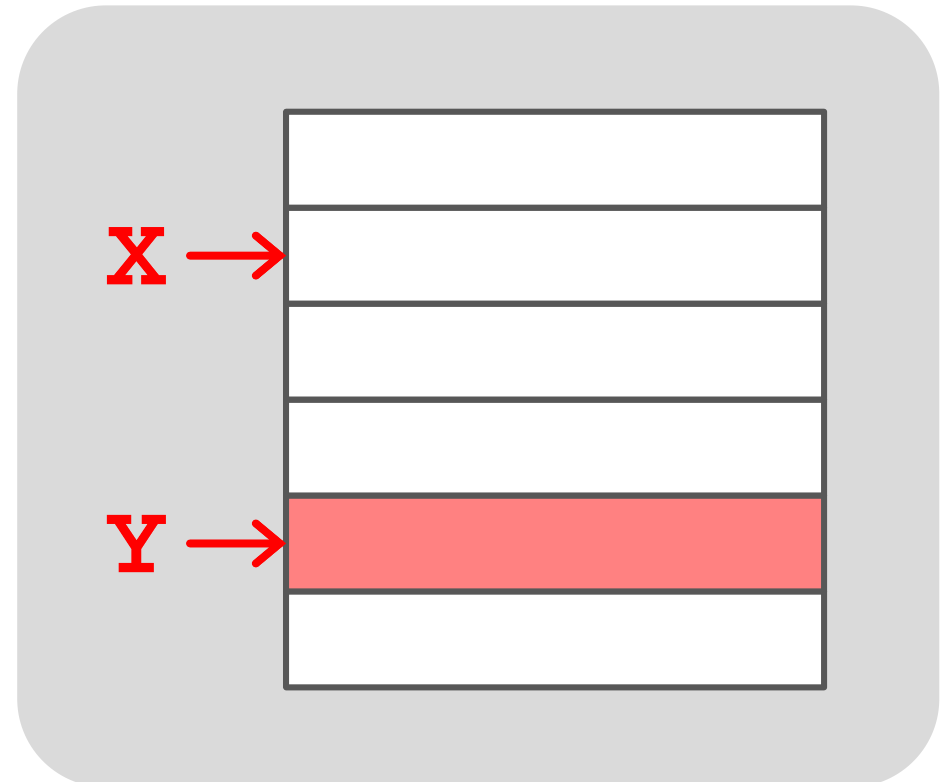

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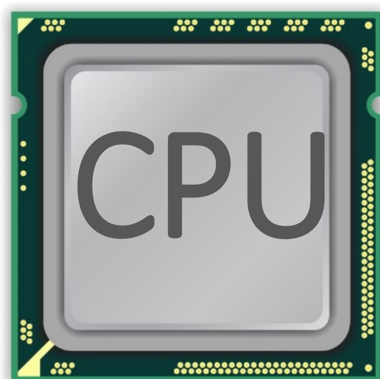
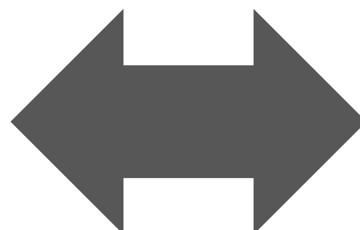
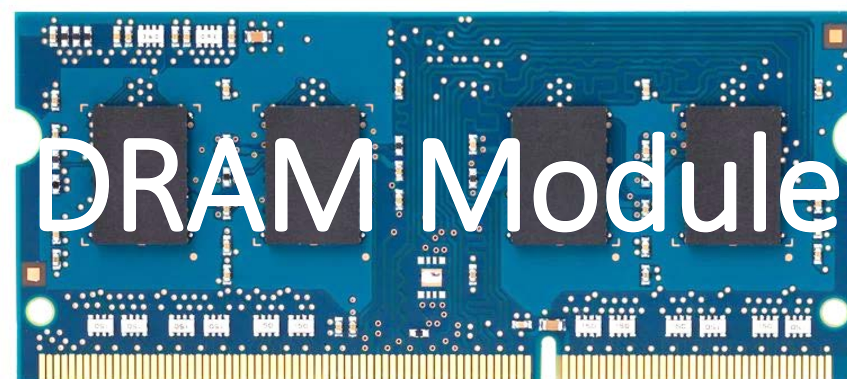
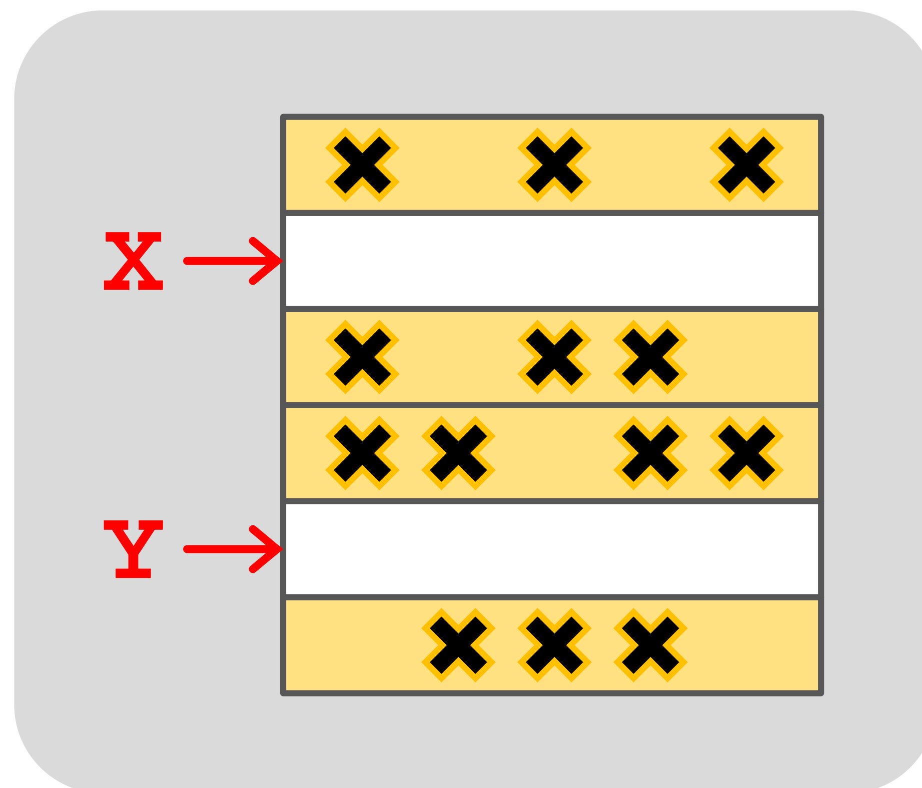







```
loop:
  mov (X), %eax
  mov (Y), %ebx
  clflush (X)
  clflush (Y)
  mfence
  jmp loop
```



Download from: https://github.com/CMU-SAFARI/rowhammer

Observed Errors in Real Systems

CPU Architecture	Errors	Access-Rate
Intel Haswell (2013)	22.9K	12.3M/sec
Intel Ivy Bridge (2012)	20.7K	11.7M/sec
Intel Sandy Bridge (2011)	16.1K	11.6M/sec
AMD Piledriver (2012)	59	6.1M/sec

A real reliability & security issue

Kim+, "Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors," ISCA 2014.

One Can Take Over an Otherwise-Secure System

Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors

Abstract. Memory isolation is a key property of a reliable and secure computing system — an access to one memory address should not have unintended side effects on data stored in other addresses. However, as DRAM process technology

Project Zero

Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors (Kim et al., ISCA 2014)

News and updates from the Project Zero team at Google

Exploiting the DRAM rowhammer bug to gain kernel privileges (Seaborn, 2015)

Monday, March 9, 2015

Exploiting the DRAM rowhammer bug to gain kernel privileges

RowHammer Security Attack Example

- "Rowhammer" is a problem with some recent DRAM devices in which repeatedly accessing a row of memory can cause bit flips in adjacent rows (Kim et al., ISCA 2014).
  - Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors (Kim et al., ISCA 2014)

- We tested a selection of laptops and found that a subset of them exhibited the problem.
- We built two working privilege escalation exploits that use this effect.
  - Exploiting the DRAM rowhammer bug to gain kernel privileges (Seaborn+, 2015)

- One exploit uses rowhammer-induced bit flips to gain kernel privileges on x86-64 Linux when run as an unprivileged userland process.
- When run on a machine vulnerable to the rowhammer problem, the process was able to induce bit flips in page table entries (PTEs).
- It was able to use this to gain write access to its own page table, and hence gain read-write access to all of physical memory.

Exploiting the DRAM rowhammer bug to gain kernel privileges (Seaborn & Dullien, 2015)

Security Implications

Security Implications

It's like breaking into an apartment by repeatedly slamming a neighbor's door until the vibrations open the door you were after

Selected Readings on RowHammer (I)

- Our first detailed study: Rowhammer analysis and solutions (June 2014)
  - Yoongu Kim, Ross Daly, Jeremie Kim, Chris Fallin, Ji Hye Lee, Donghyuk Lee, Chris Wilkerson, Konrad Lai, and Onur Mutlu,
    "Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors"
    *Proceedings of the 41st International Symposium on Computer Architecture (**ISCA**)*, Minneapolis, MN, June 2014. [Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)] [Source Code and Data]

- Our Source Code to Induce Errors in Modern DRAM Chips (June 2014)
  - https://github.com/CMU-SAFARI/rowhammer

- Google Project Zero's Attack to Take Over a System (March 2015)
  - Exploiting the DRAM rowhammer bug to gain kernel privileges (Seaborn+, 2015)
  - https://github.com/google/rowhammer-test
  - **Double-sided Rowhammer**

Selected Readings on RowHammer (II)

- Remote RowHammer Attacks via JavaScript (July 2015)
  - http://arxiv.org/abs/1507.06955
  - https://github.com/IAIK/rowhammerjs
  - Gruss et al., DIMVA 2016.
  - **CLFLUSH-free Rowhammer**
  - "A fully automated attack that requires nothing but a website with JavaScript to **trigger faults on remote hardware**."
  - "We can gain unrestricted access to systems of website visitors."

- ANVIL: Software-Based Protection Against Next-Generation Rowhammer Attacks (March 2016)
  - http://dl.acm.org/citation.cfm?doid=2872362.2872390
  - Aweke et al., ASPLOS 2016
  - **CLFLUSH-free Rowhammer**
  - Software based monitoring for rowhammer detection

Selected Readings on RowHammer (III)

- Dedup Est Machina: Memory Deduplication as an Advanced Exploitation Vector (May 2016)
  - https://www.ieee-security.org/TC/SP2016/papers/0824a987.pdf
  - Bosman et al., IEEE S&P 2016.
  - Exploits Rowhammer and Memory Deduplication to overtake a browser
  - "We report on the **first reliable remote exploit for the Rowhammer vulnerability** running entirely in Microsoft Edge."
  - "[an attacker] … can reliably "own" a system with all defenses up, even if the software is entirely free of bugs."

Selected Readings on RowHammer (IV)

- Flip Feng Shui: Hammering a Needle in the Software Stack (August 2016)
  - https://www.usenix.org/system/files/conference/usenixsecurity16/sec16_paper_razavi.pdf
  - Razavi et al., USENIX Security 2016.
  - Combines memory deduplication and RowHammer
  - "**A malicious VM can gain unauthorized access to a co-hosted VM running OpenSSH**."
  - Breaks OpenSSH public key authentication

- Drammer: Deterministic Rowhammer Attacks on Mobile Platforms (October 2016)
  - http://dl.acm.org/citation.cfm?id=2976749.2978406
  - Van Der Veen et al., CCS 2016
  - **Can take over an ARM-based Android system deterministically**
  - Exploits predictable physical memory allocator behavior
    - Can deterministically place security-sensitive data (e.g., page table) in an attacker-chosen, vulnerable location in memory

Selected Readings on RowHammer (V)

- Grand Pwning Unit: Accelerating Microarchitectural Attacks with the GPU (May 2018)
  - https://www.vusec.net/wp-content/uploads/2018/05/glitch.pdf
  - Frigo et al., IEEE S&P 2018.
  - The first end-to-end remote Rowhammer exploit on mobile platforms that use our GPU-based primitives in orchestration to **compromise browsers on mobile devices in under two minutes**.

- Throwhammer: Rowhammer Attacks over the Network and Defenses (July 2018)
  - https://www.cs.vu.nl/~herbertb/download/papers/throwhammer_atc18.pdf
  - Tatar et al., USENIX ATC 2018.
  - "[We] show that **an attacker can trigger and exploit Rowhammer bit flips directly from a remote machine by only sending network packets**."

Selected Readings on RowHammer (VI)

- Nethammer: Inducing Rowhammer Faults through Network Requests (July 2018)
  - https://arxiv.org/pdf/1805.04956.pdf
  - Lipp et al., arxiv.org 2018.
  - "Nethammer is the first truly **remote Rowhammer attack**, without a single attacker-controlled line of code on the targeted system."

More Security Implications (I)

"We can gain unrestricted access to systems of website visitors."

www.iaik.tugraz.at

Not there yet, but ...

ROWHAMMERJS

ROOT privileges for web apps!

29 Daniel Gruss (@lavados), Clémentine Maurice (@BloodyTangerine),
December 28, 2015 — 32c3, Hamburg, Germany

Rowhammer.js: A Remote Software-Induced Fault Attack in JavaScript (DIMVA'16)

More Security Implications (II)

"Can gain control of a smart phone deterministically"

Source: https://fossbytes.com/drammer-rowhammer-attack-android-root-devices/

Drammer: Deterministic Rowhammer Attacks on Mobile Platforms, CCS'16

More Security Implications (III)

- Using an integrated GPU in a mobile system to remotely escalate privilege via the WebGL interface

"GRAND PWNING UNIT" —

Drive-by Rowhammer attack uses GPU to compromise an Android phone

JavaScript based GLitch pwns browsers by flipping bits inside memory chips.

DAN GOODIN - 5/3/2018, 12:00 PM

Grand Pwning Unit: Accelerating Microarchitectural Attacks with the GPU

Pietro Frigo
Vrije Universiteit Amsterdam
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Cristiano Giuffrida
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Herbert Bos
Vrije Universiteit Amsterdam
herbertb@cs.vu.nl

Kaveh Razavi
Vrije Universiteit Amsterdam
kaveh@cs.vu.nl

More Security Implications (IV)

- Rowhammer over RDMA (I)

BIZ & IT TECH SCIENCE POLICY CARS GAMING & CULTURE

THROWHAMMER —

Packets over a LAN are all it takes to trigger serious Rowhammer bit flips

The bar for exploiting potentially serious DDR weakness keeps getting lower.

DAN GOODIN - 5/10/2018, 5:26 PM

Throwhammer: Rowhammer Attacks over the Network and Defenses

Andrei Tatar, *VU Amsterdam*
Radhesh Krishnan, *VU Amsterdam*
Elias Athanasopoulos, *University of Cyprus*
Cristiano Giuffrida, *VU Amsterdam*
Herbert Bos, *VU Amsterdam*
Kaveh Razavi, *VU Amsterdam*

More Security Implications (V)

- Rowhammer over RDMA (II)

Nethammer—Exploiting DRAM Rowhammer Bug Through Network Requests

Nethammer:
Inducing Rowhammer Faults through Network Requests

Moritz Lipp
Graz University of Technology

Misiker Tadesse Aga
University of Michigan

Michael Schwarz
Graz University of Technology

Daniel Gruss
Graz University of Technology

Clémentine Maurice
Univ Rennes, CNRS, IRISA

Lukas Raab
Graz University of Technology

Lukas Lamster
Graz University of Technology

More Security Implications?

Understanding RowHammer

Root Causes of Disturbance Errors

- *Cause 1: Electromagnetic coupling*
  - Toggling the wordline voltage briefly increases the voltage of adjacent wordlines
  - Slightly opens adjacent rows → Charge leakage
- *Cause 2: Conductive bridges*
- *Cause 3: Hot-carrier injection*

Confirmed by at least one manufacturer

Experimental DRAM Testing Infrastructure

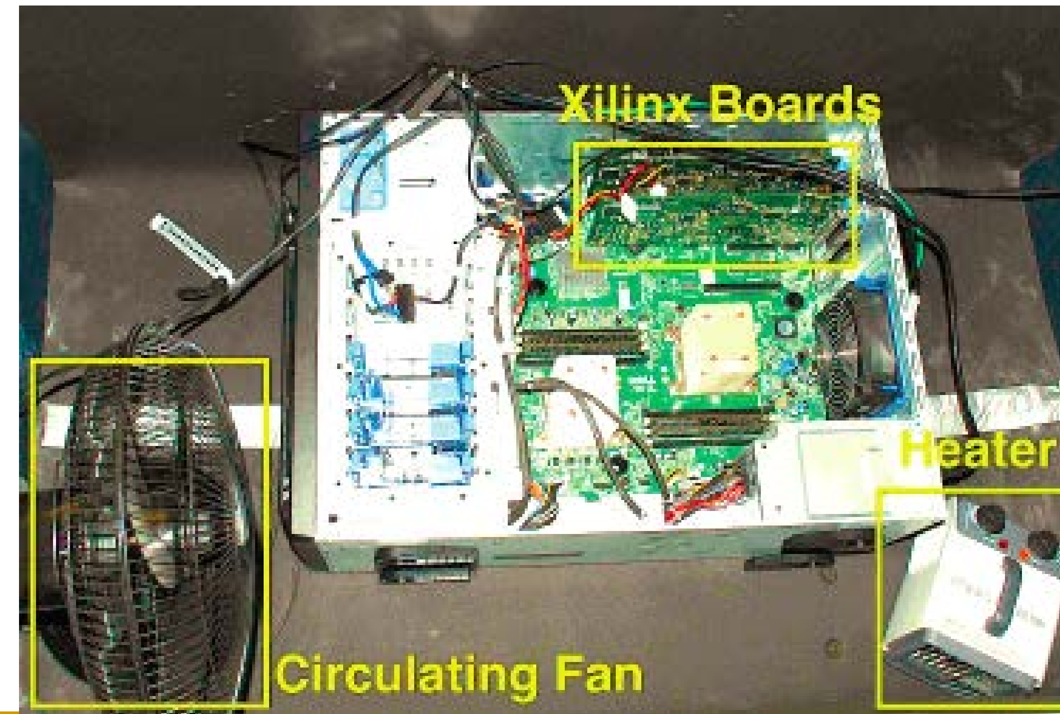
An Experimental Study of Data Retention Behavior in Modern DRAM Devices: Implications for Retention Time Profiling Mechanisms (Liu et al., ISCA 2013)

The Efficacy of Error Mitigation Techniques for DRAM Retention Failures: A Comparative Experimental Study (Khan et al., SIGMETRICS 2014)

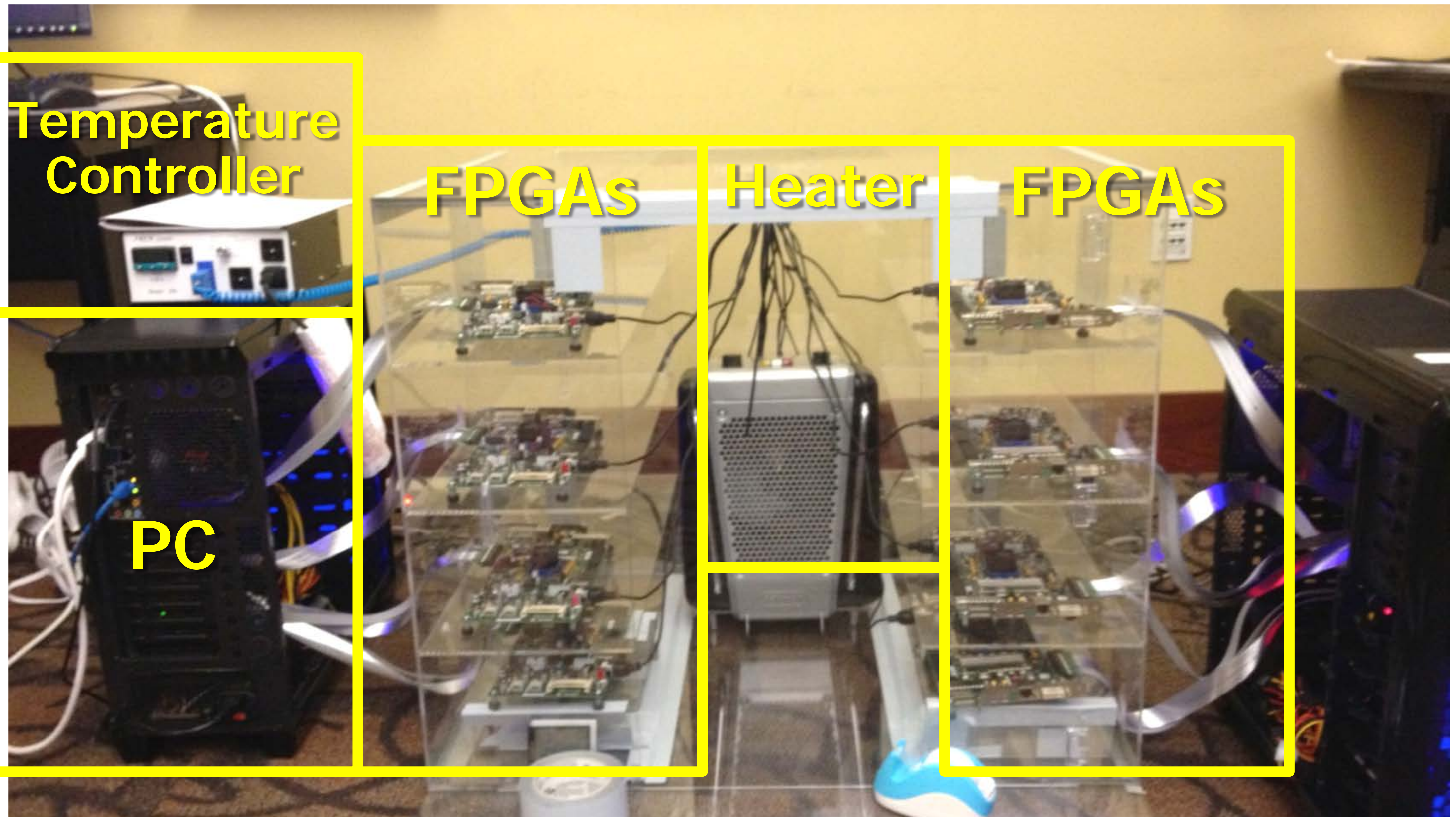
Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors (Kim et al., ISCA 2014)

Adaptive-Latency DRAM: Optimizing DRAM Timing for the Common-Case (Lee et al., HPCA 2015)

AVATAR: A Variable-Retention-Time (VRT) Aware Refresh for DRAM Systems (Qureshi et al., DSN 2015)



Experimental DRAM Testing Infrastructure

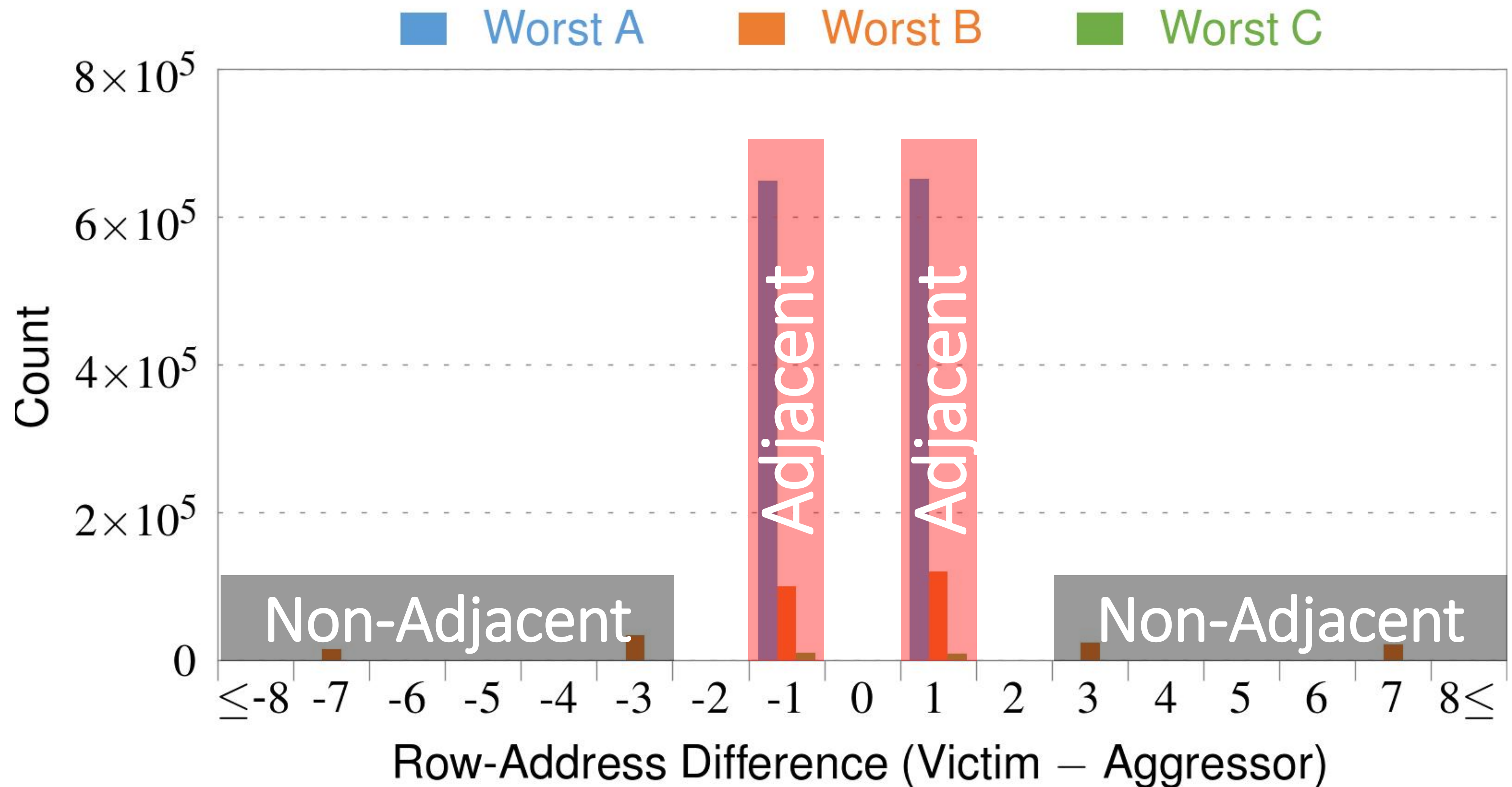


RowHammer Characterization Results

1. Most Modules Are at Risk
2. Errors vs. Vintage
3. Error = Charge Loss
4. Adjacency: Aggressor & Victim
5. Sensitivity Studies
6. Other Results in Paper
7. Solution Space

Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors, (Kim et al., ISCA 2014)

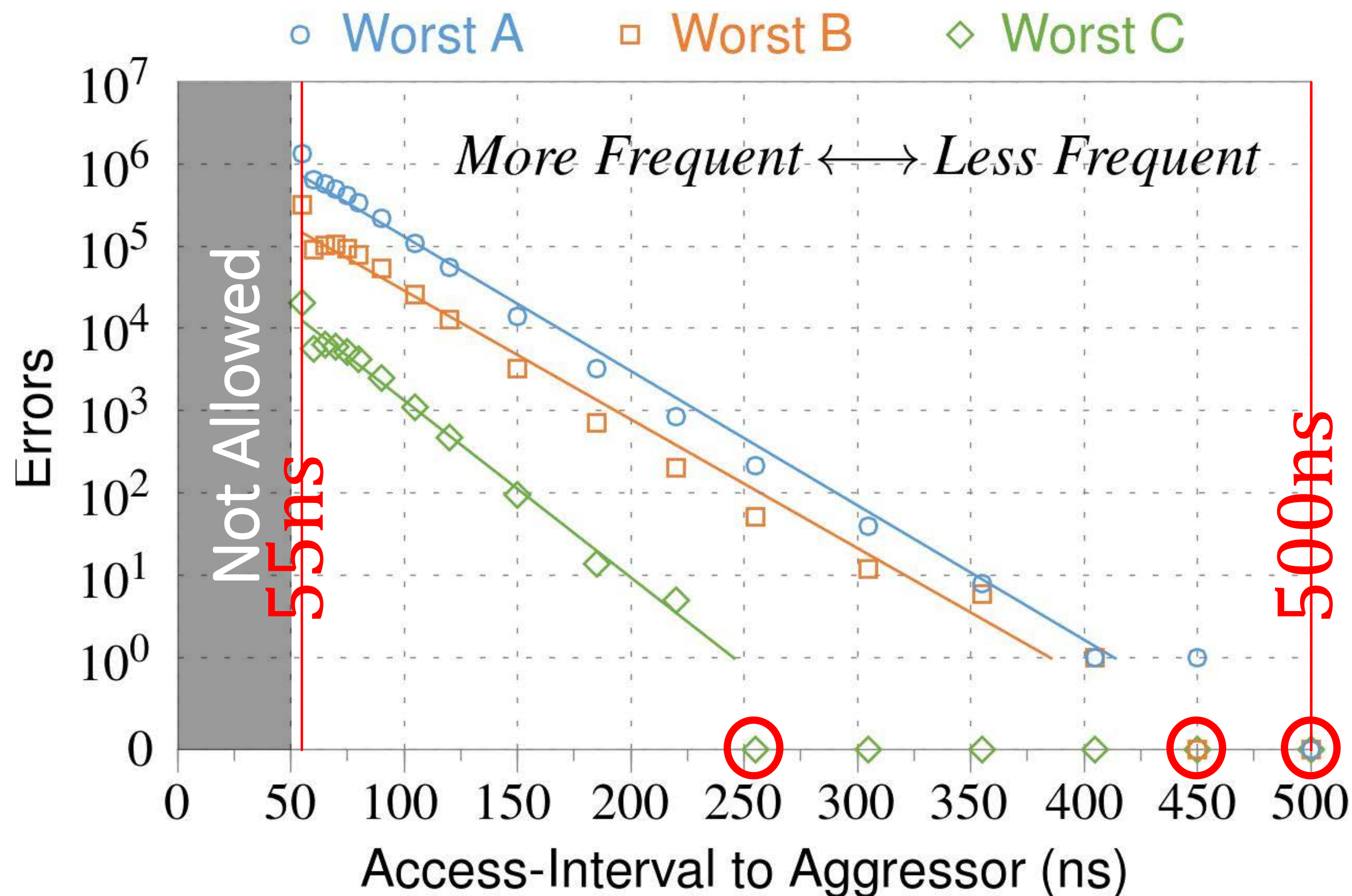
4. Adjacency: Aggressor & Victim



Note: For three modules with the most errors (only first bank)

Most aggressors & victims are adjacent

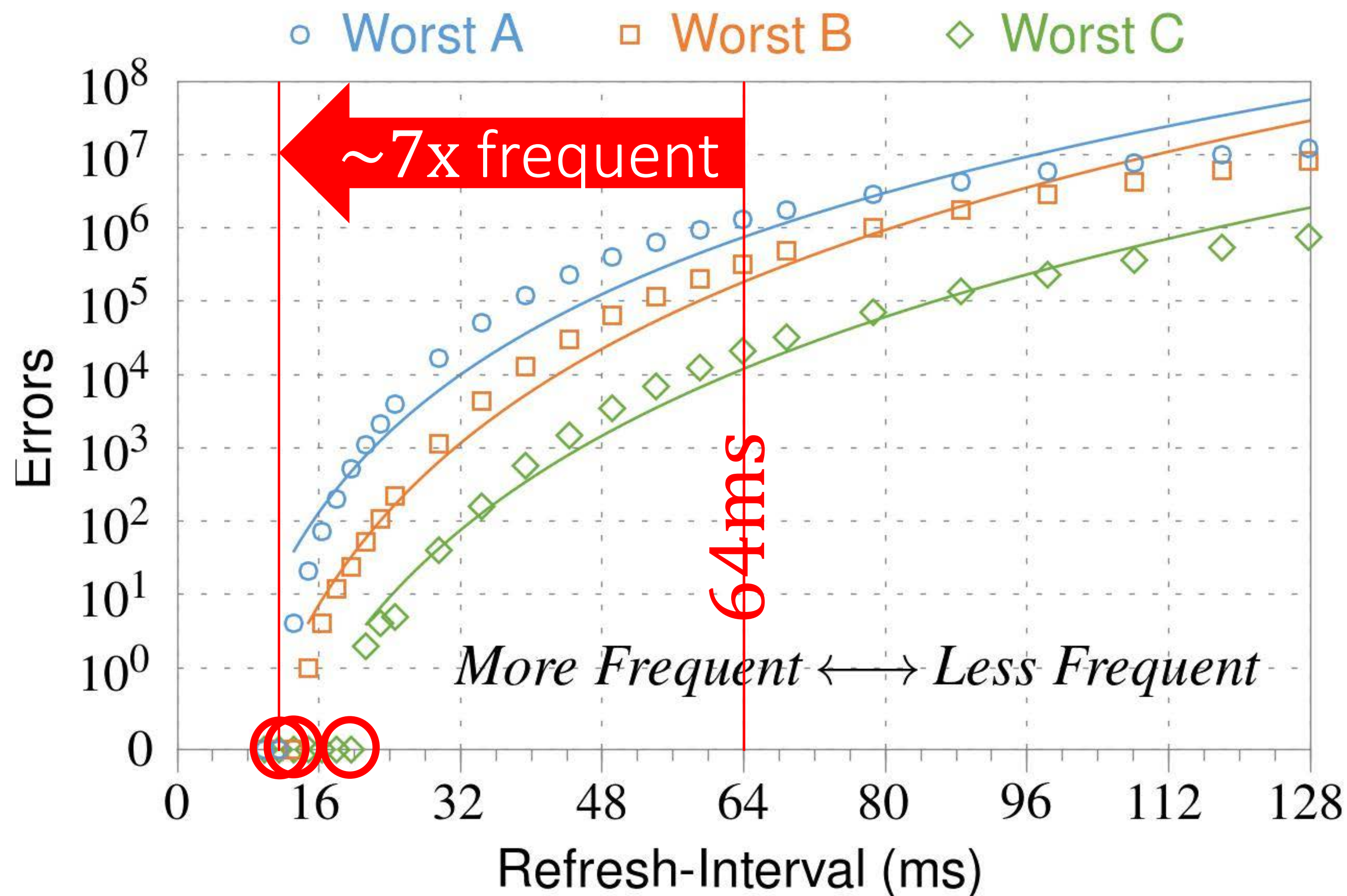
❶ Access Interval (Aggressor)



Note: For three modules with the most errors (only first bank)

Less frequent accesses → Fewer errors

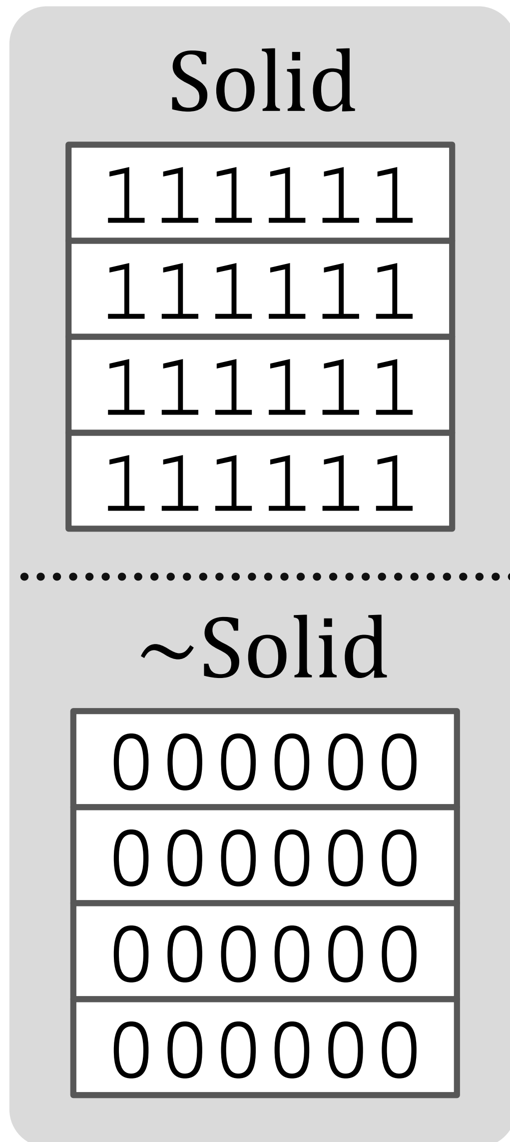
❷ Refresh Interval

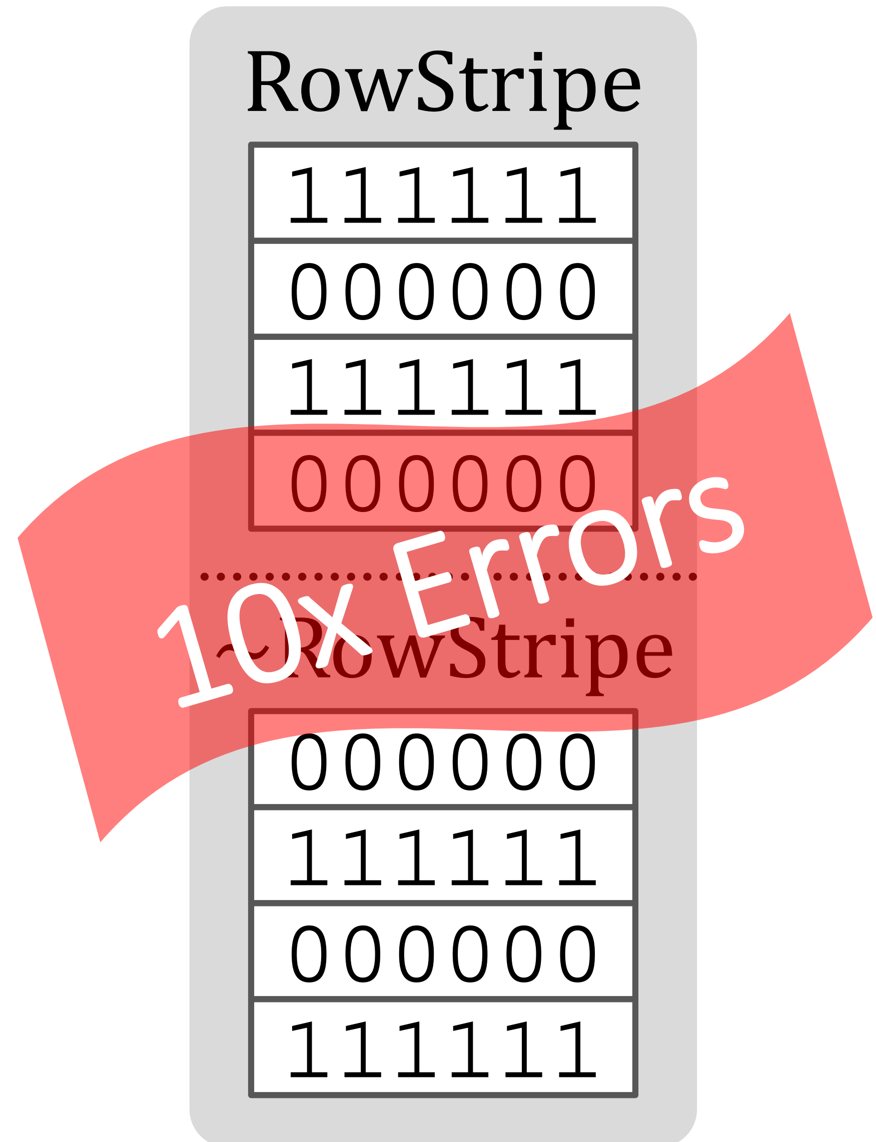


Note: Using three modules with the most errors (only first bank)

More frequent refreshes → Fewer errors

3 Data Pattern





Errors affected by data stored in other cells

6. Other Results (in Paper)

- *Victim Cells ≠ Weak Cells (i.e., leaky cells)*
  - Almost no overlap between them
- *Errors not strongly affected by temperature*
  - Default temperature: 50°C
  - At 30°C and 70°C, number of errors changes <15%
- *Errors are repeatable*
  - Across ten iterations of testing, >70% of victim cells had errors in every iteration

6. Other Results (in Paper) cont'd

- *As many as 4 errors per cache-line*
  - Simple ECC (e.g., SECDED) cannot prevent all errors
- *Number of cells & rows affected by aggressor*
  - Victims cells per aggressor: ≤ 110
  - Victims rows per aggressor: ≤ 9
- *Cells affected by two aggressors on either side*

More on RowHammer Analysis

- Yoongu Kim, Ross Daly, Jeremie Kim, Chris Fallin, Ji Hye Lee, Donghyuk Lee, Chris Wilkerson, Konrad Lai, and Onur Mutlu, **"Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors"** *Proceedings of the 41st International Symposium on Computer Architecture* ***(ISCA)***, Minneapolis, MN, June 2014. [Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)] [Source Code and Data]

Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors

Yoongu Kim[1] Ross Daly* Jeremie Kim[1] Chris Fallin* Ji Hye Lee[1]
Donghyuk Lee[1] Chris Wilkerson[2] Konrad Lai Onur Mutlu[1]

[1]Carnegie Mellon University [2]Intel Labs

Retrospective on RowHammer & Future

- Onur Mutlu,
  "The RowHammer Problem and Other Issues We May Face as Memory Becomes Denser"
  Invited Paper in Proceedings of the Design, Automation, and Test in Europe Conference ***(DATE)***, Lausanne, Switzerland, March 2017.
  [Slides (pptx) (pdf)]

The RowHammer Problem
and Other Issues We May Face as Memory Becomes Denser

Onur Mutlu
ETH Zürich
onur.mutlu@inf.ethz.ch
https://people.inf.ethz.ch/omutlu

RowHammer Solutions

Some Potential Solutions

- Make better DRAM chips — Cost
- Refresh frequently — Power, Performance
- Sophisticated ECC — Cost, Power
- Access counters — Cost, Power, Complexity

Naive Solutions

1. *Throttle accesses to same row*
   - Limit access-interval: $\geq 500\text{ns}$
   - Limit number of accesses: $\leq 128\text{K}$ $(= 64\text{ms}/500\text{ns})$

2. *Refresh more frequently*
   - Shorten refresh-interval by $\sim 7\text{x}$

Both naive solutions introduce significant overhead in performance and power

Apple's Patch for RowHammer

- https://support.apple.com/en-gb/HT204934

Available for: OS X Mountain Lion v10.8.5, OS X Mavericks v10.9.5

Impact: A malicious application may induce memory corruption to escalate privileges

Description: A disturbance error, also known as Rowhammer, exists with some DDR3 RAM that could have led to memory corruption. This issue was mitigated by increasing memory refresh rates.

CVE-ID

CVE-2015-3693 : Mark Seaborn and Thomas Dullien of Google, working from original research by Yoongu Kim et al (2014)

HP, Lenovo, and other vendors released similar patches

Our Solution to RowHammer

- **PARA:** *Probabilistic Adjacent Row Activation*
- **Key Idea**
  - **After closing a row, we activate (i.e., refresh) one of its neighbors with a low probability**: $p = 0.005$
- **Reliability Guarantee**
  - When $p=0.005$, errors in one year: 9.4×10^{-14}
  - By adjusting the value of p, we can vary the strength of protection against errors

Advantages of PARA

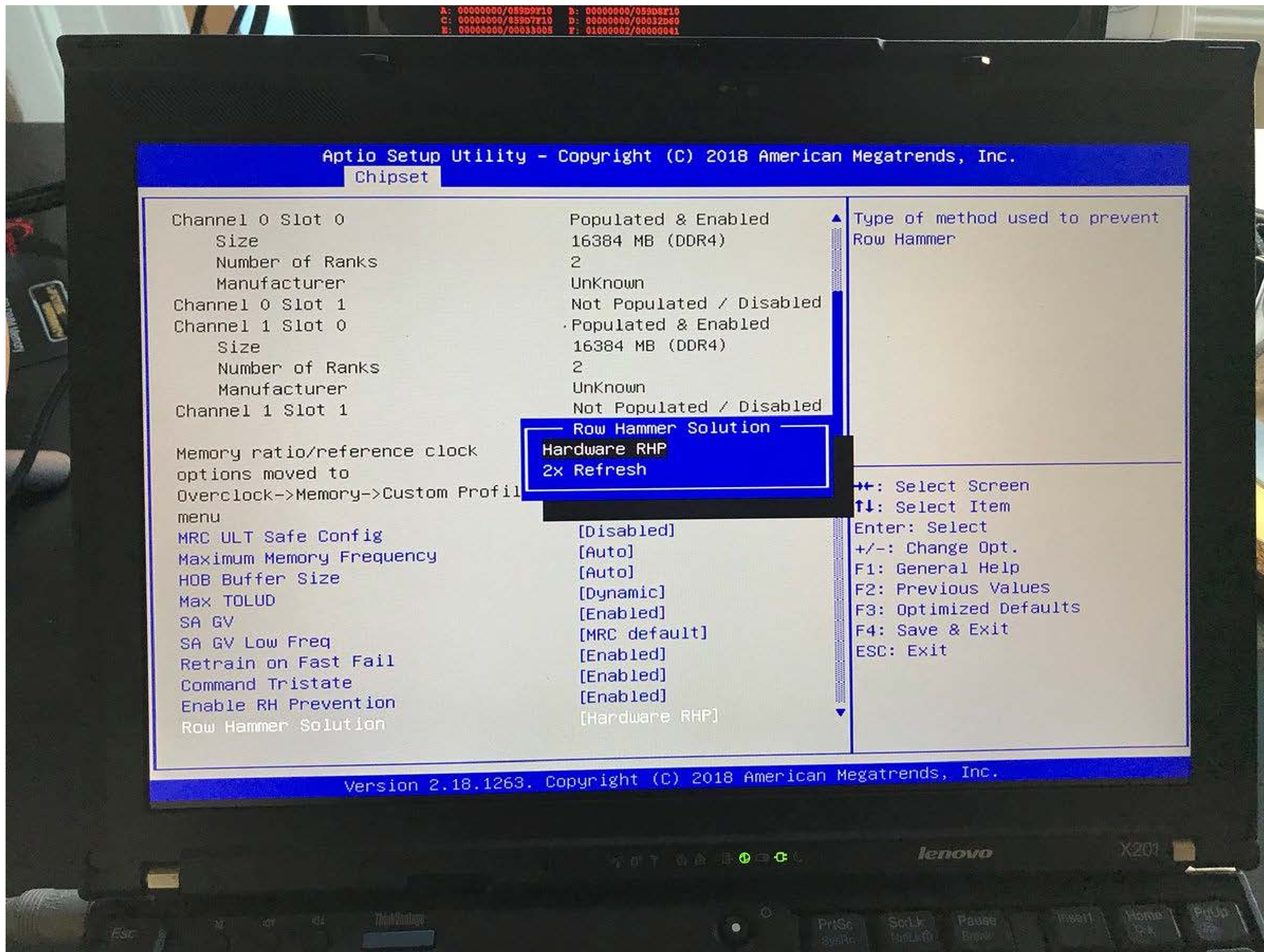
- *PARA refreshes rows infrequently*
  - Low power
  - Low performance-overhead
    - Average slowdown: 0.20% (for 29 benchmarks)
    - Maximum slowdown: 0.75%
- *PARA is stateless*
  - Low cost
  - Low complexity
- *PARA is an effective and low-overhead solution to prevent disturbance errors*

Requirements for PARA

- If implemented in DRAM chip
  - Enough slack in timing parameters
  - Plenty of slack today:
    - Lee et al., "**Adaptive-Latency DRAM: Optimizing DRAM Timing for the Common Case**," HPCA 2015.
    - Chang et al., "**Understanding Latency Variation in Modern DRAM Chips**," SIGMETRICS 2016.
    - Lee et al., "**Design-Induced Latency Variation in Modern DRAM Chips**," SIGMETRICS 2017.
    - Chang et al., "**Understanding Reduced-Voltage Operation in Modern DRAM Devices**," SIGMETRICS 2017.
    - Ghose et al., "**What Your DRAM Power Models Are Not Telling You: Lessons from a Detailed Experimental Study**," SIGMETRICS 2018.

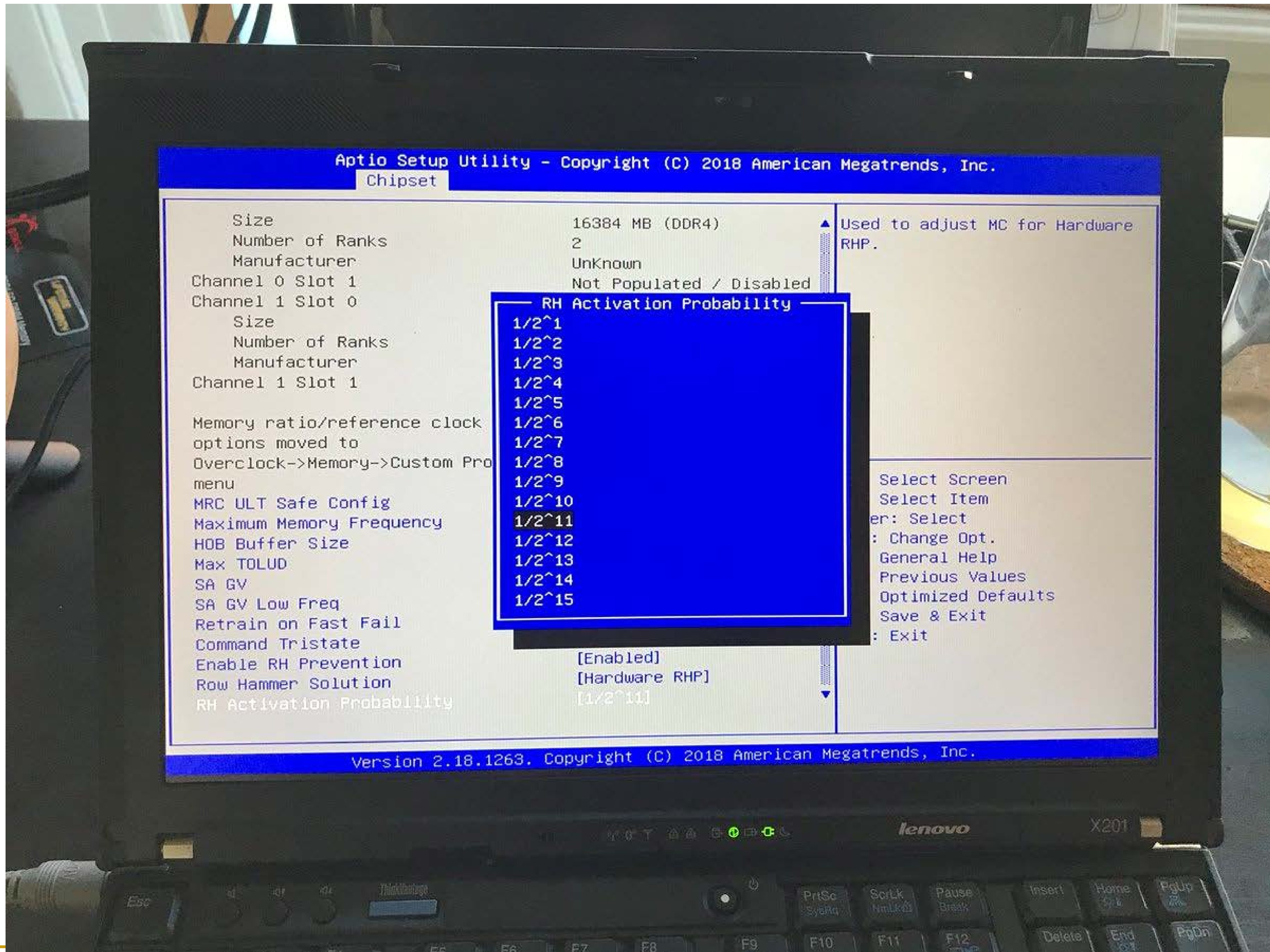
- If implemented in memory controller
  - Better coordination between memory controller and DRAM

Probabilistic Activation in Real Life (I)



https://twitter.com/isislovecruft/status/1021939922754723841

Probabilistic Activation in Real Life (II)



https://twitter.com/isislovecruft/status/1021939922754723841

More on RowHammer Analysis

- Yoongu Kim, Ross Daly, Jeremie Kim, Chris Fallin, Ji Hye Lee, Donghyuk Lee, Chris Wilkerson, Konrad Lai, and Onur Mutlu, **"Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors"** *Proceedings of the 41st International Symposium on Computer Architecture* ***(ISCA)***, Minneapolis, MN, June 2014. [Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)] [Source Code and Data]

Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors

Yoongu Kim[1] Ross Daly* Jeremie Kim[1] Chris Fallin* Ji Hye Lee[1]
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Future of Memory Reliability

- Onur Mutlu,
  "The RowHammer Problem and Other Issues We May Face as Memory Becomes Denser"
  *Invited Paper in Proceedings of the Design, Automation, and Test in Europe Conference (**DATE**)*, Lausanne, Switzerland, March 2017.
  [Slides (pptx) (pdf)]

The RowHammer Problem and Other Issues We May Face as Memory Becomes Denser

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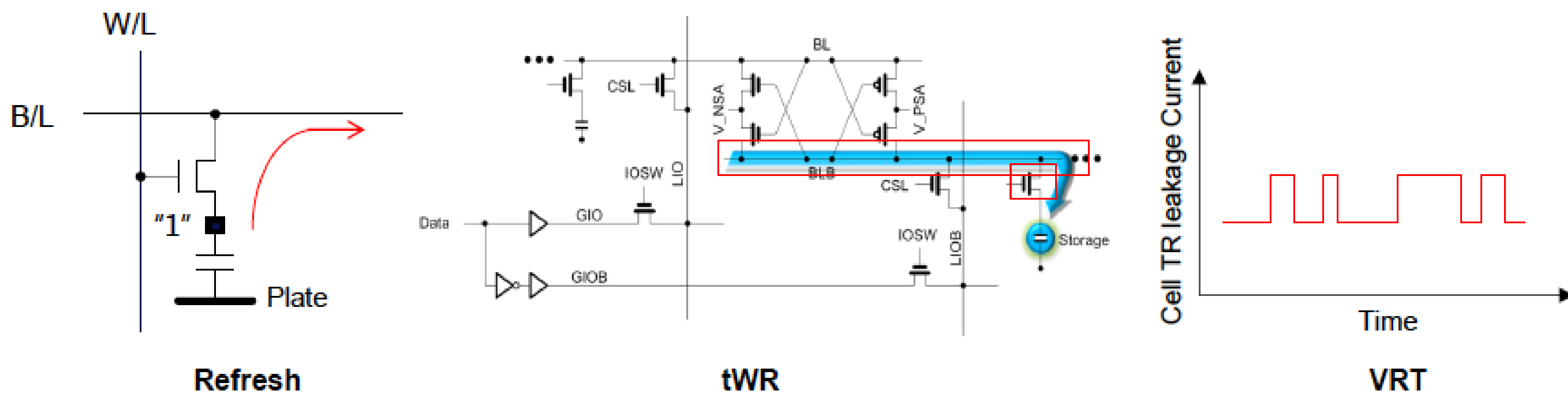
https://people.inf.ethz.ch/omutlu

Industry Is Writing Papers About It, Too

DRAM Process Scaling Challenges

- ❖ **Refresh**
  - Difficult to build high-aspect ratio cell capacitors decreasing cell capacitance
  - Leakage current of cell access transistors increasing
- ❖ **tWR**
  - Contact resistance between the cell capacitor and access transistor increasing
  - On-current of the cell access transistor decreasing
  - Bit-line resistance increasing
- ❖ **VRT**
  - Occurring more frequently with cell capacitance decreasing



Refresh **tWR** **VRT**

Call for Intelligent Memory Controllers

DRAM Process Scaling Challenges

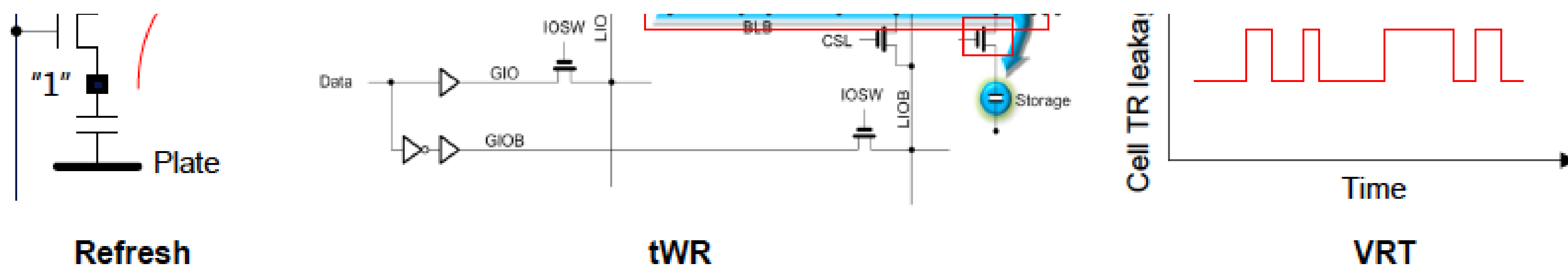
- **Refresh**
  - Difficult to build high-aspect ratio cell capacitors decreasing cell capacitance

THE MEMORY FORUM 2014

Co-Architecting Controllers and DRAM to Enhance DRAM Process Scaling

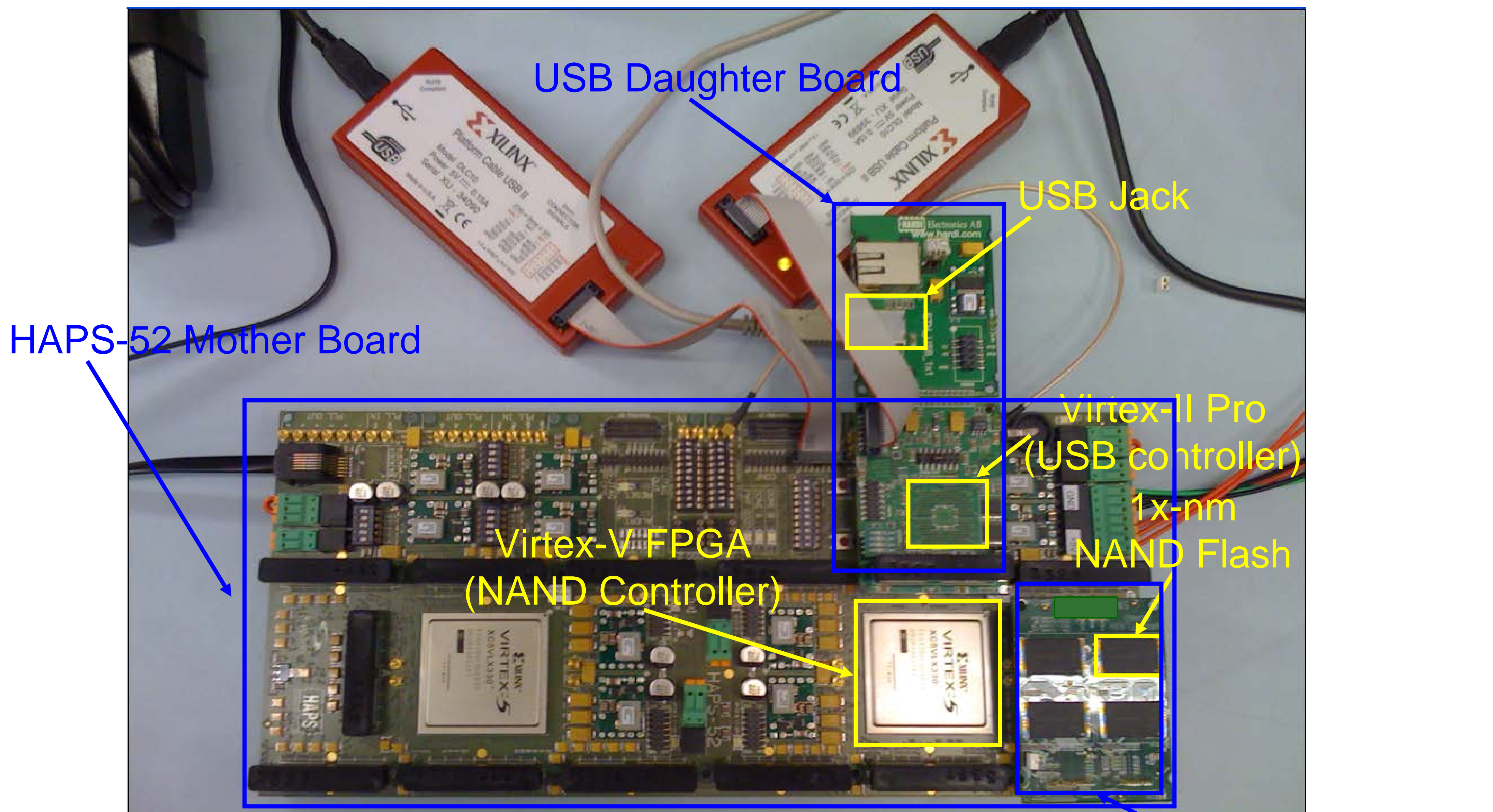
Uksong Kang, Hak-soo Yu, Churoo Park, *Hongzhong Zheng, **John Halbert, **Kuljit Bains, SeongJin Jang, and Joo Sun Choi

*Samsung Electronics, Hwasung, Korea / *Samsung Electronics, San Jose / **Intel*



SAMSUNG intel

Aside: Intelligent Controller for NAND Flash



[DATE 2012, ICCD 2012, DATE 2013, ITJ 2013, ICCD 2013, SIGMETRICS 2014, HPCA 2015, DSN 2015, MSST 2015, JSAC 2016, HPCA 2017, DFRWS 2017, PIEEE 2017, HPCA 2018, SIGMETRICS 2018]

Cai+, "Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives," Proc. IEEE 2017.

Aside: Intelligent Controller for NAND Flash

Proceedings of the IEEE, Sept. 2017

Error Characterization, Mitigation, and Recovery in Flash-Memory-Based Solid-State Drives

This paper reviews the most recent advances in solid-state drive (SSD) error characterization, mitigation, and data recovery techniques to improve both SSD's reliability and lifetime.

By Yu Cai, Saugata Ghose, Erich F. Haratsch, Yixin Luo, and Onur Mutlu

https://arxiv.org/pdf/1706.08642

A Key Takeaway

Main Memory Needs

Intelligent Controllers

Challenge and Opportunity for Future

Fundamentally

Secure, Reliable, Safe

Computing Architectures

Future Memory Reliability/Security Challenges

Future of Main Memory

- DRAM is becoming less reliable → more vulnerable

Large-Scale Failure Analysis of DRAM Chips

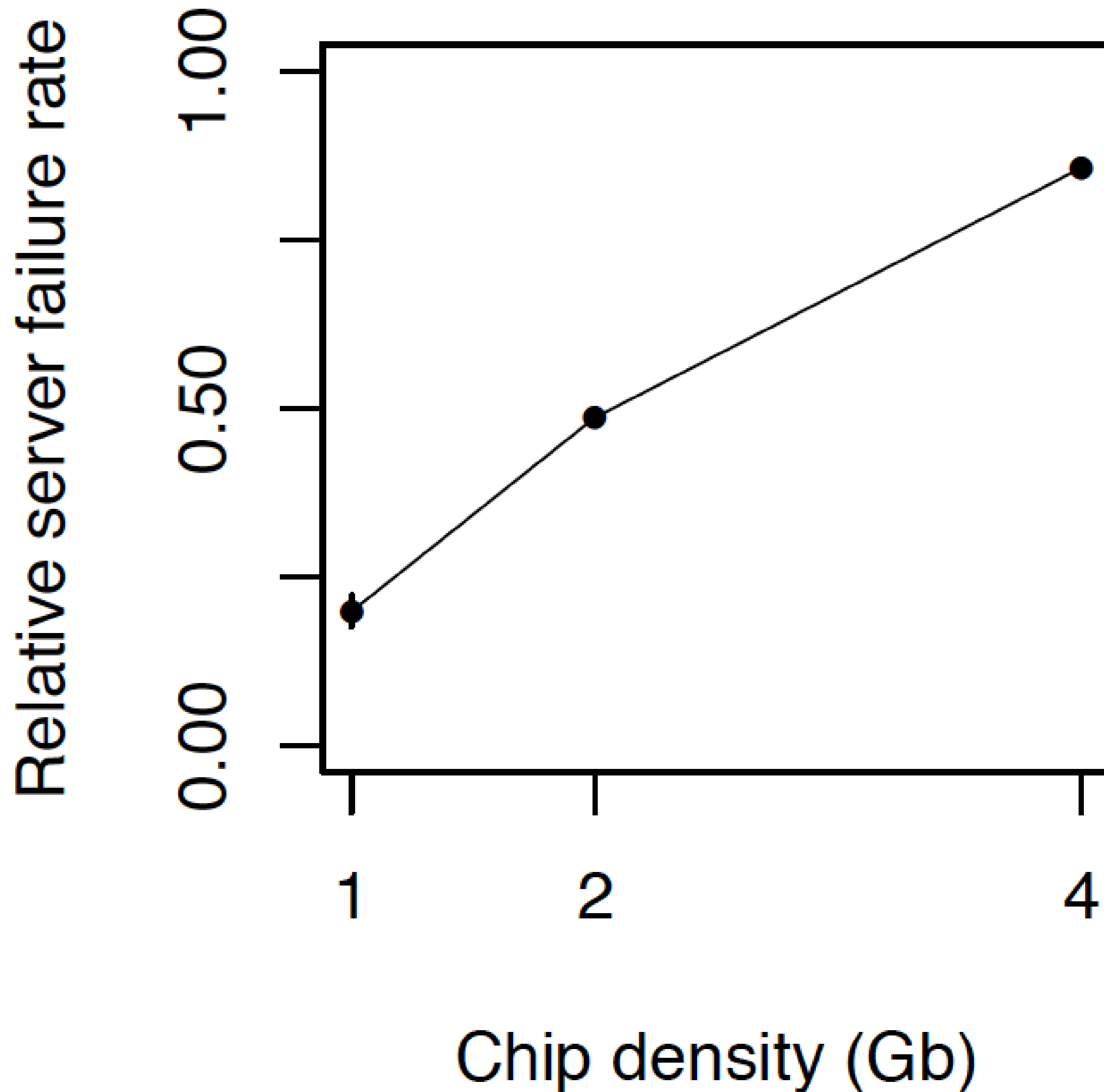
- Analysis and modeling of memory errors found in all of Facebook's server fleet

- Justin Meza, Qiang Wu, Sanjeev Kumar, and Onur Mutlu, **"Revisiting Memory Errors in Large-Scale Production Data Centers: Analysis and Modeling of New Trends from the Field"** *Proceedings of the 45th Annual IEEE/IFIP International Conference on Dependable Systems and Networks* ***(DSN)***, Rio de Janeiro, Brazil, June 2015.
  [Slides (pptx) (pdf)] [DRAM Error Model]

Revisiting Memory Errors in Large-Scale Production Data Centers: Analysis and Modeling of New Trends from the Field

Justin Meza Qiang Wu * Sanjeev Kumar * Onur Mutlu
Carnegie Mellon University * Facebook, Inc.

DRAM Reliability Reducing



Intuition: quadratic increase in capacity

Meza+, "Revisiting Memory Errors in Large-Scale Production Data Centers," DSN'15.

Future of Main Memory

- DRAM is becoming less reliable → more vulnerable
- Due to difficulties in DRAM scaling, other problems may also appear (or they may be going unnoticed)
- Some errors may already be slipping into the field
  - Read disturb errors (Rowhammer)
  - Retention errors
  - Read errors, write errors
  - ...
- These errors can also pose security vulnerabilities

DRAM Data Retention Time Failures

- Determining the data retention time of a cell/row is getting more difficult

- Retention failures may already be slipping into the field

Analysis of Data Retention Failures [ISCA'13]

- Jamie Liu, Ben Jaiyen, Yoongu Kim, Chris Wilkerson, and Onur Mutlu, **"An Experimental Study of Data Retention Behavior in Modern DRAM Devices: Implications for Retention Time Profiling Mechanisms"** *Proceedings of the 40th International Symposium on Computer Architecture* ***(ISCA)***, Tel-Aviv, Israel, June 2013. Slides (ppt) Slides (pdf)

An Experimental Study of Data Retention Behavior in Modern DRAM Devices: Implications for Retention Time Profiling Mechanisms

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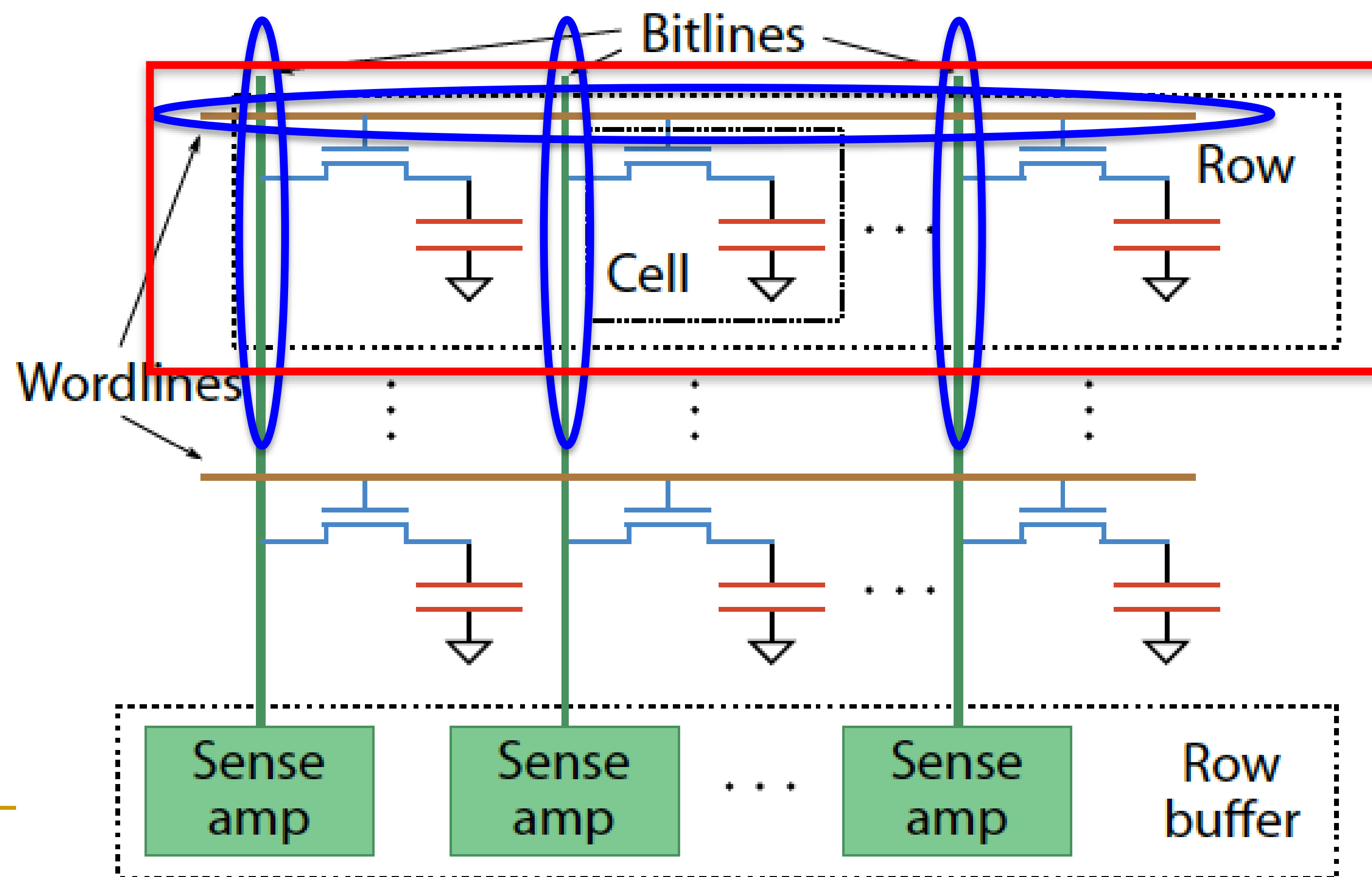
Two Challenges to Retention Time Profiling

- Data Pattern Dependence (DPD) of retention time

- Variable Retention Time (VRT) phenomenon

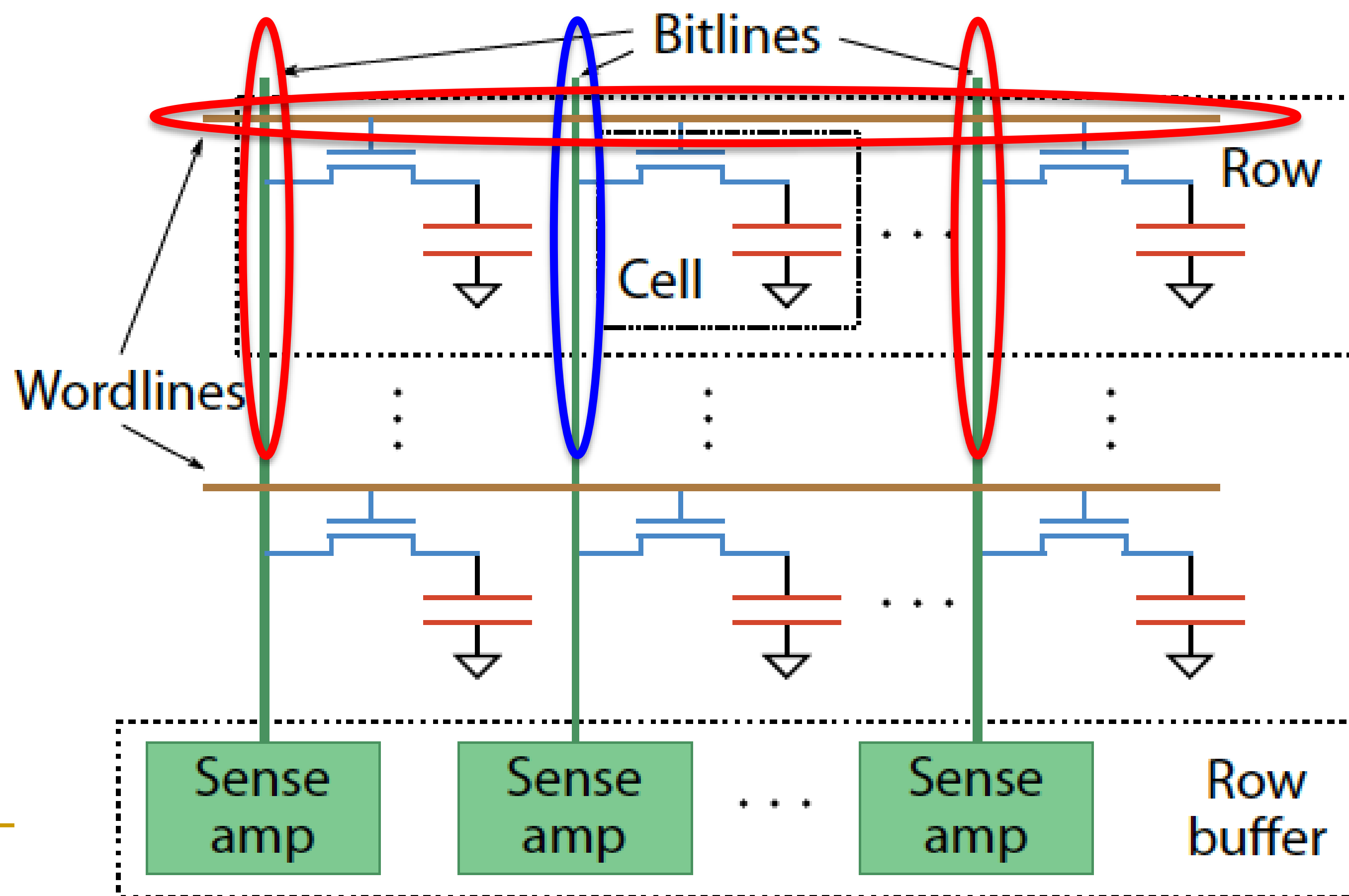
Two Challenges to Retention Time Profiling

- Challenge 1: Data Pattern Dependence (DPD)
  - Retention time of a DRAM cell depends on its value and the values of cells nearby it
  - When a row is activated, all bitlines are perturbed simultaneously



Data Pattern Dependence

- Electrical noise on the bitline affects reliable sensing of a DRAM cell
- The magnitude of this noise is affected by values of nearby cells via
  - Bitline-bitline coupling → electrical coupling between adjacent bitlines
  - Bitline-wordline coupling → electrical coupling between each bitline and the activated wordline



Data Pattern Dependence

- Electrical noise on the bitline affects reliable sensing of a DRAM cell
- The magnitude of this noise is affected by values of nearby cells via
  - Bitline-bitline coupling → electrical coupling between adjacent bitlines
  - Bitline-wordline coupling → electrical coupling between each bitline and the activated wordline

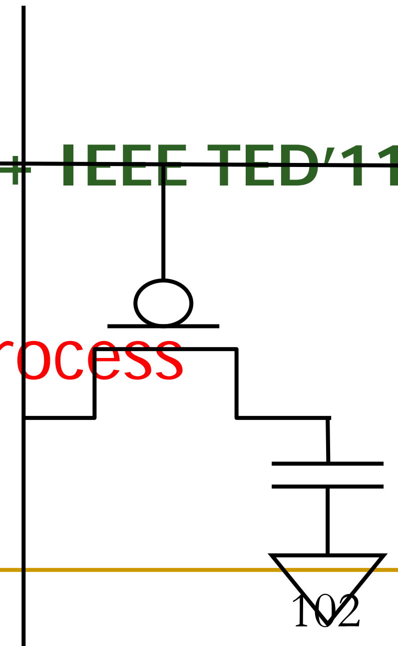
- Retention time of a cell depends on data patterns stored in nearby cells

  → need to find the worst data pattern to find worst-case retention time

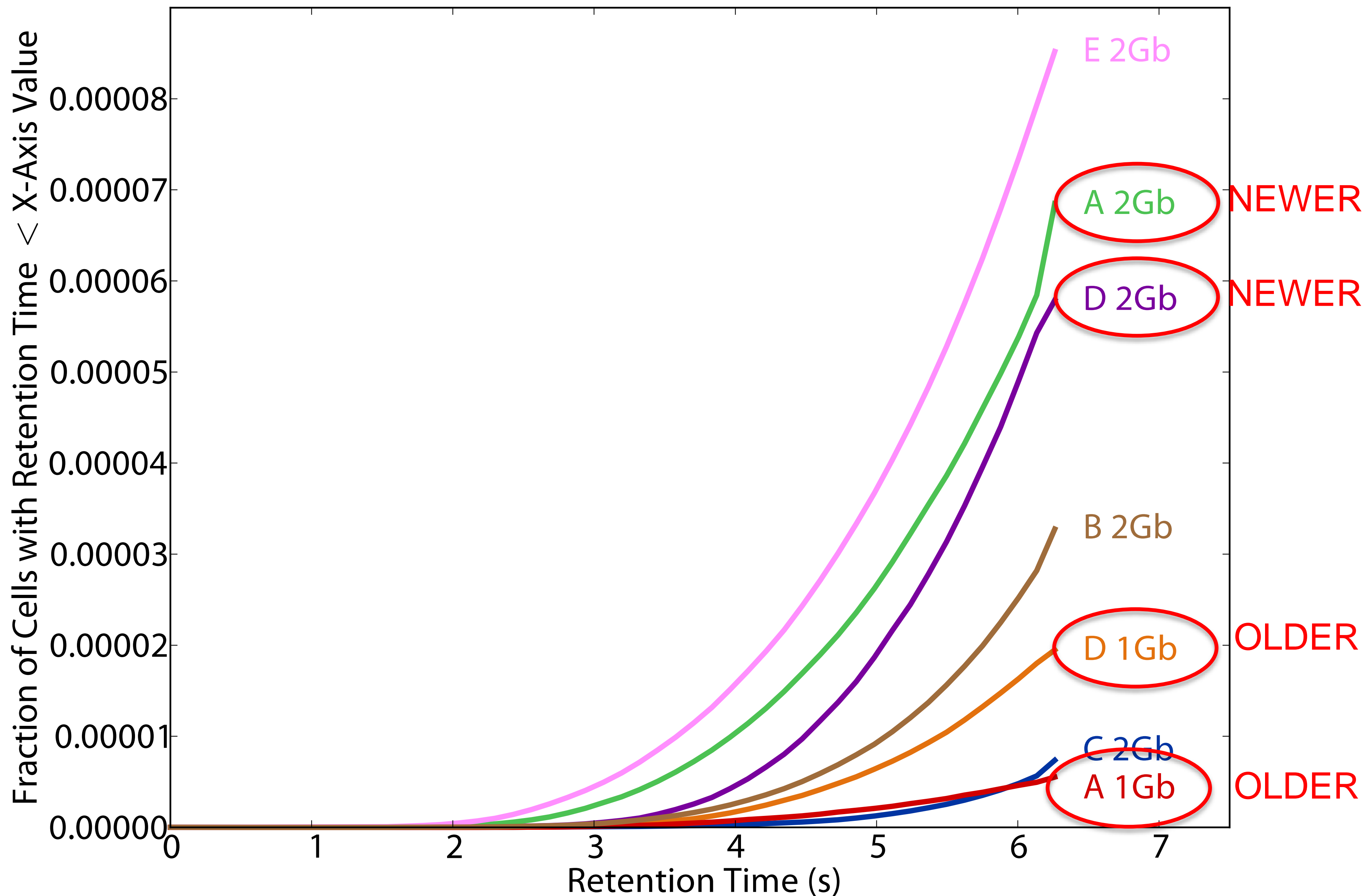
  → this pattern is location dependent

Two Challenges to Retention Time Profiling

- Challenge 2: Variable Retention Time (VRT)
  - Retention time of a DRAM cell changes randomly over time
    - a cell alternates between multiple retention time states
  - Leakage current of a cell changes sporadically due to a charge trap in the gate oxide of the DRAM cell access transistor
  - When the trap becomes occupied, charge leaks more readily from the transistor's drain, leading to a short retention time
    - Called *Trap-Assisted Gate-Induced Drain Leakage*
  - This process appears to be a random process **[Kim+ IEEE TED'11]**
  - Worst-case retention time depends on a random process → need to find the worst case despite this

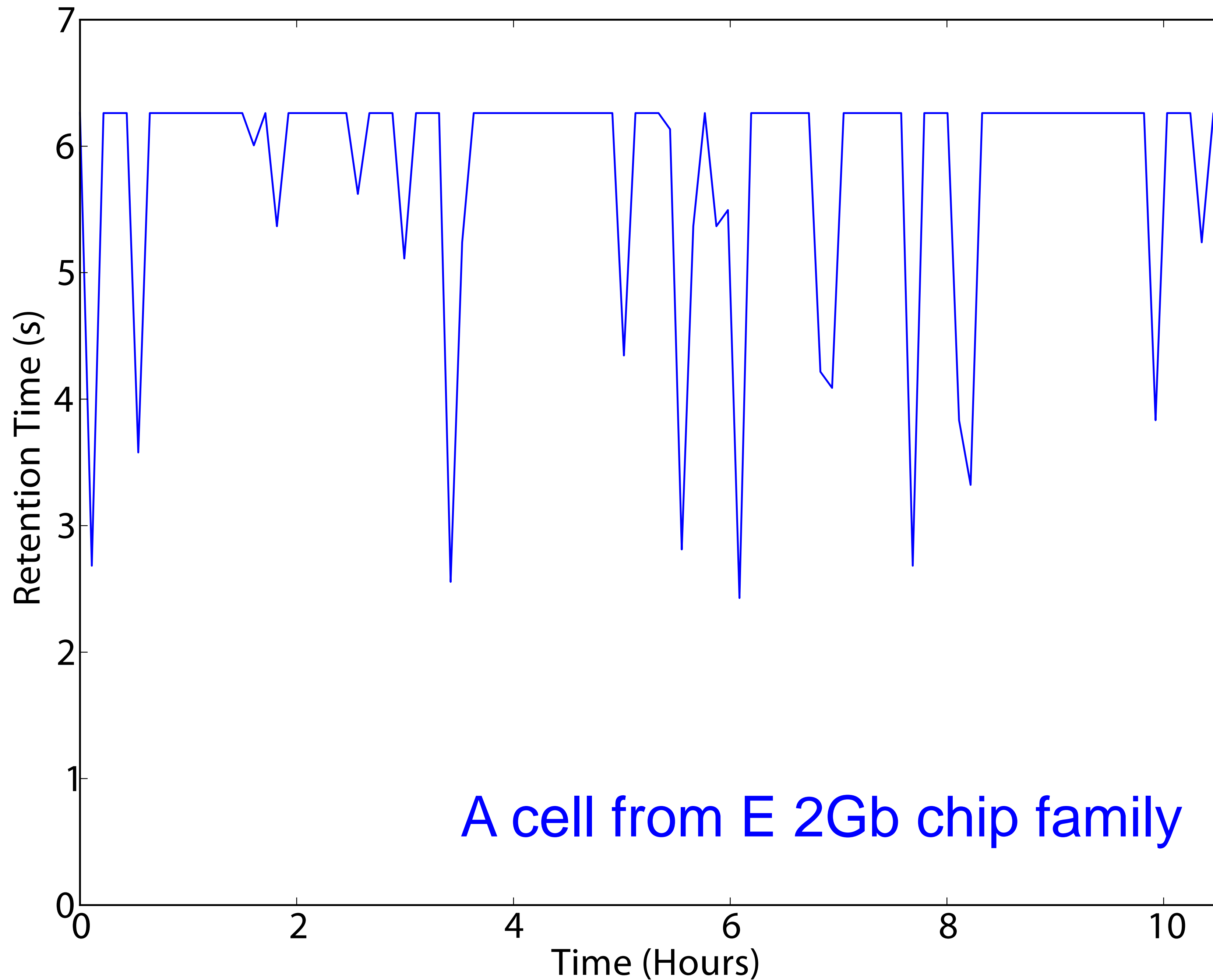


Modern DRAM Retention Time Distribution

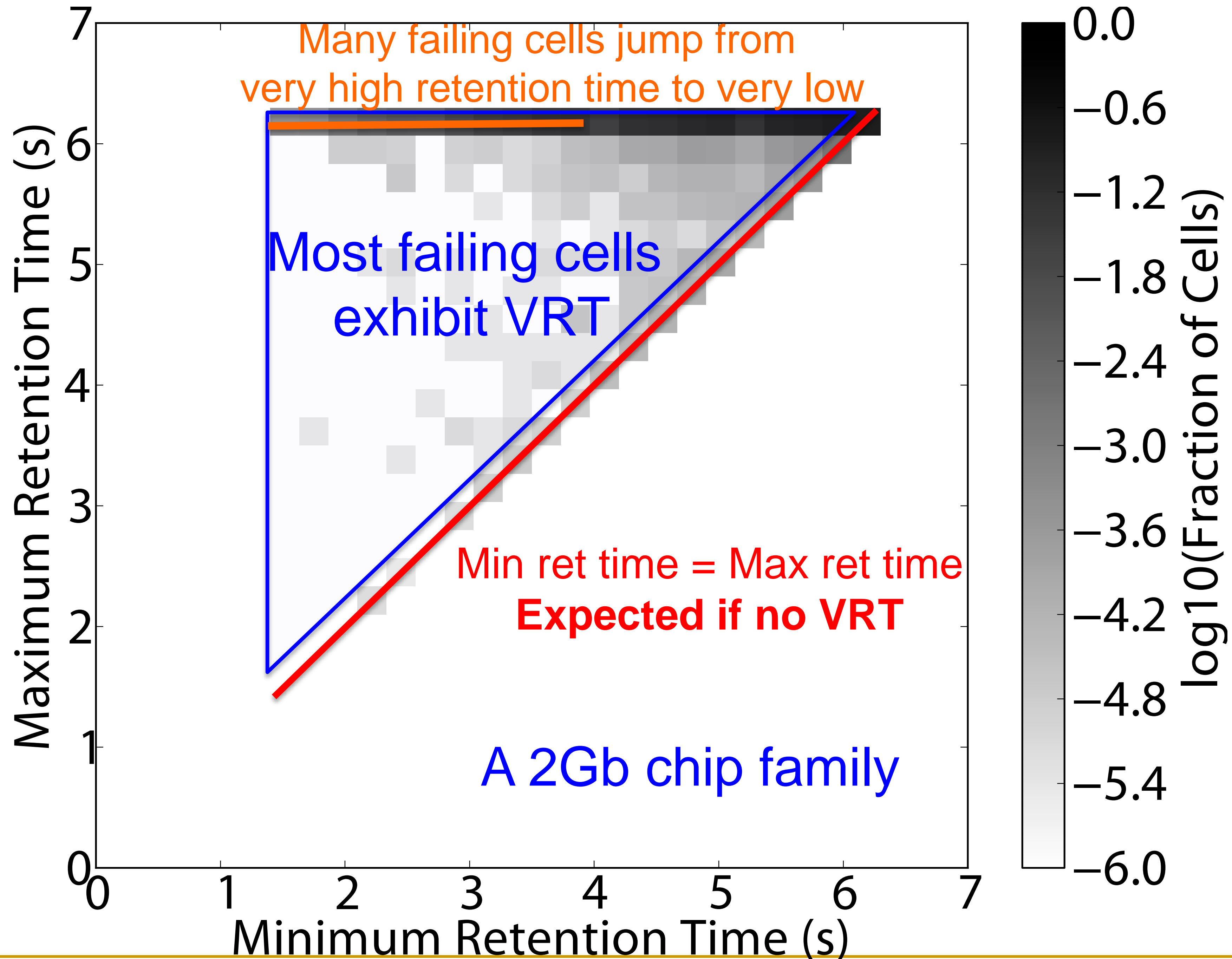


Newer device families have more weak cells than older ones
Likely a result of technology scaling

An Example VRT Cell



Variable Retention Time



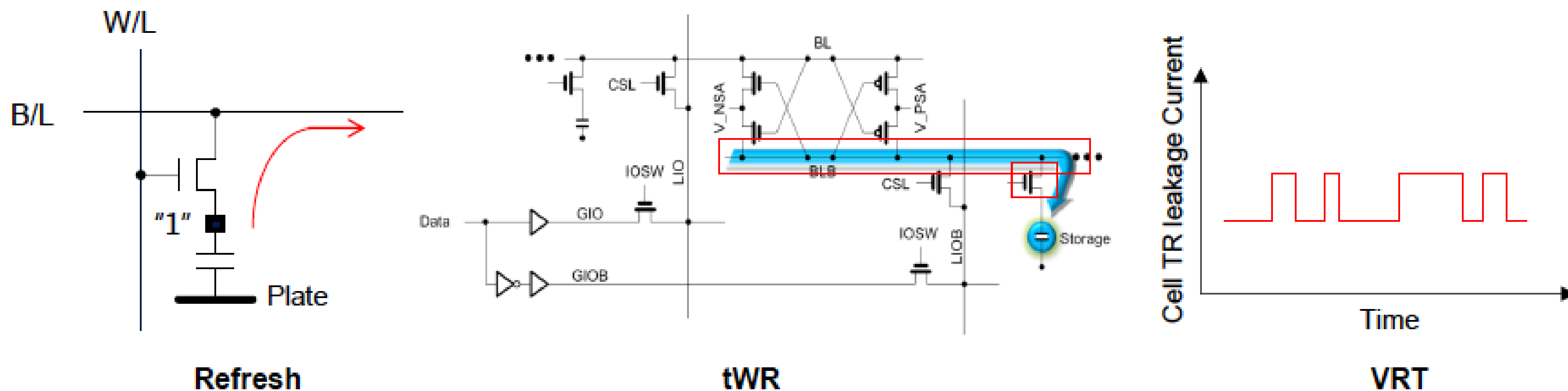
Industry Is Writing Papers About It, Too

DRAM Process Scaling Challenges

❖ **Refresh**
- Difficult to build high-aspect ratio cell capacitors decreasing cell capacitance
- Leakage current of cell access transistors increasing

❖ **tWR**
- Contact resistance between the cell capacitor and access transistor increasing
- On-current of the cell access transistor decreasing
- Bit-line resistance increasing

❖ **VRT**
- Occurring more frequently with cell capacitance decreasing



SAMSUNG intel

Industry Is Writing Papers About It, Too

DRAM Process Scaling Challenges

❖ **Refresh**

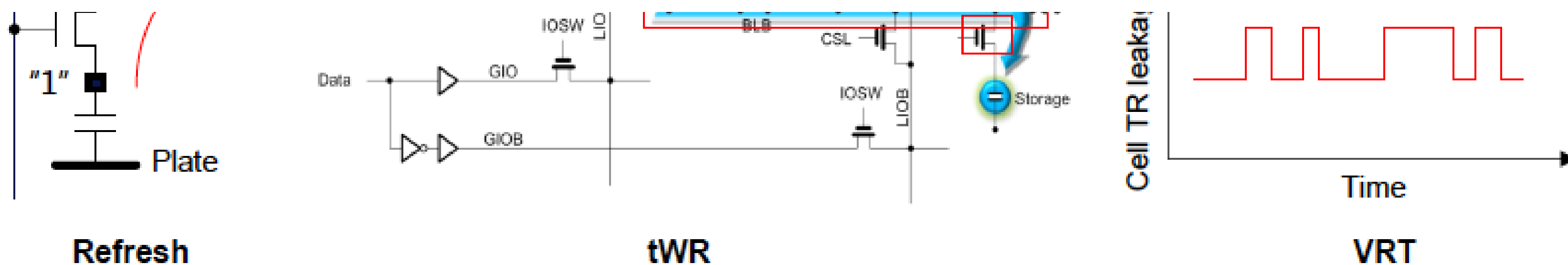
- Difficult to build high-aspect ratio cell capacitors decreasing cell capacitance

THE MEMORY FORUM 2014

Co-Architecting Controllers and DRAM to Enhance DRAM Process Scaling

Uksong Kang, Hak-soo Yu, Churoo Park, *Hongzhong Zheng, **John Halbert, **Kuljit Bains, SeongJin Jang, and Joo Sun Choi

*Samsung Electronics, Hwasung, Korea / *Samsung Electronics, San Jose / **Intel*



Mitigation of Retention Issues [SIGMETRICS'14]

- Samira Khan, Donghyuk Lee, Yoongu Kim, Alaa Alameldeen, Chris Wilkerson, and Onur Mutlu,
"The Efficacy of Error Mitigation Techniques for DRAM Retention Failures: A Comparative Experimental Study"
Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems (SIGMETRICS), Austin, TX, June 2014. [Slides (pptx) (pdf)] [Poster (pptx) (pdf)] [Full data sets]

The Efficacy of Error Mitigation Techniques for DRAM Retention Failures: A Comparative Experimental Study

Samira Khan†* samirakhan@cmu.edu

Donghyuk Lee† donghyuk1@cmu.edu

Yoongu Kim† yoongukim@cmu.edu

Alaa R. Alameldeen* alaa.r.alameldeen@intel.com

Chris Wilkerson* chris.wilkerson@intel.com

Onur Mutlu† onur@cmu.edu

†Carnegie Mellon University *Intel Labs

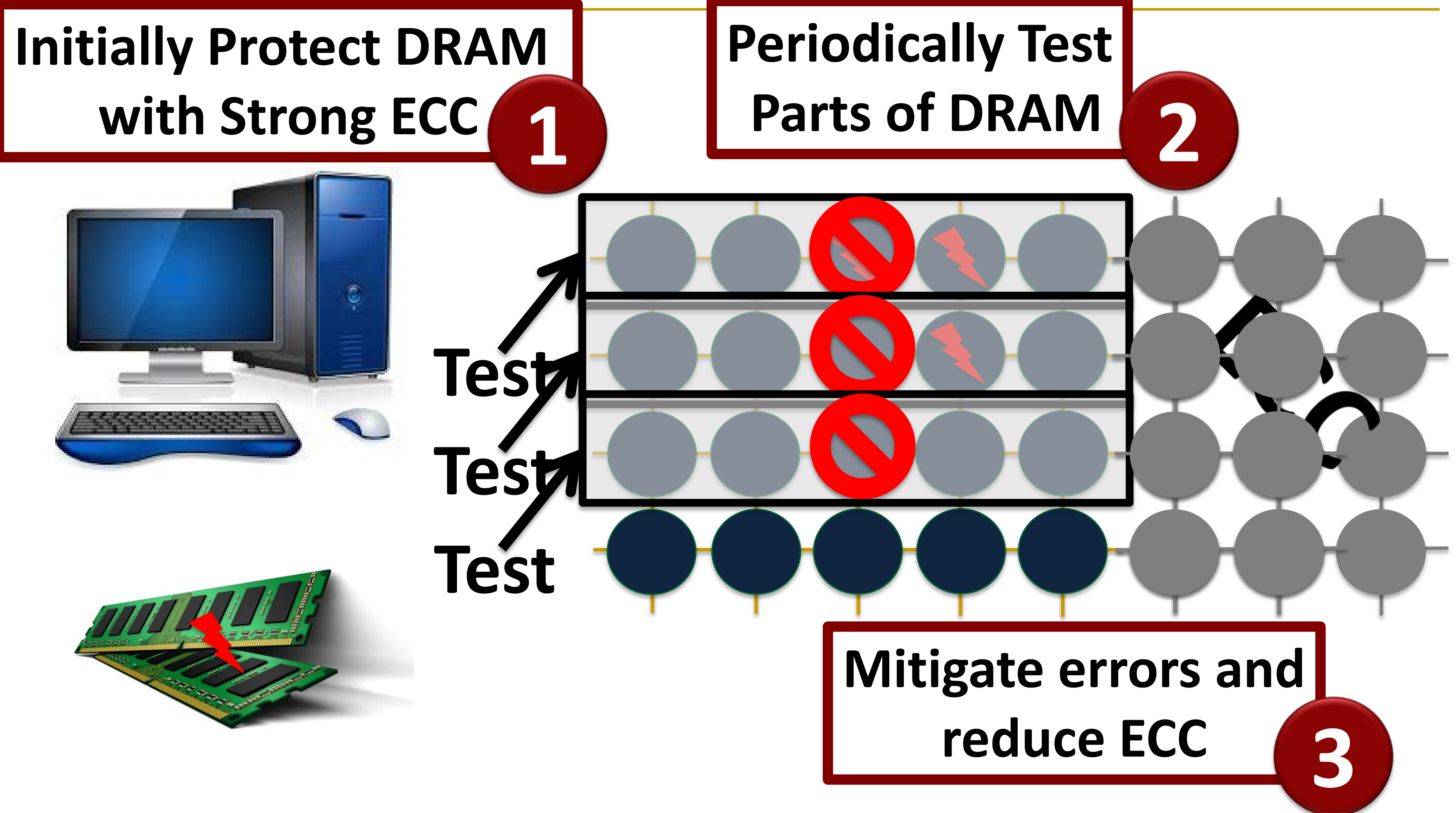
Towards an Online Profiling System

Key Observations:

- **Testing alone cannot detect all possible failures**
- **Combination of ECC and other mitigation techniques is much more effective**
  - **But degrades performance**
- **Testing can help to reduce the ECC strength**
  - **Even when starting with a higher strength ECC**

Khan+, "The Efficacy of Error Mitigation Techniques for DRAM Retention Failures: A Comparative Experimental Study," SIGMETRICS 2014.

Towards an Online Profiling System



Run tests periodically after a short interval at smaller regions of memory

Handling Variable Retention Time [DSN'15]

- Moinuddin Qureshi, Dae Hyun Kim, Samira Khan, Prashant Nair, and Onur Mutlu, **"AVATAR: A Variable-Retention-Time (VRT) Aware Refresh for DRAM Systems"**
  *Proceedings of the 45th Annual IEEE/IFIP International Conference on Dependable Systems and Networks (**DSN**)*, Rio de Janeiro, Brazil, June 2015.
  [Slides (pptx) (pdf)]

AVATAR: A Variable-Retention-Time (VRT) Aware Refresh for DRAM Systems

Moinuddin K. Qureshi† Dae-Hyun Kim† Samira Khan‡ Prashant J. Nair† Onur Mutlu‡
†Georgia Institute of Technology
{moin, dhkim, pnair6}@ece.gatech.edu
‡Carnegie Mellon University
{samirakhan, onur}@cmu.edu

Handling Data-Dependent Failures [DSN'16]

- Samira Khan, Donghyuk Lee, and Onur Mutlu,
  "PARBOR: An Efficient System-Level Technique to Detect Data-Dependent Failures in DRAM"
  Proceedings of the 45th Annual IEEE/IFIP International Conference on Dependable Systems and Networks ***(DSN)***, Toulouse, France, June 2016.
  [Slides (pptx) (pdf)]

PARBOR: An Efficient System-Level Technique to Detect Data-Dependent Failures in DRAM

Samira Khan[⋆] Donghyuk Lee[†‡] Onur Mutlu[*†]
[⋆]University of Virginia [†]Carnegie Mellon University [‡]Nvidia [*]ETH Zürich

Handling Data-Dependent Failures [MICRO'17]

- Samira Khan, Chris Wilkerson, Zhe Wang, Alaa R. Alameldeen, Donghyuk Lee, and Onur Mutlu,
  "Detecting and Mitigating Data-Dependent DRAM Failures by Exploiting Current Memory Content"
  Proceedings of the 50th International Symposium on Microarchitecture ***(MICRO)***, Boston, MA, USA, October 2017.
  [Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)] [Poster (pptx) (pdf)]

Detecting and Mitigating Data-Dependent DRAM Failures by Exploiting Current Memory Content

Samira Khan[⋆] Chris Wilkerson[†] Zhe Wang[†] Alaa R. Alameldeen[†] Donghyuk Lee[‡] Onur Mutlu[*]
[⋆]University of Virginia [†]Intel Labs [‡]Nvidia Research [*]ETH Zürich

Handling Both DPD and VRT [ISCA'17]

- Minesh Patel, Jeremie S. Kim, and Onur Mutlu,
  "The Reach Profiler (REAPER): Enabling the Mitigation of DRAM Retention Failures via Profiling at Aggressive Conditions"
  *Proceedings of the 44th International Symposium on Computer Architecture (**ISCA**)*, Toronto, Canada, June 2017.
  [Slides (pptx) (pdf)]
  [Lightning Session Slides (pptx) (pdf)]

- First experimental analysis of (mobile) LPDDR4 chips
- Analyzes the complex tradeoff space of retention time profiling
- Idea: enable fast and robust profiling at higher refresh intervals & temperatures

The Reach Profiler (REAPER): Enabling the Mitigation of DRAM Retention Failures via Profiling at Aggressive Conditions

Minesh Patel[§‡] Jeremie S. Kim[‡§] Onur Mutlu[§‡]
[§]ETH Zürich [‡]Carnegie Mellon University

The DRAM Latency PUF:

Quickly Evaluating Physical Unclonable Functions by Exploiting the Latency-Reliability Tradeoff in Modern Commodity DRAM Devices

Jeremie S. Kim **Minesh Patel**
Hasan Hassan **Onur Mutlu**

QR Code for the paper
https://people.inf.ethz.ch/omutlu/pub/dram-latency-puf_hpca18.pdf

HPCA 2018

SAFARI

ETH Zürich SAFARI

Carnegie Mellon

Keeping Future Memory Secure

How Do We Keep Memory Secure?

- DRAM
- Flash memory
- Emerging Technologies
  - Phase Change Memory
  - STT-MRAM
  - RRAM, memristors
  - ...

Solution Direction: Principled Designs

Design fundamentally secure computing architectures

Predict and prevent such safety issues

Recall: Collapse of the "Galloping Gertie"

Source: AP
http://www.wsdot.wa.gov/tnbhistory/connections/connections3.htm

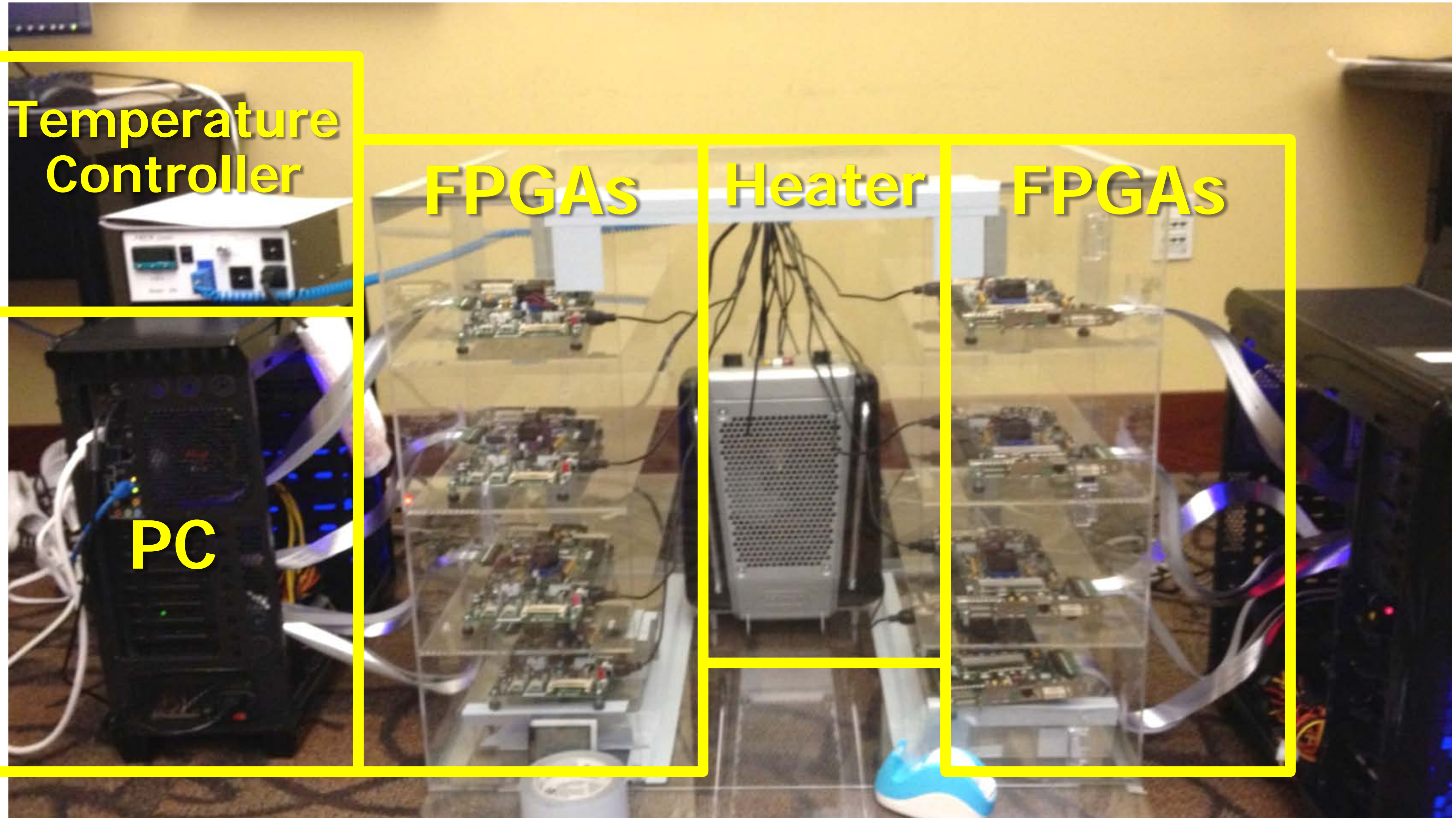
How Do We Keep Memory Secure?

- Understand: Solid methodologies for failure modeling and discovery
  - Modeling based on real device data – small scale and large scale
  - Metrics for secure architectures

- Architect: Principled co-architecting of system and memory
  - Good partitioning of duties across the stack
  - Patch-ability in the field

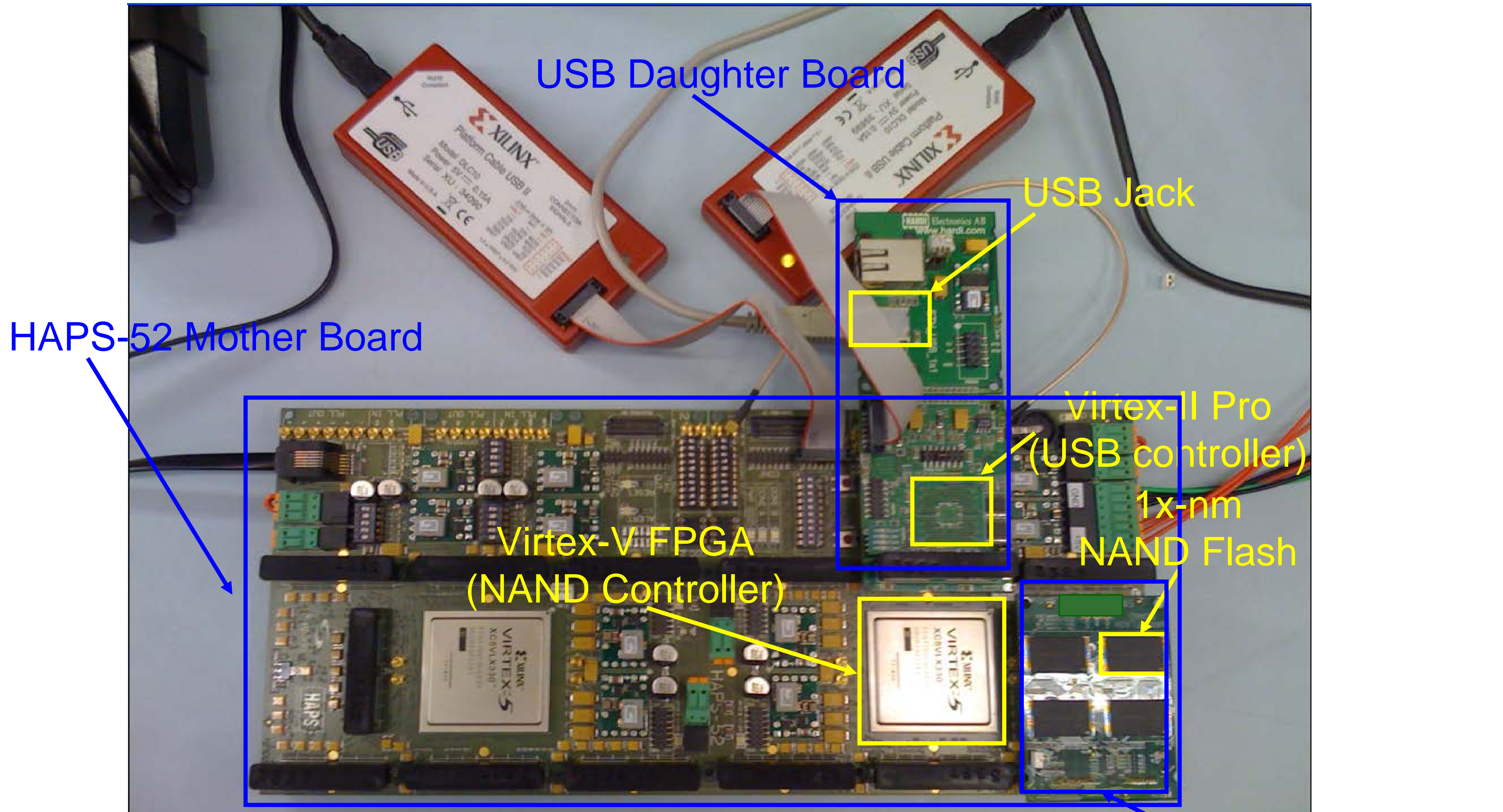
- Design & Test: Principled electronic design, automation, testing
  - Design for security
  - High coverage and good interaction with reliability methods

Understand and Model with Experiments (DRAM)



Kim+, "Flipping Bits in Memory Without Accessing Them: An Experimental Study of DRAM Disturbance Errors," ISCA 2014.

Understand and Model with Experiments (Flash)



[DATE 2012, ICCD 2012, DATE 2013, ITJ 2013, ICCD 2013, SIGMETRICS 2014, HPCA 2015, DSN 2015, MSST 2015, JSAC 2016, HPCA 2017, DFRWS 2017, PIEEE'17, HPCA'18, SIGMETRICS'18]

Cai+, "Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives," Proc. IEEE 2017.

Understanding Flash Memory Reliability

Proceedings of the IEEE, Sept. 2017

Error Characterization, Mitigation, and Recovery in Flash-Memory-Based Solid-State Drives

This paper reviews the most recent advances in solid-state drive (SSD) error characterization, mitigation, and data recovery techniques to improve both SSD's reliability and lifetime.

By Yu Cai, Saugata Ghose, Erich F. Haratsch, Yixin Luo, and Onur Mutlu

https://arxiv.org/pdf/1706.08642

Understanding Flash Memory Reliability

- Justin Meza, Qiang Wu, Sanjeev Kumar, and Onur Mutlu,
  "A Large-Scale Study of Flash Memory Errors in the Field"
  Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems (***SIGMETRICS***), Portland, OR, June 2015.
  [Slides (pptx) (pdf)] [Coverage at ZDNet] [Coverage on The Register] [Coverage on TechSpot] [Coverage on The Tech Report]

A Large-Scale Study of Flash Memory Failures in the Field

Justin Meza	Qiang Wu	Sanjeev Kumar	Onur Mutlu
Carnegie Mellon University	Facebook, Inc.	Facebook, Inc.	Carnegie Mellon University
meza@cmu.edu	qwu@fb.com	skumar@fb.com	onur@cmu.edu

NAND Flash Vulnerabilities **[HPCA'17]**

HPCA, Feb. 2017

Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques

Yu Cai[†] Saugata Ghose[†] Yixin Luo[‡†] Ken Mai[†] Onur Mutlu[§†] Erich F. Haratsch[‡]
[†]*Carnegie Mellon University* [‡]*Seagate Technology* [§]*ETH Zürich*

Modern NAND flash memory chips provide high density by storing two bits of data in each flash cell, called a multi-level cell *(MLC). An MLC partitions the threshold voltage range of a flash cell into four* voltage states. *When a flash cell is programmed, a high voltage is applied to the cell. Due to parasitic capacitance coupling between flash cells that are physically close to each other, flash cell programming can lead to* cell-to-cell program interference, *which introduces errors into* neighboring *flash cells. In order to reduce the impact of cell-to-cell interference on the reliability of MLC NAND flash memory, flash manufacturers adopt a* two-step programming method, *which programs the MLC in two separate steps. First, the flash memory partially programs the least significant bit of the MLC to some intermediate threshold voltage. Second, it programs the most significant bit to bring the MLC up to its full voltage state.*

In this paper, we demonstrate that two-step programming exposes new reliability and security vulnerabilities. We expe-

belongs to a different flash memory *page* (the unit of data programmed and read at the same time), which we refer to, respectively, as the least significant bit (LSB) page and the most significant bit (MSB) page [5].

A flash cell is programmed by applying a large voltage on the control gate of the transistor, which triggers charge transfer into the floating gate, thereby increasing the threshold voltage. To precisely control the threshold voltage of the cell, the flash memory uses *incremental step pulse programming* (ISPP) [12, 21, 25, 41]. ISPP applies multiple short pulses of the programming voltage to the control gate, in order to increase the cell threshold voltage by some small voltage amount (V_{step}) after each step. Initial MLC designs programmed the threshold voltage in *one shot*, issuing all of the pulses back-to-back to program *both* bits of data at the same time. However, as flash memory scales down, the distance between neighboring flash cells decreases, which

https://people.inf.ethz.ch/omutlu/pub/flash-memory-programming-vulnerabilities_hpca17.pdf

3D NAND Flash Reliability I **[HPCA'18]**

- Yixin Luo, Saugata Ghose, Yu Cai, Erich F. Haratsch, and Onur Mutlu, **"HeatWatch: Improving 3D NAND Flash Memory Device Reliability by Exploiting Self-Recovery and Temperature-Awareness"**
  Proceedings of the 24th International Symposium on High-Performance Computer Architecture ***(HPCA)***, Vienna, Austria, February 2018.
  [Lightning Talk Video]
  [Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)]

HeatWatch: Improving 3D NAND Flash Memory Device Reliability by Exploiting Self-Recovery and Temperature Awareness

Yixin Luo[†] Saugata Ghose[†] Yu Cai[‡] Erich F. Haratsch[‡] Onur Mutlu[§†]
[†]*Carnegie Mellon University* [‡]*Seagate Technology* [§]*ETH Zürich*

3D NAND Flash Reliability II [SIGMETRICS'18]

- Yixin Luo, Saugata Ghose, Yu Cai, Erich F. Haratsch, and Onur Mutlu, **"Improving 3D NAND Flash Memory Lifetime by Tolerating Early Retention Loss and Process Variation"** *Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems* ***(SIGMETRICS)***, Irvine, CA, USA, June 2018.
[Abstract]

Improving 3D NAND Flash Memory Lifetime by Tolerating Early Retention Loss and Process Variation

Yixin Luo[†] Saugata Ghose[†] Yu Cai[†] Erich F. Haratsch[‡] Onur Mutlu[§†]

[†]Carnegie Mellon University [‡]Seagate Technology [§]ETH Zürich

Potential NAND Flash Memory Vulnerabilities

- Yu Cai, Saugata Ghose, Erich F. Haratsch, Yixin Luo, and Onur Mutlu, **"Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives"** *Proceedings of the IEEE*, September 2017.

Cai+, "Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis," DATE 2012.

Cai+, "Flash Correct-and-Refresh: Retention-Aware Error Management for Increased Flash Memory Lifetime," ICCD 2012.

Cai+, "Threshold Voltage Distribution in MLC NAND Flash Memory: Characterization, Analysis and Modeling," DATE 2013.

Cai+, "Error Analysis and Retention-Aware Error Management for NAND Flash Memory," Intel Technology Journal 2013.

Cai+, "Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation," ICCD 2013.

Cai+, "Neighbor-Cell Assisted Error Correction for MLC NAND Flash Memories," SIGMETRICS 2014.

Cai+,"Data Retention in MLC NAND Flash Memory: Characterization, Optimization and Recovery," HPCA 2015.

Cai+, "Read Disturb Errors in MLC NAND Flash Memory: Characterization and Mitigation," DSN 2015.

Luo+, "WARM: Improving NAND Flash Memory Lifetime with Write-hotness Aware Retention Management," MSST 2015.

Meza+, "A Large-Scale Study of Flash Memory Errors in the Field," SIGMETRICS 2015.

Luo+, "Enabling Accurate and Practical Online Flash Channel Modeling for Modern MLC NAND Flash Memory," IEEE JSAC 2016.

Cai+, "Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques," HPCA 2017.

Fukami+, "Improving the Reliability of Chip-Off Forensic Analysis of NAND Flash Memory Devices," DFRWS EU 2017.

Luo+, "HeatWatch: Improving 3D NAND Flash Memory Device Reliability by Exploiting Self-Recovery and Temperature-Awareness," HPCA 2018.

Luo+, "Improving 3D NAND Flash Memory Lifetime by Tolerating Early Retention Loss and Process Variation," SIGMETRICS 2018.

Cai+, "Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives," Proc. IEEE 2017.

There are Two Other Solution Directions

- **New Technologies:** Replace or (more likely) augment DRAM with a different technology
  - Non-volatile memories

- **Embracing Un-reliability:** Design memories with different reliability and store data intelligently across them **[Luo+ DSN 2014]**

- …

Fundamental solutions to security require co-design across the hierarchy

More on Heterogeneous-Reliability Memory

- Yixin Luo, Sriram Govindan, Bikash Sharma, Mark Santaniello, Justin Meza, Aman Kansal, Jie Liu, Badriddine Khessib, Kushagra Vaid, and Onur Mutlu, **"Characterizing Application Memory Error Vulnerability to Optimize Data Center Cost via Heterogeneous-Reliability Memory"** *Proceedings of the 44th Annual IEEE/IFIP International Conference on Dependable Systems and Networks (DSN)*, Atlanta, GA, June 2014. [Summary] [Slides (pptx) (pdf)] [Coverage on ZDNet]

Characterizing Application Memory Error Vulnerability to Optimize Datacenter Cost via Heterogeneous-Reliability Memory

Yixin Luo Sriram Govindan* Bikash Sharma* Mark Santaniello* Justin Meza
Aman Kansal* Jie Liu* Badriddine Khessib* Kushagra Vaid* Onur Mutlu
Carnegie Mellon University, yixinluo@cs.cmu.edu, {meza, onur}@cmu.edu
*Microsoft Corporation, {srgovin, bsharma, marksan, kansal, jie.liu, bkhessib, kvaid}@microsoft.com

Conclusion

Summary: Memory Reliability and Security

- Memory reliability is reducing
- Reliability issues open up security vulnerabilities
  - Very hard to defend against
- Rowhammer is an example
  - Its implications on system security research are tremendous & exciting

- **Good news: We have a lot more to do.**
- Understand: Solid methodologies for failure modeling and discovery
  - Modeling based on real device data – small scale and large scale
- Architect: Principled co-architecting of system and memory
  - Good partitioning of duties across the stack
- Design & Test: Principled electronic design, automation, testing
  - High coverage and good interaction with system reliability methods

Challenge and Opportunity for Future

Fundamentally

Secure, Reliable, Safe

Computing Architectures

One Important Takeaway

Main Memory Needs

Intelligent Controllers

RowHammer and Beyond

RowHammer and Other Issues We May Face as Memory Becomes Denser

Onur Mutlu
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https://people.inf.ethz.ch/omutlu
2 August 2018
MSR Faculty Summit

ETH zürich

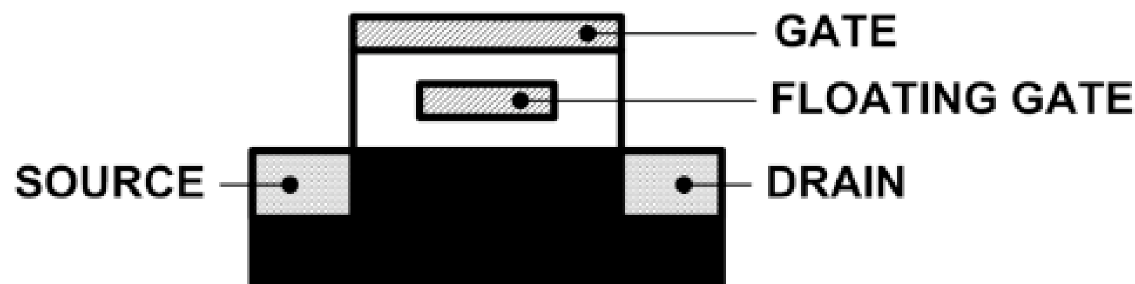
Carnegie Mellon

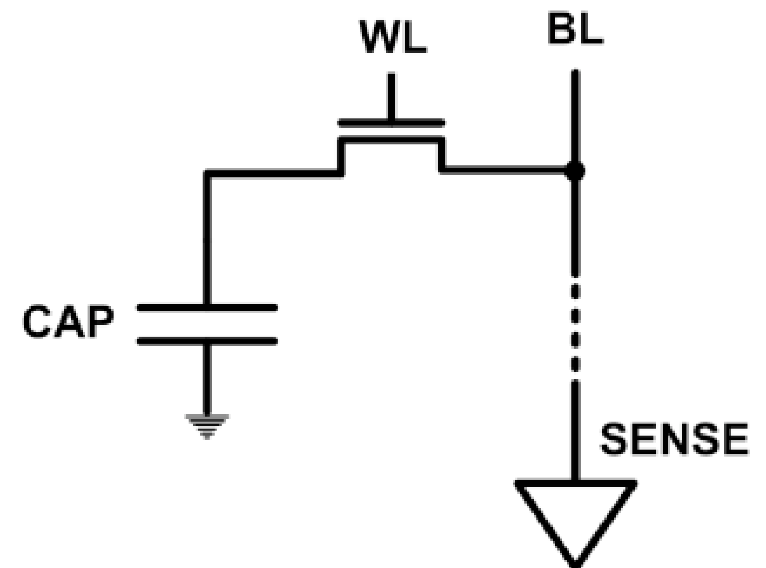
Backup Slides

Flash Memory Reliability and Security

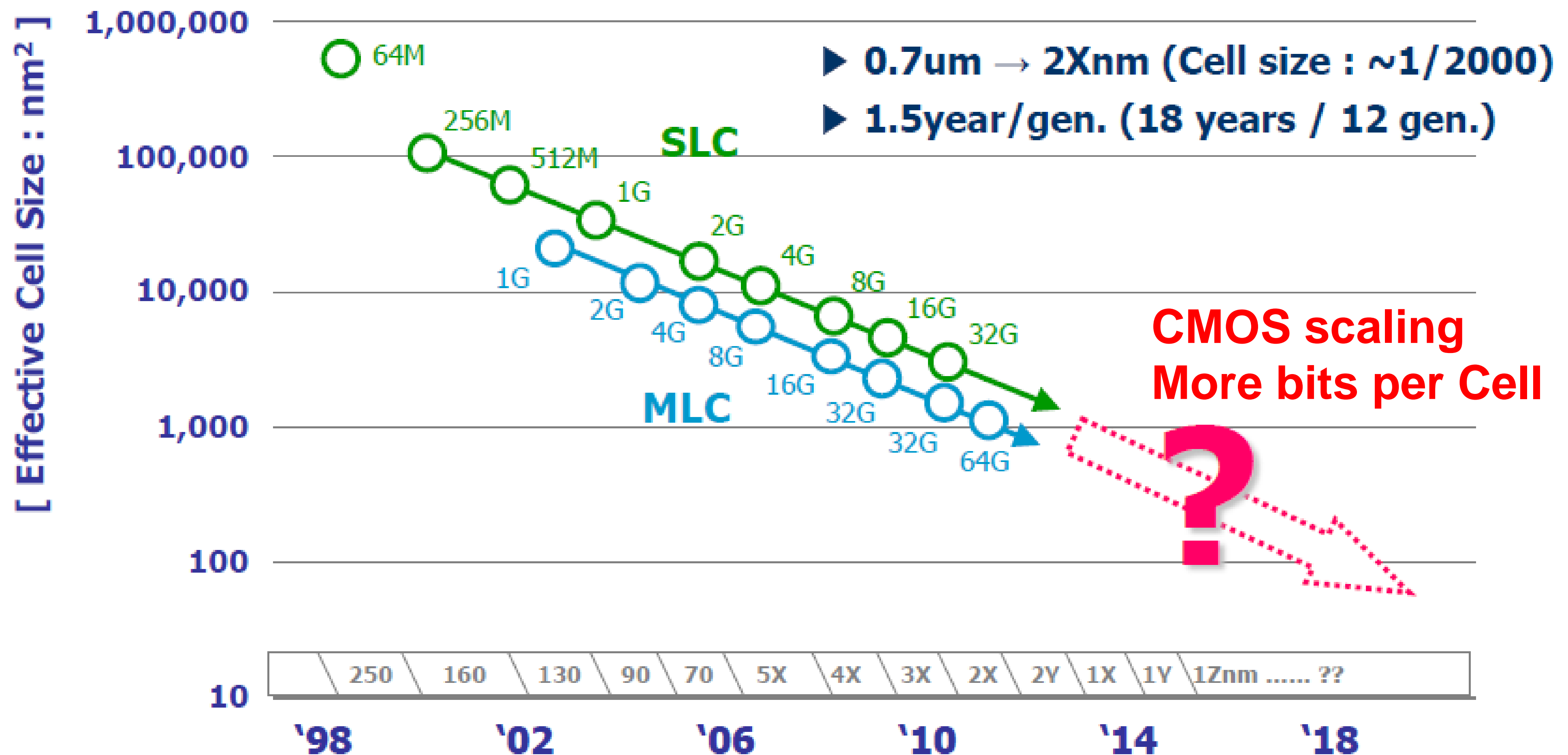
Limits of Charge Memory

- Difficult charge placement and control
  - Flash: floating gate charge
  - DRAM: capacitor charge, transistor leakage
- Reliable sensing becomes difficult as charge storage unit size reduces





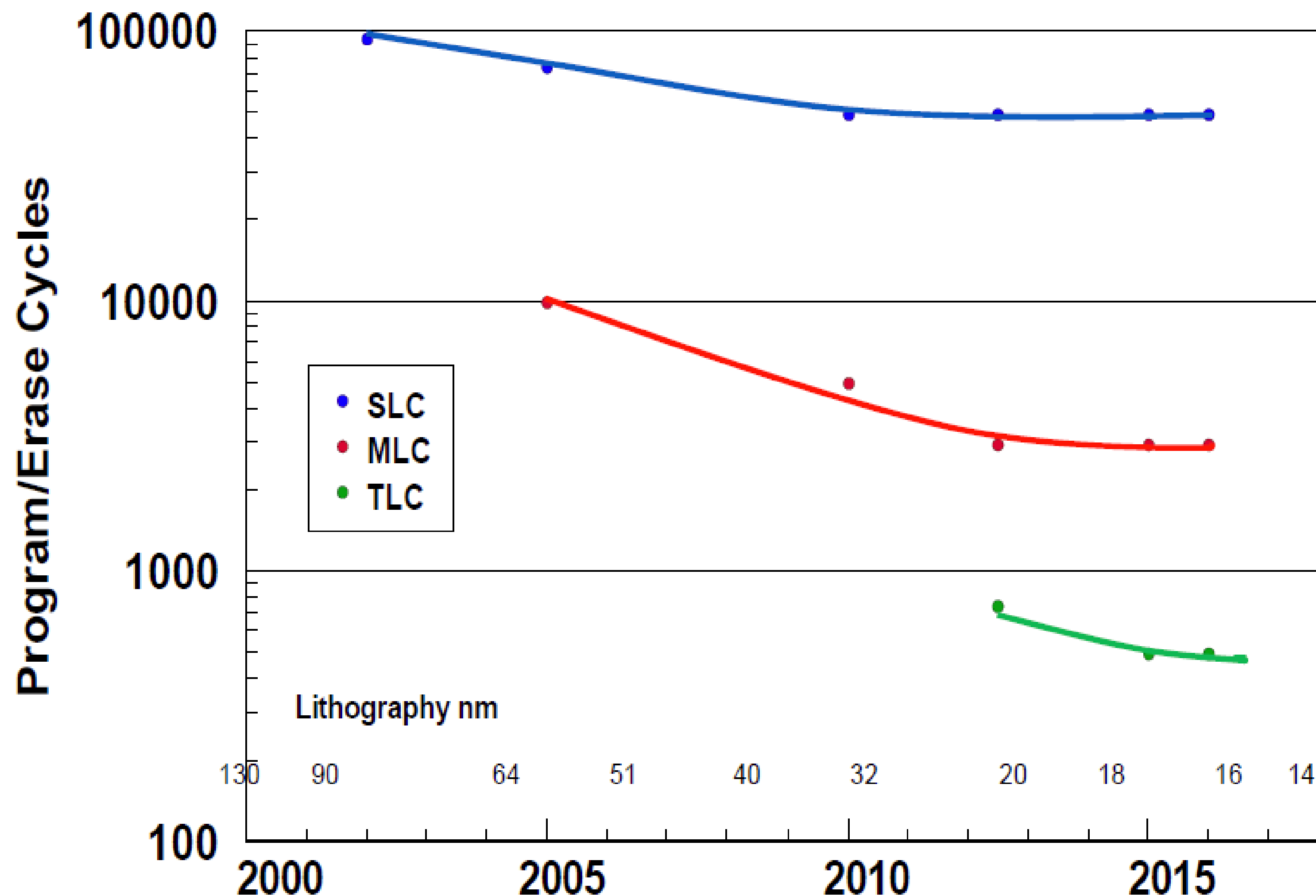
Evolution of NAND Flash Memory



Seaung Suk Lee, "Emerging Challenges in NAND Flash Technology", Flash Summit 2011 (Hynix)

- Flash memory is widening its range of applications
  - Portable consumer devices, laptop PCs and enterprise servers

Flash Challenges: Reliability and Endurance



E. Grochowski et al., "Future technology challenges for NAND flash and HDD products", Flash Memory Summit 2012

- **P/E cycles (provided)**

A few thousand

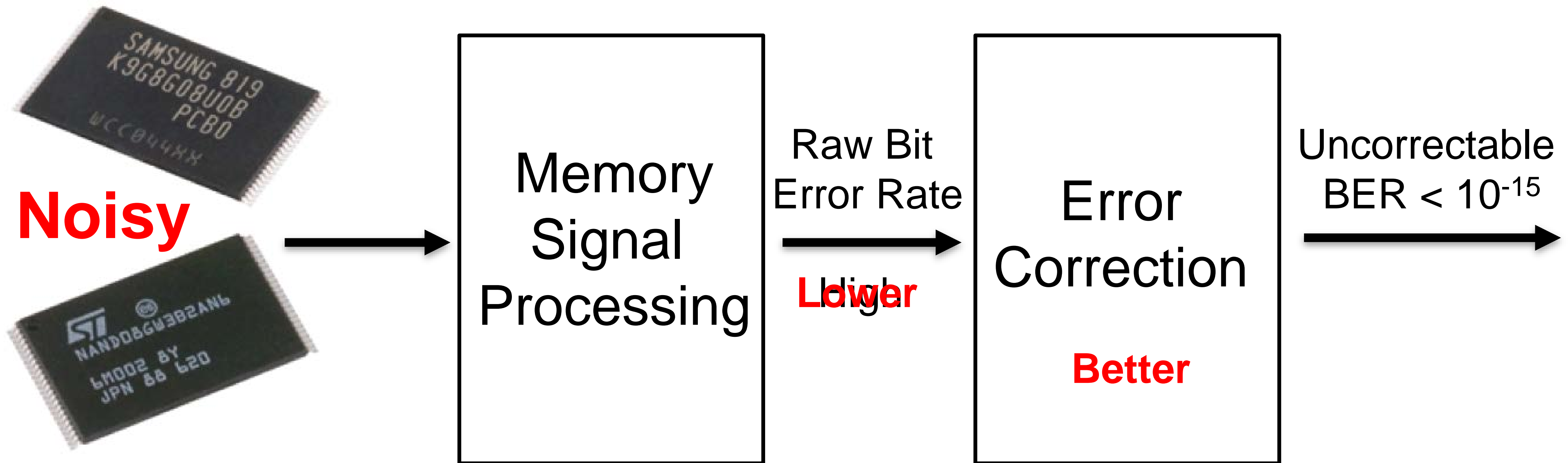
- **P/E cycles (required)**

Writing
the full capacity
of the drive
10 times per day
for 5 years
(STEC)

> 50k P/E cycles

NAND Flash Memory is Increasingly Noisy

Future NAND Flash-based Storage Architecture



Our Goals:

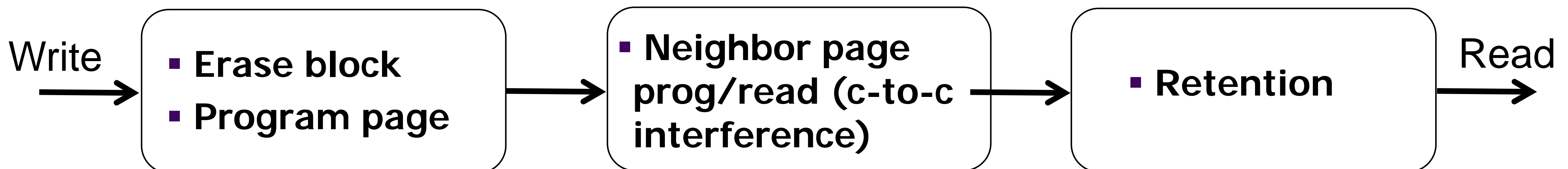
Build reliable error models for NAND flash memory

Design efficient reliability mechanisms based on the model

NAND Flash Error Model

Experimentally characterize and model dominant errors

Cai et al., "Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis"", **DATE 2012**
Luo et al., "Enabling Accurate and Practical Online Flash Channel Modeling for Modern MLC NAND Flash Memory", **JSAC 2016**



Cai et al., "Threshold voltage distribution in MLC NAND Flash Memory: Characterization, Analysis, and Modeling", **DATE 2013**

Cai et al., "Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques", **HPCA 2017**

Cai et al., "Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation", **ICCD 2013**

Cai et al., "Neighbor-Cell Assisted Error Correction in MLC NAND Flash Memories", **SIGMETRICS 2014**

Cai et al., "Read Disturb Errors in MLC NAND Flash Memory: Characterization and Mitigation", **DSN 2015**

Cai et al., "Flash Correct-and-Refresh: Retention-aware error management for increased flash memory lifetime", **ICCD 2012**

Cai et al., "Error Analysis and Retention-Aware Error Management for NAND Flash Memory", **ITJ 2013**

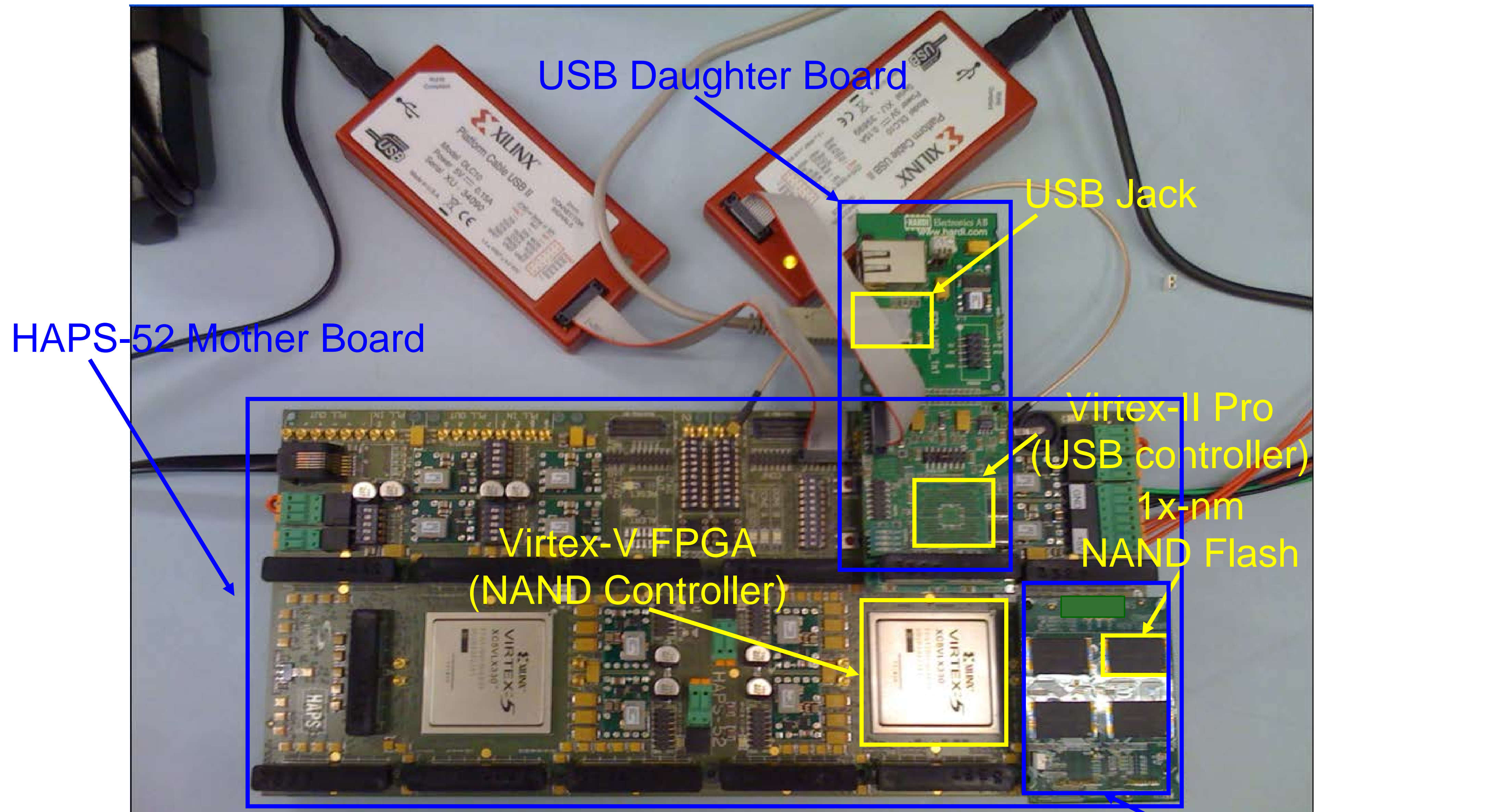
Cai et al., "Data Retention in MLC NAND Flash Memory: Characterization, Optimization and Recovery", **HPCA 2015**

Our Goals and Approach

- Goals:
  - Understand error mechanisms and develop reliable predictive models for MLC NAND flash memory errors
  - Develop efficient error management techniques to mitigate errors and improve flash reliability and endurance

- Approach:
  - Solid experimental analyses of errors in real MLC NAND flash memory → drive the understanding and models
  - Understanding, models, and creativity → drive the new techniques

Experimental Testing Platform



[DATE 2012, ICCD 2012, DATE 2013, ITJ 2013, ICCD 2013, SIGMETRICS 2014, HPCA 2015, DSN 2015, MSST 2015, JSAC 2016, HPCA 2017, DFRWS 2017, PIEEE 2017, HPCA 2018, SIGMETRICS 2018]

Cai+, "Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives," Proc. IEEE 2017.

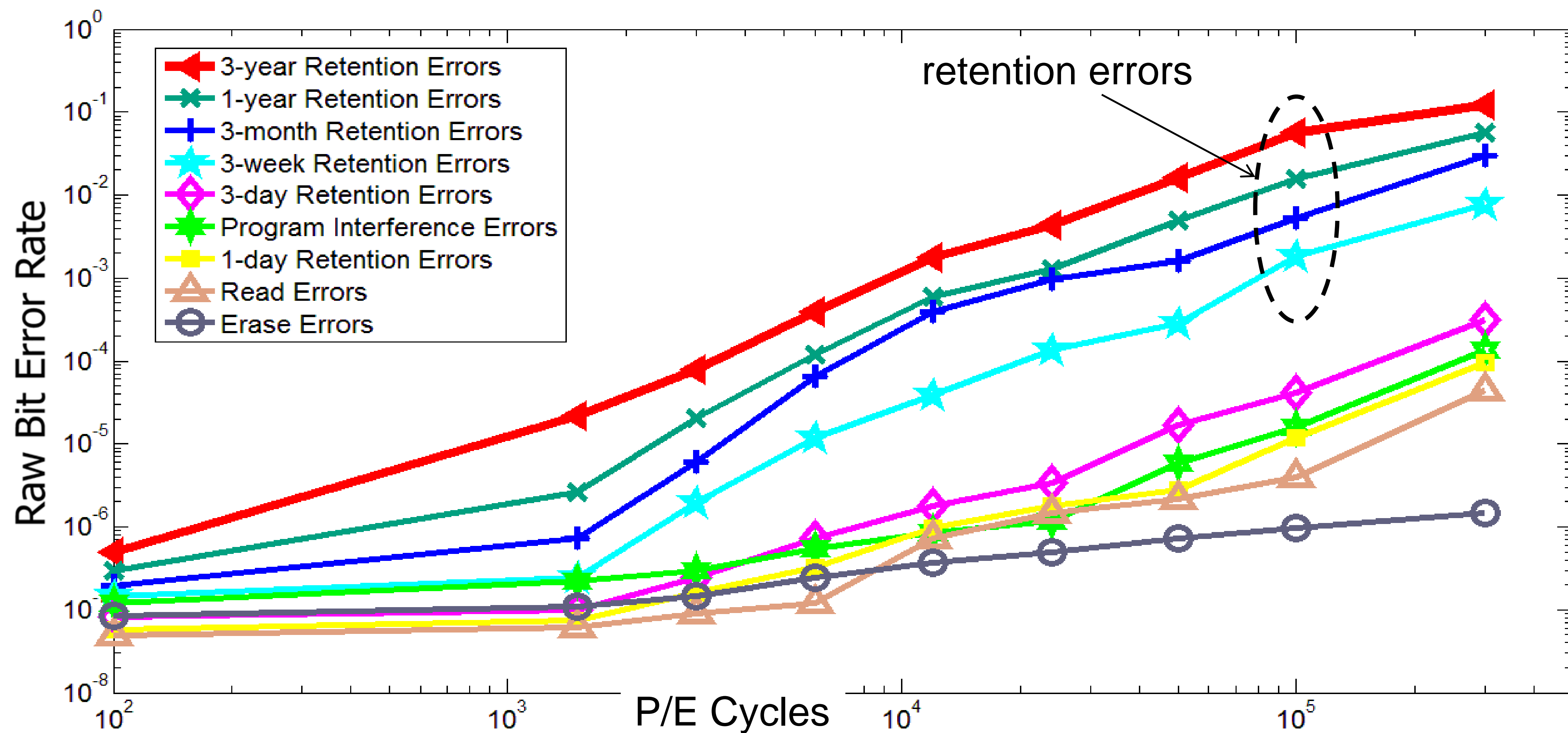
NAND Flash Error Types

- Four types of errors [Cai+, DATE 2012]

- Caused by common flash operations
  - Read errors
  - Erase errors
  - Program (interference) errors

- Caused by flash cell losing charge over time
  - Retention errors
    - Whether an error happens depends on required retention time
    - Especially problematic in MLC flash because threshold voltage window to determine stored value is smaller

Observations: Flash Error Analysis



- Raw bit error rate increases exponentially with P/E cycles
- Retention errors are dominant (>99% for 1-year ret. time)
- Retention errors increase with retention time requirement

Cai et al., Error Patterns in MLC NAND Flash Memory, DATE 2012.

More on Flash Error Analysis

- Yu Cai, Erich F. Haratsch, Onur Mutlu, and Ken Mai, **"Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis"** *Proceedings of the Design, Automation, and Test in Europe Conference* ***(DATE)***, Dresden, Germany, March 2012. Slides (ppt)

Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis

Yu Cai[1], Erich F. Haratsch[2], Onur Mutlu[1] and Ken Mai[1]
[1]Department of Electrical and Computer Engineering, Carnegie Mellon University, Pittsburgh, PA
[2]LSI Corporation, 1110 American Parkway NE, Allentown, PA
[1]{yucai, onur, kenmai}@andrew.cmu.edu, [2]erich.haratsch@lsi.com

Solution to Retention Errors

- Refresh periodically
- Change the period based on P/E cycle wearout
  - Refresh more often at higher P/E cycles
- Use a combination of in-place and remapping-based refresh
- Cai et al. "Flash Correct-and-Refresh: Retention-Aware Error Management for Increased Flash Memory Lifetime", ICCD 2012.

Flash Correct-and-Refresh [ICCD'12]

- Yu Cai, Gulay Yalcin, Onur Mutlu, Erich F. Haratsch, Adrian Cristal, Osman Unsal, and Ken Mai,
"Flash Correct-and-Refresh: Retention-Aware Error Management for Increased Flash Memory Lifetime"
Proceedings of the 30th IEEE International Conference on Computer Design ***(ICCD)***, Montreal, Quebec, Canada, September 2012. Slides (ppt)(pdf)

Flash Correct-and-Refresh: Retention-Aware Error Management for Increased Flash Memory Lifetime

Yu Cai[1], Gulay Yalcin[2], Onur Mutlu[1], Erich F. Haratsch[3], Adrian Cristal[2], Osman S. Unsal[2] and Ken Mai[1]
[1]DSSC, Department of Electrical and Computer Engineering, Carnegie Mellon University, Pittsburgh, PA
[2]Barcelona Supercomputing Center, C/Jordi Girona 29, Barcelona, Spain
[3]LSI Corporation, 1110 American Parkway NE, Allentown, PA

Many Errors and Their Mitigation [PIEEE'17]

Table 3 List of Different Types of Errors Mitigated by NAND Flash Error Mitigation Mechanisms

Mitigation Mechanism	Error Type				
	P/E Cycling [32,33,42] (§IV-A)	*Program* [40,42,53] (§IV-B)	*Cell-to-Cell Interference* [32,35,36,55] (§IV-C)	*Data Retention* [20,32,34,37,39] (§IV-D)	*Read Disturb* [20,32,38,62] (§IV-E)
Shadow Program Sequencing [35,40] (Section V-A)			X		
Neighbor-Cell Assisted Error Correction [36] (Section V-B)			X		
Refresh [34,39,67,68] (Section V-C)				X	X
Read-Retry [33,72,107] (Section V-D)	X			X	X
Voltage Optimization [37,38,74] (Section V-E)	X			X	X
Hot Data Management [41,63,70] (Section V-F)	X	X	X	X	X
Adaptive Error Mitigation [43,65,77,78,82] (Section V-G)	X	X	X	X	X

Cai+, "Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives," Proc. IEEE 2017.

Many Errors and Their Mitigation [PIEEE'17]

Proceedings of the IEEE, Sept. 2017

Error Characterization, Mitigation, and Recovery in Flash-Memory-Based Solid-State Drives

This paper reviews the most recent advances in solid-state drive (SSD) error characterization, mitigation, and data recovery techniques to improve both SSD's reliability and lifetime.

By Yu Cai, Saugata Ghose, Erich F. Haratsch, Yixin Luo, and Onur Mutlu

https://arxiv.org/pdf/1706.08642

One Issue: Read Disturb in Flash Memory

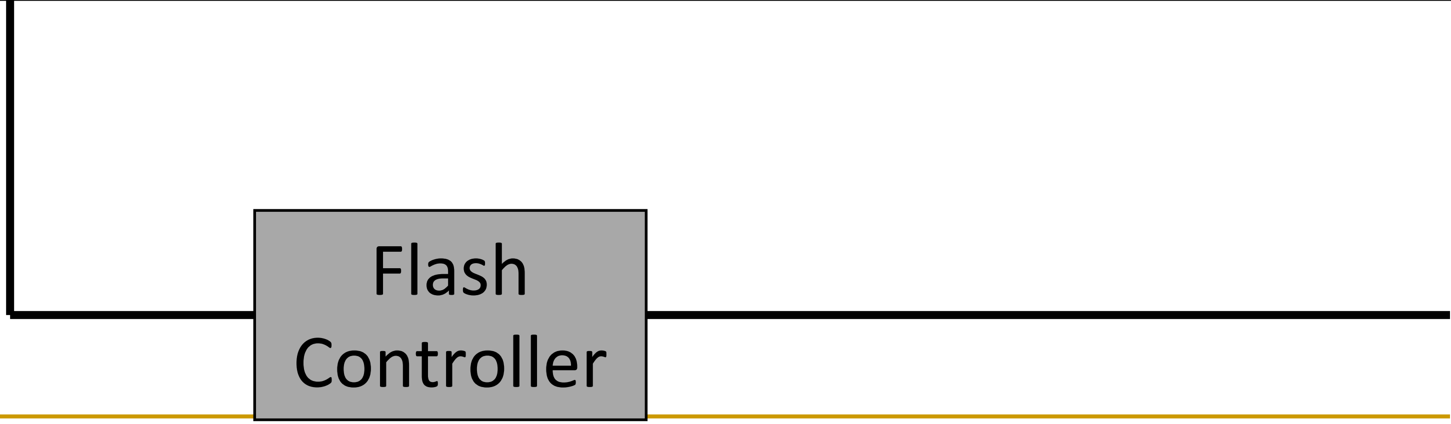
- All scaled memories are prone to read disturb errors

- DRAM
- SRAM
- Hard Disks: Adjacent Track Interference
- NAND Flash

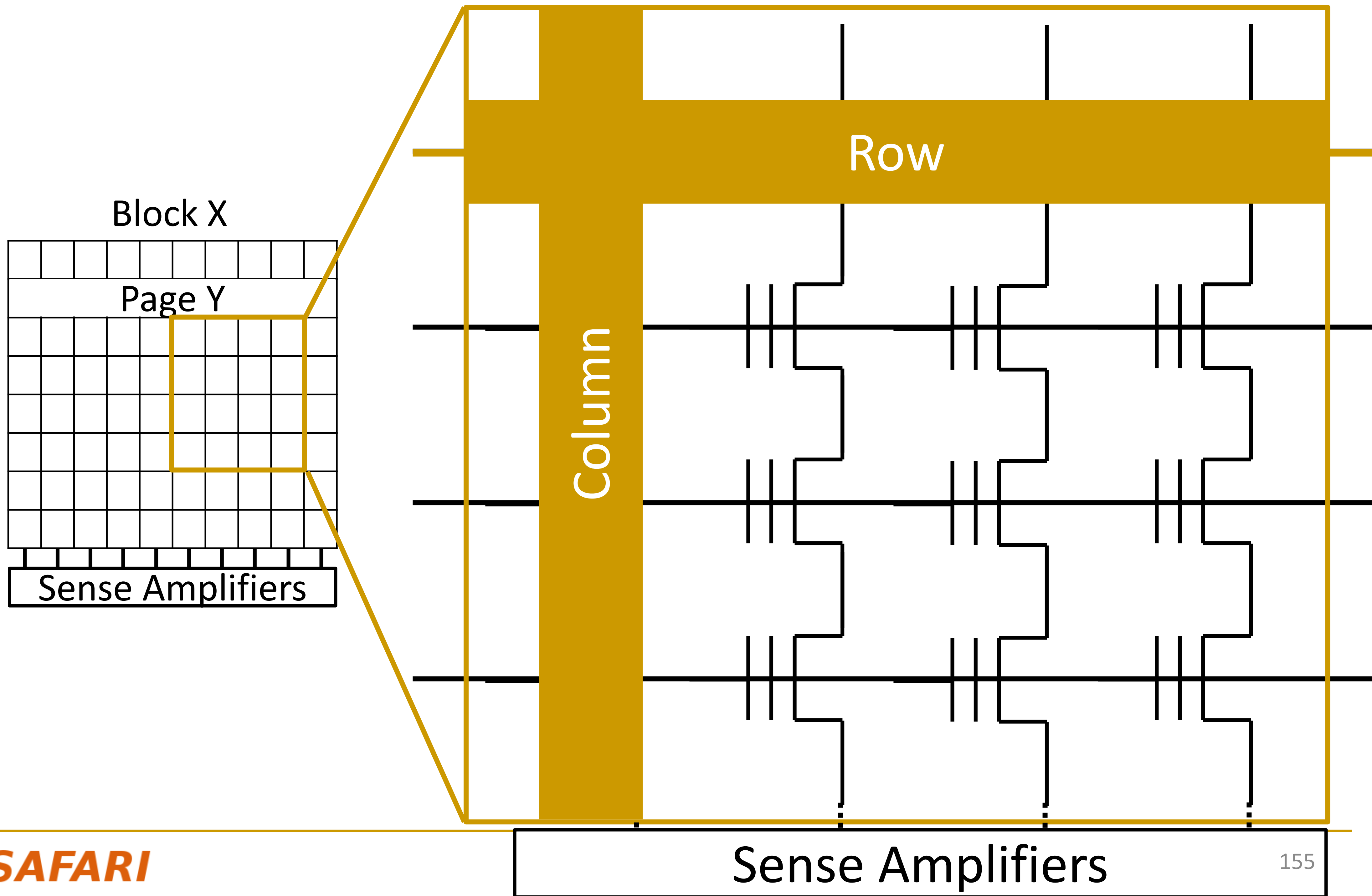
NAND Flash Memory Background

Flash Memory

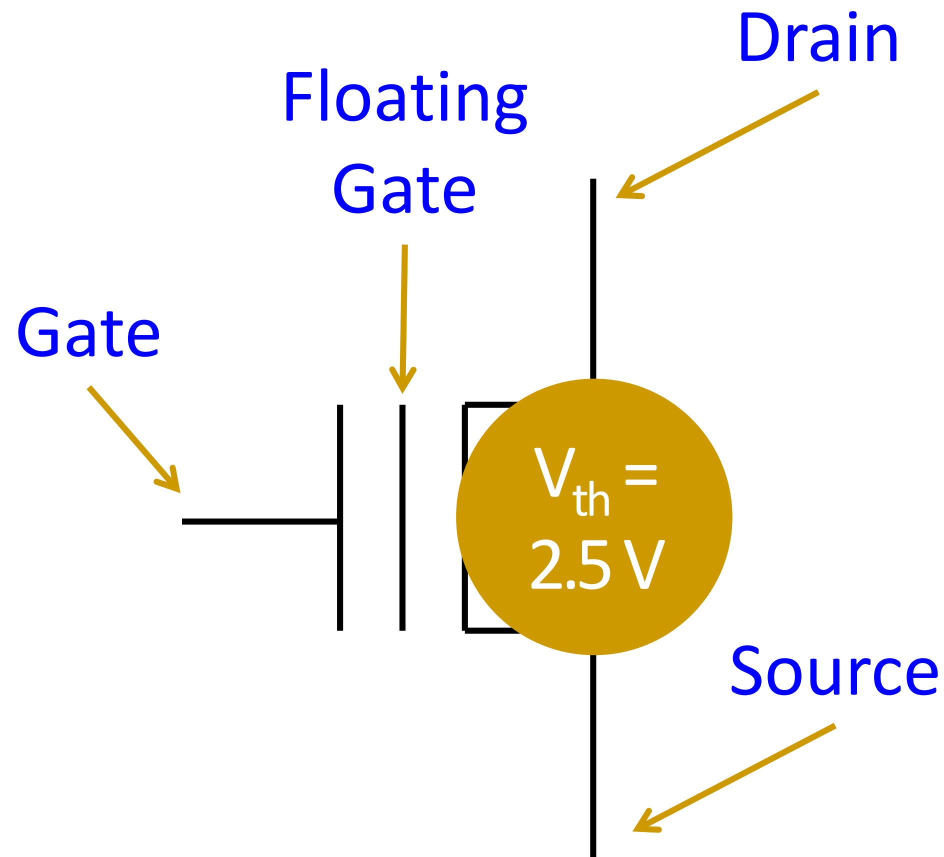
Block 0	Read	......	Block N
	Pass		
	Pass		
	…		
	Pass		



Flash Cell Array

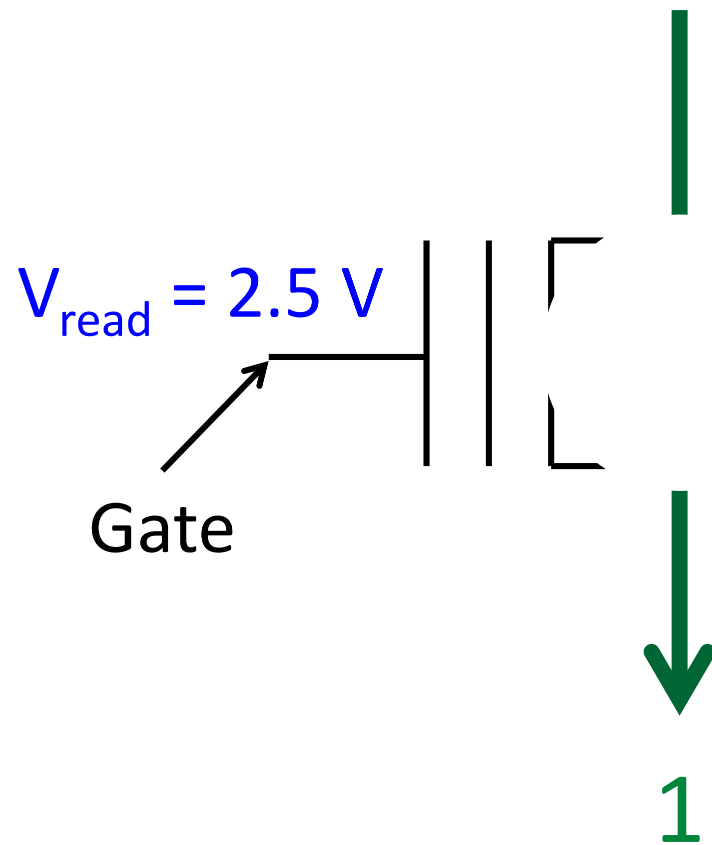


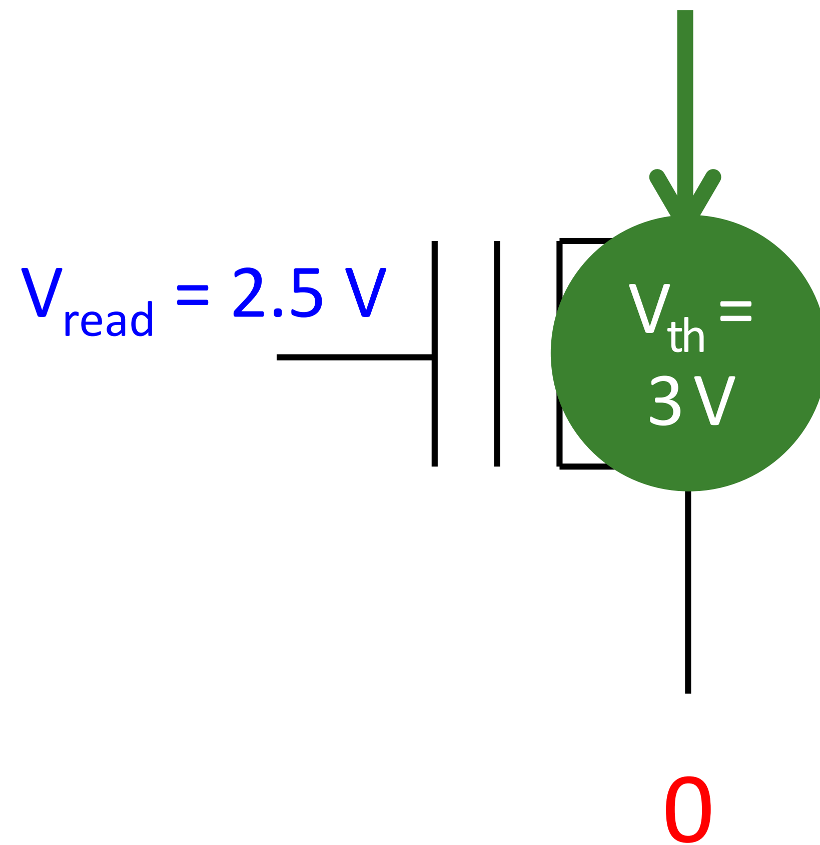
Flash Cell



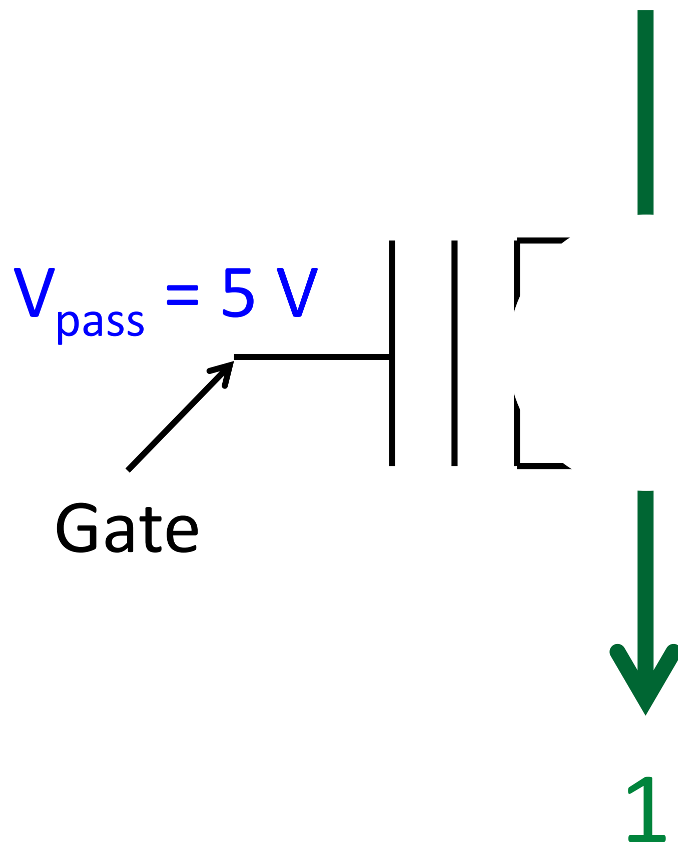
Floating Gate Transistor
(Flash Cell)

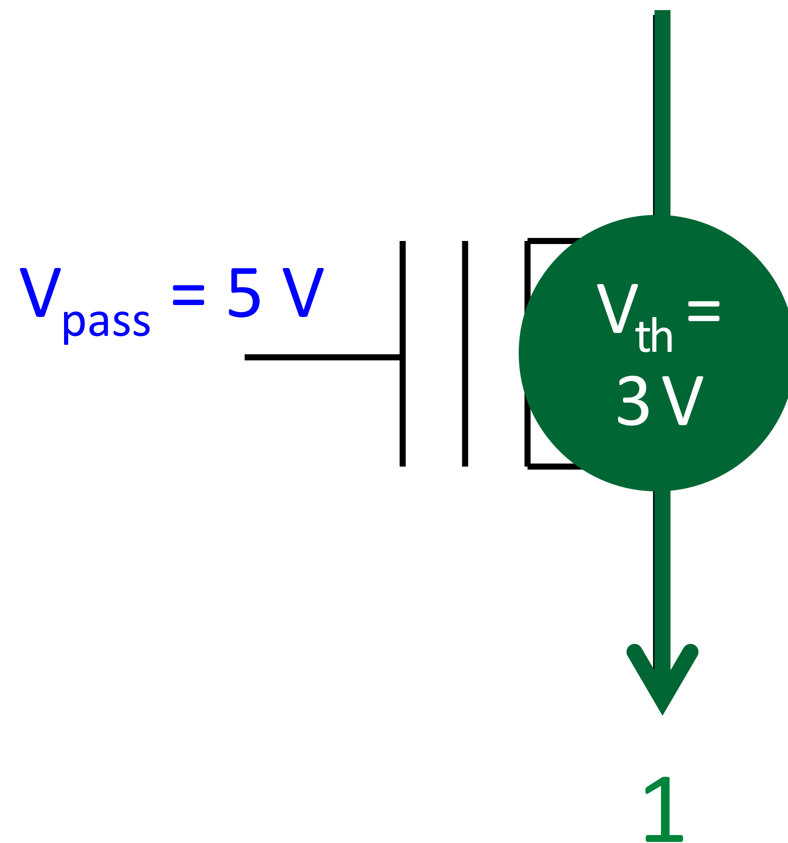
Flash Read



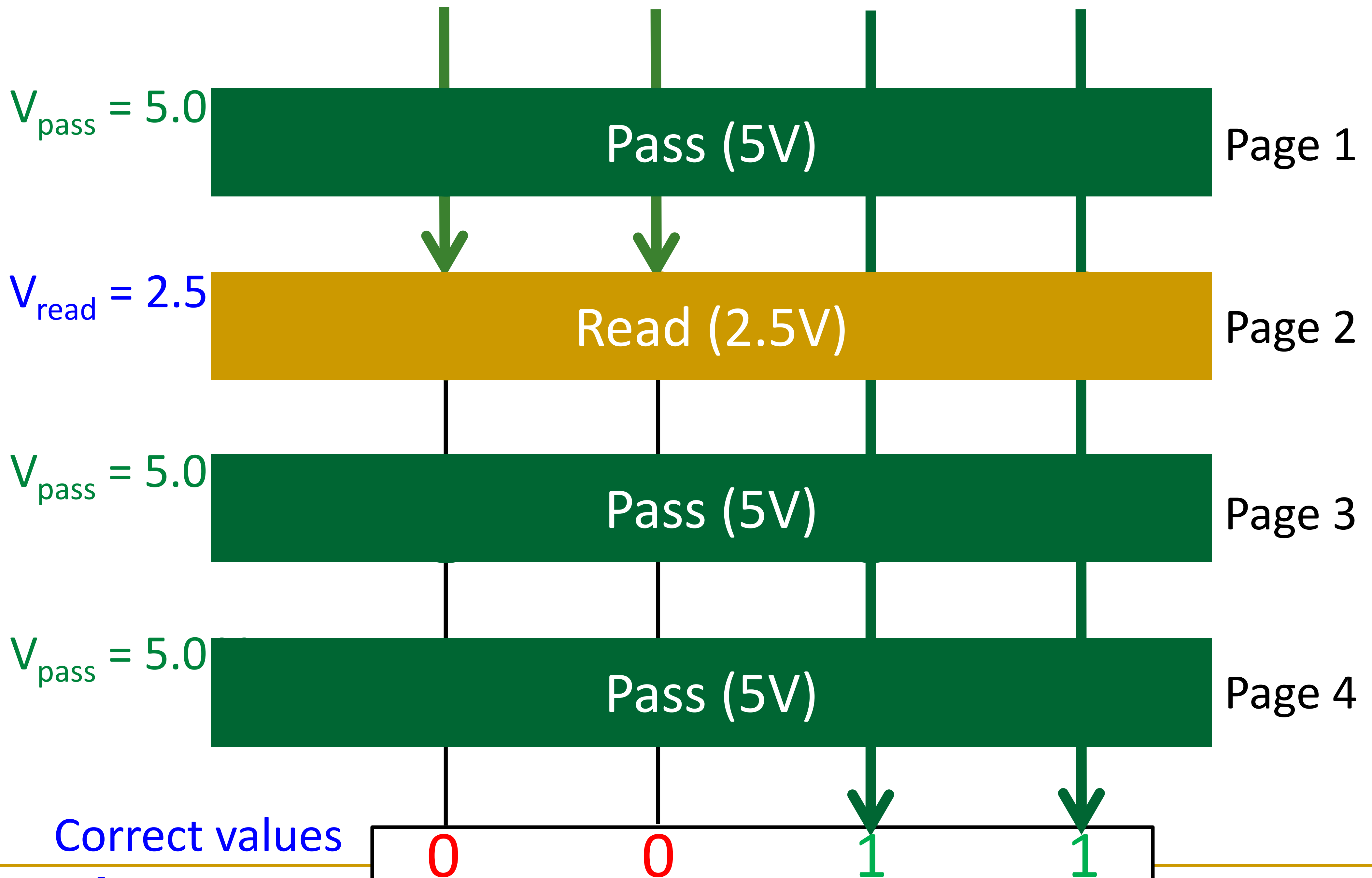


Flash Pass-Through

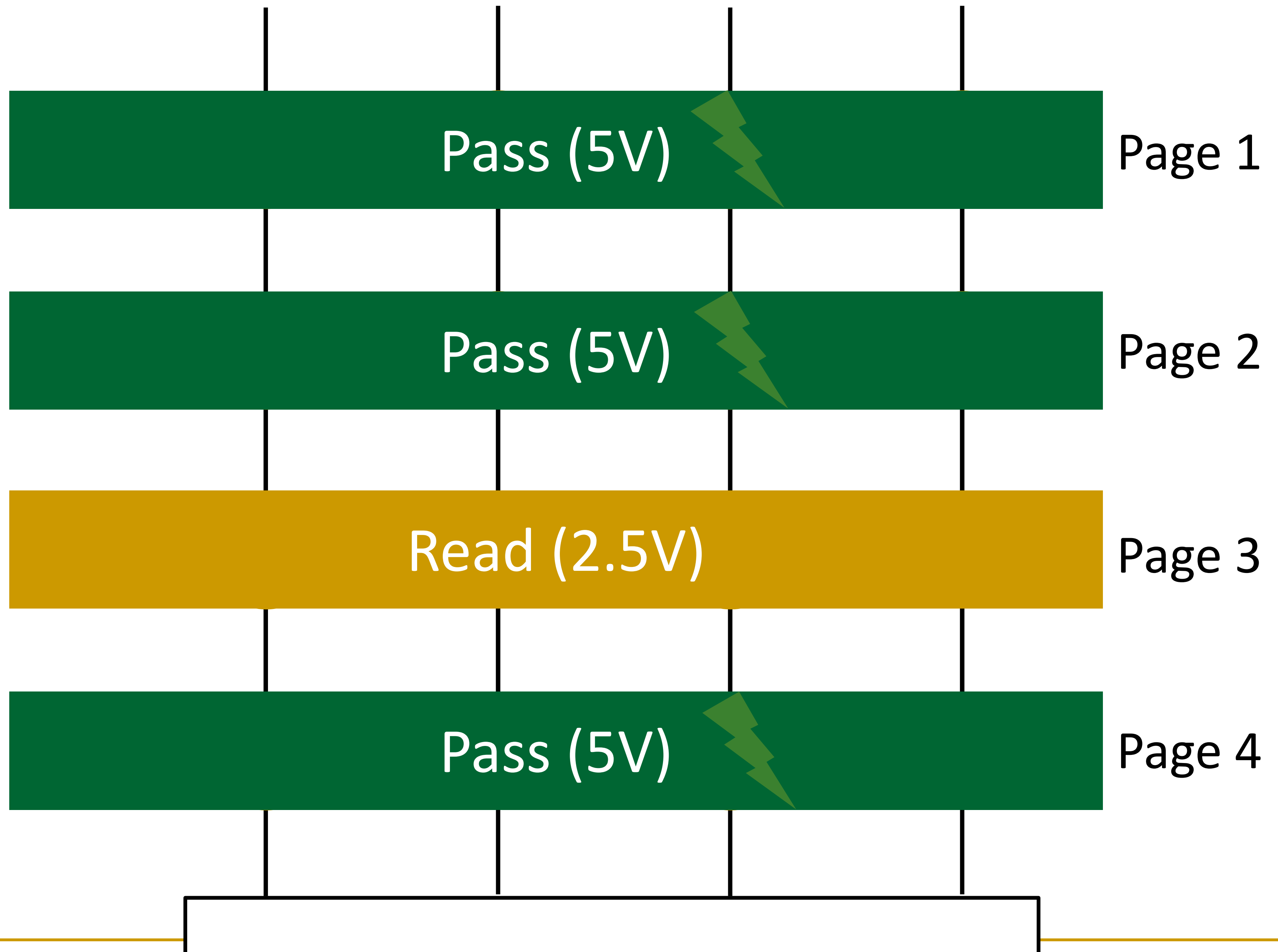




Read from Flash Cell Array

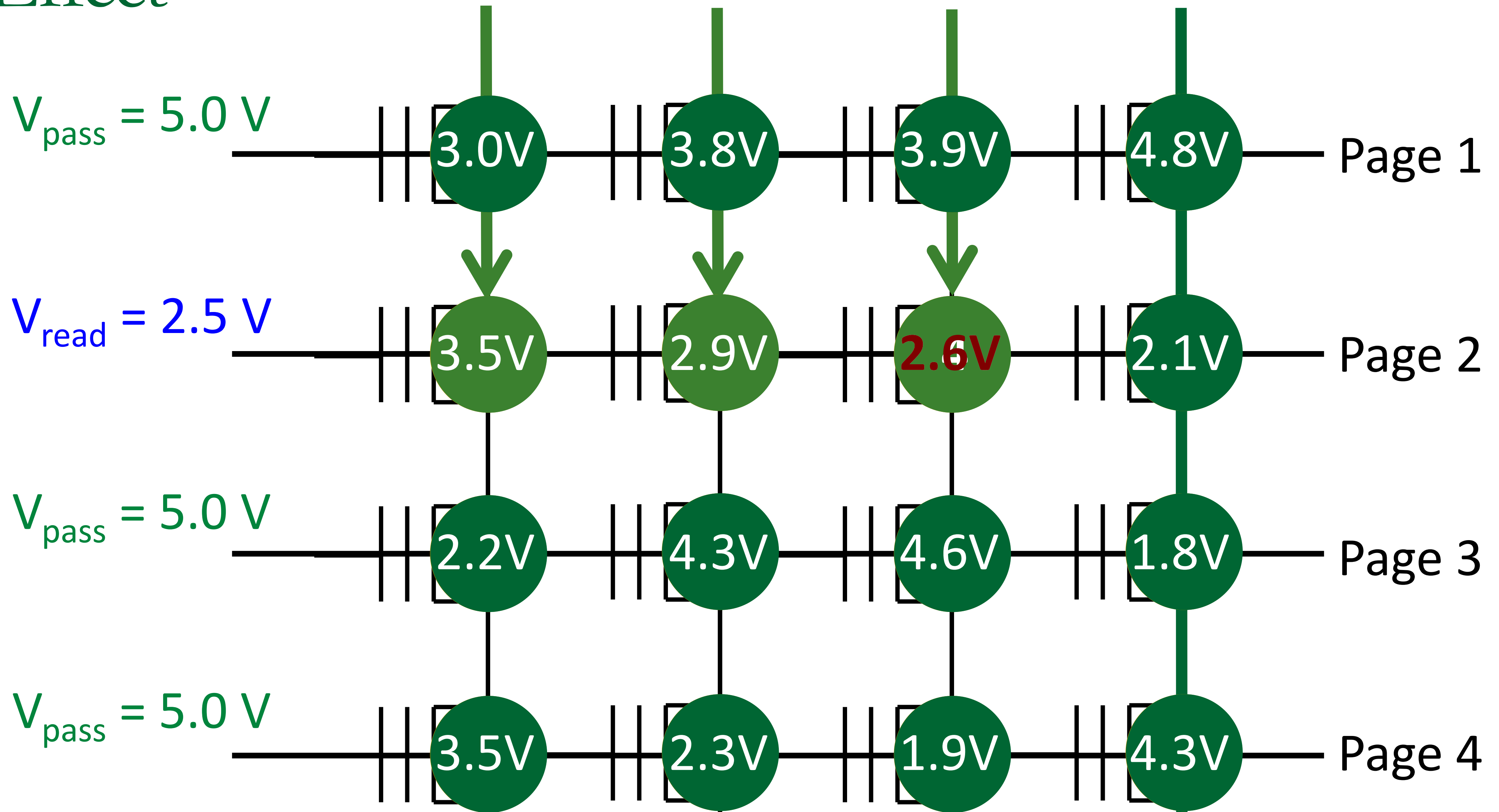


Read Disturb Problem: ‘Weak Programming’ Effect



Repeatedly read page 3 (or any page other than page 2)

Read Disturb Problem: "Weak Programming" Effect

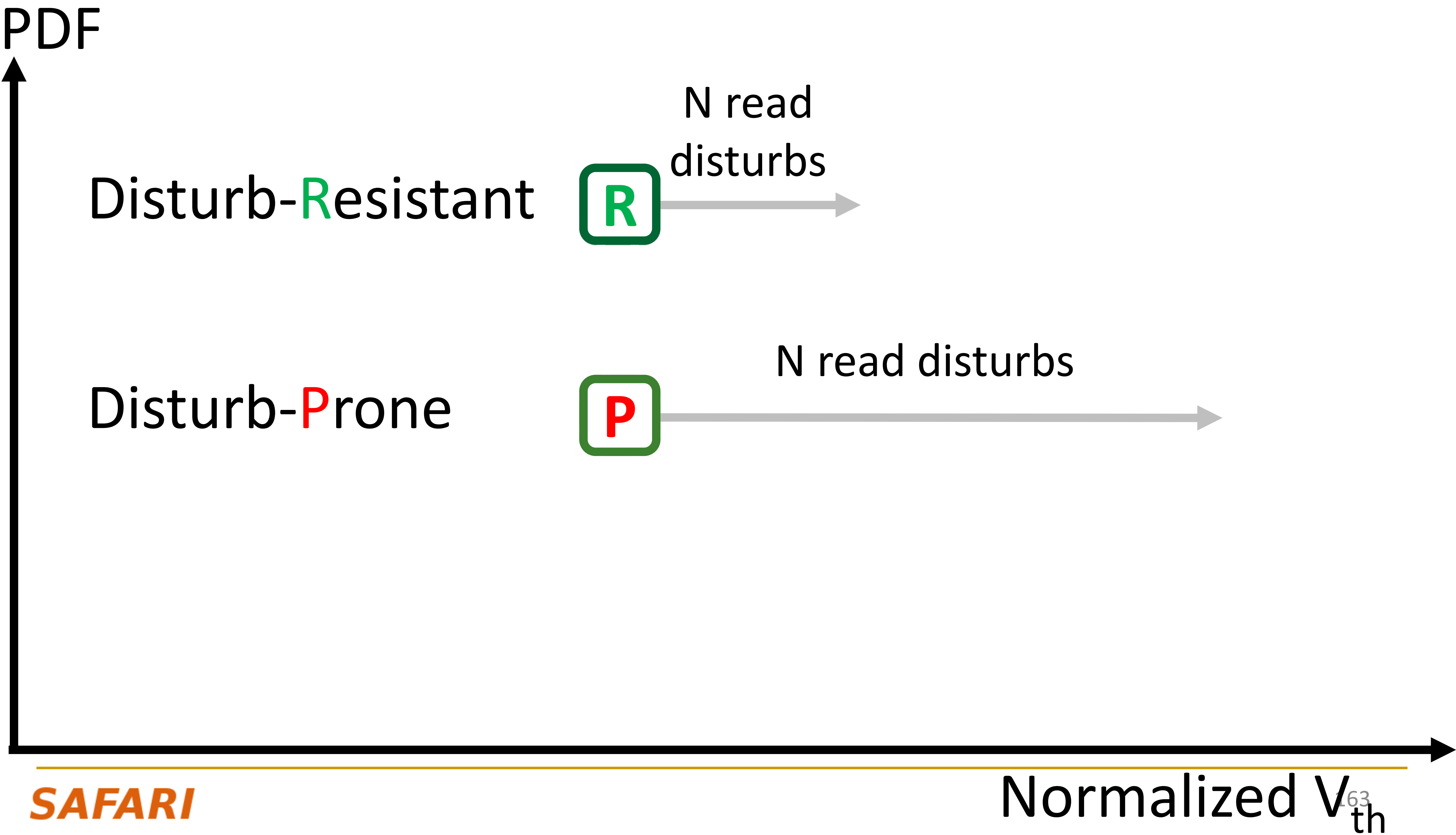


High pass-through voltage induces "weak-programming" effect

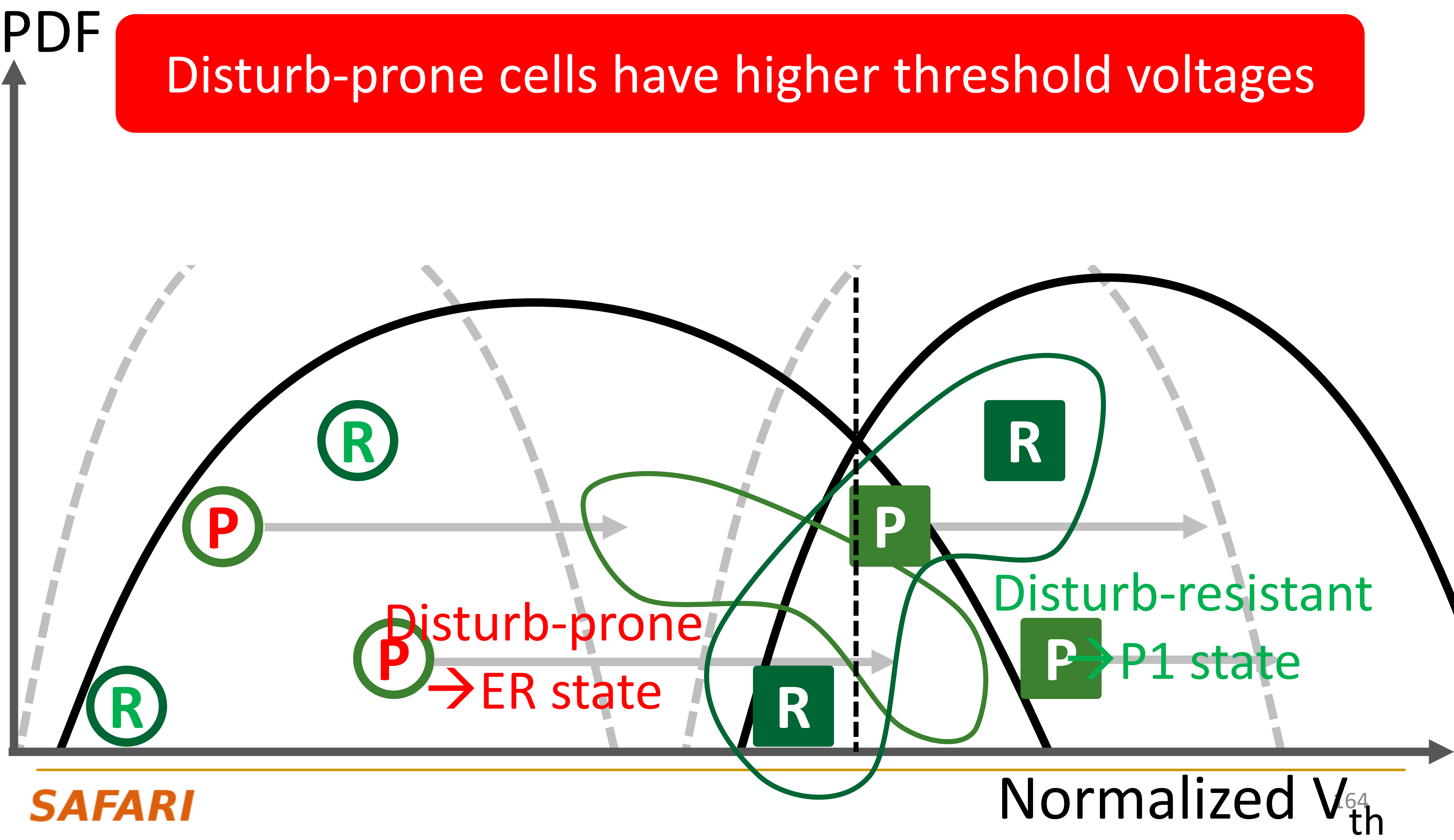
Executive Summary [DSN'15]

- ***Read disturb errors*** limit flash memory lifetime today
  - Apply a *high pass-through voltage (V_{pass})* to multiple pages on a read
  - Repeated application of V_{pass} can alter stored values in unread pages
- We **characterize read disturb** on real NAND flash chips
  - Slightly lowering V_{pass} greatly reduces read disturb errors
  - Some flash cells are more prone to read disturb
- **Technique 1:** Mitigate read disturb errors online
  - ***V_{pass} Tuning*** dynamically finds and applies a lowered V_{pass} per block
  - Flash memory lifetime improves by 21%
- **Technique 2:** Recover after failure to prevent data loss
  - ***Read Disturb Oriented Error Recovery*** (RDR) selectively corrects cells more susceptible to read disturb errors
  - Reduces raw bit error rate (RBER) by up to 36%

Read Disturb Prone vs. Resistant Cells



Observation 2: Some Flash Cells Are More Prone to Read Disturb



Read Disturb Oriented Error Recovery (RDR)

- Triggered by an uncorrectable flash error
  - Back up all valid data in the faulty block
  - Disturb the faulty page 100K times (more)
  - Compare V_{th}'s before and after read disturb
  - Select cells susceptible to flash errors ($V_{ref}-\sigma<V_{th}<V_{ref}-\sigma$)
  - Predict among these susceptible cells
    - Cells with more V_{th} shifts are disturb-prone → Higher V_{th} state
    - Cells with less V_{th} shifts are disturb-resistant → Lower V_{th} state

Reduces total error count by up to 36% @ 1M read disturbs
ECC can be used to correct the remaining errors

More on Flash Read Disturb Errors [DSN'15]

- Yu Cai, Yixin Luo, Saugata Ghose, Erich F. Haratsch, Ken Mai, and Onur Mutlu,
"Read Disturb Errors in MLC NAND Flash Memory: Characterization and Mitigation"
Proceedings of the 45th Annual IEEE/IFIP International Conference on Dependable Systems and Networks ***(DSN)***, Rio de Janeiro, Brazil, June 2015.

Read Disturb Errors in MLC NAND Flash Memory: Characterization, Mitigation, and Recovery

Yu Cai, Yixin Luo, Saugata Ghose, Erich F. Haratsch*, Ken Mai, Onur Mutlu
Carnegie Mellon University, *Seagate Technology
yucaicai@gmail.com, {yixinluo, ghose, kenmai, onur}@cmu.edu

Large-Scale SSD Error Analysis [SIGMETRICS'15]

- First large-scale field study of flash memory errors

- Justin Meza, Qiang Wu, Sanjeev Kumar, and Onur Mutlu,
"A Large-Scale Study of Flash Memory Errors in the Field"
Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems ***(SIGMETRICS)***, Portland, OR, June 2015.
[Slides (pptx) (pdf)] [Coverage at ZDNet] [Coverage on The Register] [Coverage on TechSpot] [Coverage on The Tech Report]

A Large-Scale Study of Flash Memory Failures in the Field

Justin Meza	Qiang Wu	Sanjeev Kumar	Onur Mutlu
Carnegie Mellon University	Facebook, Inc.	Facebook, Inc.	Carnegie Mellon University
meza@cmu.edu	qwu@fb.com	skumar@fb.com	onur@cmu.edu

Another Lecture: NAND Flash Reliability

- Yu Cai, Saugata Ghose, Erich F. Haratsch, Yixin Luo, and Onur Mutlu, **"Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives"** *Proceedings of the IEEE*, September 2017.

Cai+, "Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis," DATE 2012.

Cai+, "Flash Correct-and-Refresh: Retention-Aware Error Management for Increased Flash Memory Lifetime," ICCD 2012.

Cai+, "Threshold Voltage Distribution in MLC NAND Flash Memory: Characterization, Analysis and Modeling," DATE 2013.

Cai+, "Error Analysis and Retention-Aware Error Management for NAND Flash Memory," Intel Technology Journal 2013.

Cai+, "Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation," ICCD 2013.

Cai+, "Neighbor-Cell Assisted Error Correction for MLC NAND Flash Memories," SIGMETRICS 2014.

Cai+,"Data Retention in MLC NAND Flash Memory: Characterization, Optimization and Recovery," HPCA 2015.

Cai+, "Read Disturb Errors in MLC NAND Flash Memory: Characterization and Mitigation," DSN 2015.

Luo+, "WARM: Improving NAND Flash Memory Lifetime with Write-hotness Aware Retention Management," MSST 2015.

Meza+, "A Large-Scale Study of Flash Memory Errors in the Field," SIGMETRICS 2015.

Luo+, "Enabling Accurate and Practical Online Flash Channel Modeling for Modern MLC NAND Flash Memory," IEEE JSAC 2016.

Cai+, "Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques," HPCA 2017.

Fukami+, "Improving the Reliability of Chip-Off Forensic Analysis of NAND Flash Memory Devices," DFRWS EU 2017.

Luo+, "HeatWatch: Improving 3D NAND Flash Memory Device Reliability by Exploiting Self-Recovery and Temperature-Awareness," HPCA 2018.

Luo+, "Improving 3D NAND Flash Memory Lifetime by Tolerating Early Retention Loss and Process Variation," SIGMETRICS 2018.

Cai+, "Error Characterization, Mitigation, and Recovery in Flash Memory Based Solid State Drives," Proc. IEEE 2017.

NAND Flash Vulnerabilities **[HPCA'17]**

HPCA, Feb. 2017

Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques

Yu Cai† Saugata Ghose† Yixin Luo‡† Ken Mai† Onur Mutlu§† Erich F. Haratsch‡
†*Carnegie Mellon University* ‡*Seagate Technology* §*ETH Zürich*

Modern NAND flash memory chips provide high density by storing two bits of data in each flash cell, called a multi-level cell *(MLC). An MLC partitions the threshold voltage range of a flash cell into four* voltage states. *When a flash cell is programmed, a high voltage is applied to the cell. Due to parasitic capacitance coupling between flash cells that are physically close to each other, flash cell programming can lead to* cell-to-cell program interference, *which introduces errors into* neighboring *flash cells. In order to reduce the impact of cell-to-cell interference on the reliability of MLC NAND flash memory, flash manufacturers adopt a* two-step programming method, *which programs the MLC in two separate steps. First, the flash memory partially programs the least significant bit of the MLC to some intermediate threshold voltage. Second, it programs the most significant bit to bring the MLC up to its full voltage state.*

In this paper, we demonstrate that two-step programming exposes new reliability and security vulnerabilities. We expe-

belongs to a different flash memory *page* (the unit of data programmed and read at the same time), which we refer to, respectively, as the least significant bit (LSB) page and the most significant bit (MSB) page [5].

A flash cell is programmed by applying a large voltage on the control gate of the transistor, which triggers charge transfer into the floating gate, thereby increasing the threshold voltage. To precisely control the threshold voltage of the cell, the flash memory uses *incremental step pulse programming* (ISPP) [12, 21, 25, 41]. ISPP applies multiple short pulses of the programming voltage to the control gate, in order to increase the cell threshold voltage by some small voltage amount (V_{step}) after each step. Initial MLC designs programmed the threshold voltage in *one shot*, issuing all of the pulses back-to-back to program *both* bits of data at the same time. However, as flash memory scales down, the distance between neighboring flash cells decreases, which

https://people.inf.ethz.ch/omutlu/pub/flash-memory-programming-vulnerabilities_hpca17.pdf

NAND Flash Errors: A Modern Survey

Proceedings of the IEEE, Sept. 2017

Error Characterization, Mitigation, and Recovery in Flash-Memory-Based Solid-State Drives

This paper reviews the most recent advances in solid-state drive (SSD) error characterization, mitigation, and data recovery techniques to improve both SSD's reliability and lifetime.

By Yu Cai, Saugata Ghose, Erich F. Haratsch, Yixin Luo, and Onur Mutlu

https://arxiv.org/pdf/1706.08642

Summary: Memory Reliability and Security

- Memory reliability is reducing
- Reliability issues open up security vulnerabilities
  - Very hard to defend against
- Rowhammer is an example
  - Its implications on system security research are tremendous & exciting

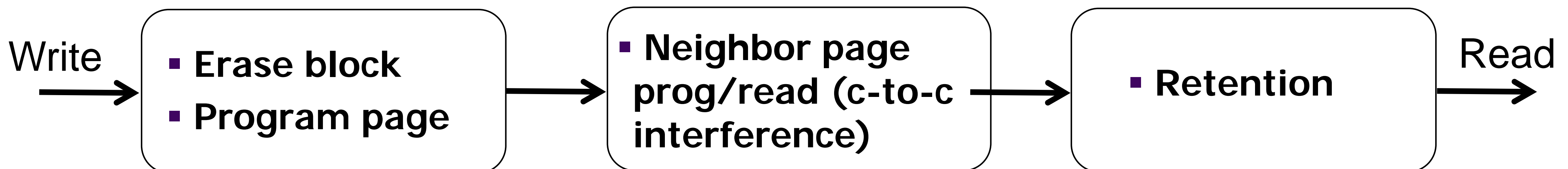
- **Good news: We have a lot more to do.**
- Understand: Solid methodologies for failure modeling and discovery
  - Modeling based on real device data – small scale and large scale
- Architect: Principled co-architecting of system and memory
  - Good partitioning of duties across the stack
- Design & Test: Principled electronic design, automation, testing
  - High coverage and good interaction with system reliability methods

Other Works on Flash Memory

NAND Flash Error Model

Experimentally characterize and model dominant errors

Cai et al., "Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis"", **DATE 2012**
Luo et al., "Enabling Accurate and Practical Online Flash Channel Modeling for Modern MLC NAND Flash Memory", **JSAC 2016**



Cai et al., "Threshold voltage distribution in MLC NAND Flash Memory: Characterization, Analysis, and Modeling", **DATE 2013**

Cai et al., "Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques", **HPCA 2017**

Cai et al., "Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation", **ICCD 2013**

Cai et al., "Neighbor-Cell Assisted Error Correction in MLC NAND Flash Memories", **SIGMETRICS 2014**

Cai et al., "Read Disturb Errors in MLC NAND Flash Memory: Characterization and Mitigation", **DSN 2015**

Cai et al., "Flash Correct-and-Refresh: Retention-aware error management for increased flash memory lifetime", **ICCD 2012**

Cai et al., "Error Analysis and Retention-Aware Error Management for NAND Flash Memory, **ITJ 2013**

Cai et al., "Data Retention in MLC NAND Flash Memory: Characterization, Optimization and Recovery" , **HPCA 2015**

Threshold Voltage Distribution

- Yu Cai, Erich F. Haratsch, Onur Mutlu, and Ken Mai, **"Threshold Voltage Distribution in MLC NAND Flash Memory: Characterization, Analysis and Modeling"** *Proceedings of the Design, Automation, and Test in Europe Conference* ***(DATE)***, Grenoble, France, March 2013. Slides (ppt)

Threshold Voltage Distribution in MLC NAND Flash Memory: Characterization, Analysis, and Modeling

Yu Cai[1], Erich F. Haratsch[2], Onur Mutlu[1] and Ken Mai[1]
[1]DSSC, Department of Electrical and Computer Engineering, Carnegie Mellon University, Pittsburgh, PA
[2]LSI Corporation, 1110 American Parkway NE, Allentown, PA
[1]{yucai, onur, kenmai}@andrew.cmu.edu, [2]erich.haratsch@lsi.com

Program Interference and Vref Prediction

- Yu Cai, Onur Mutlu, Erich F. Haratsch, and Ken Mai, **"Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation"** *Proceedings of the 31st IEEE International Conference on Computer Design* ***(ICCD)***, Asheville, NC, October 2013. Slides (pptx) (pdf) Lightning Session Slides (pdf)

Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation

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2. LSI Corporation, San Jose, CA
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Neighbor-Assisted Error Correction

- Yu Cai, Gulay Yalcin, Onur Mutlu, Eric Haratsch, Osman Unsal, Adrian Cristal, and Ken Mai, **"Neighbor-Cell Assisted Error Correction for MLC NAND Flash Memories"** *Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems (**SIGMETRICS**)*, Austin, TX, June 2014. Slides (ppt) (pdf)

Neighbor-Cell Assisted Error Correction for MLC NAND Flash Memories

Yu Cai[1], Gulay Yalcin[2], Onur Mutlu[1], Erich F. Haratsch[4],
Osman Unsal[2], Adrian Cristal[2,3], and Ken Mai[1]
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Data Retention

- Yu Cai, Yixin Luo, Erich F. Haratsch, Ken Mai, and Onur Mutlu, **"Data Retention in MLC NAND Flash Memory: Characterization, Optimization and Recovery"** *Proceedings of the 21st International Symposium on High-Performance Computer Architecture* ***(HPCA)***, Bay Area, CA, February 2015. [Slides (pptx) (pdf)]

Data Retention in MLC NAND Flash Memory: Characterization, Optimization, and Recovery

Yu Cai, Yixin Luo, Erich F. Haratsch*, Ken Mai, Onur Mutlu
Carnegie Mellon University, *LSI Corporation
yucaicai@gmail.com, yixinluo@cs.cmu.edu, erich.haratsch@lsi.com, {kenmai, omutlu}@ece.cmu.edu

SSD Error Analysis in the Field

- First large-scale field study of flash memory errors
- Justin Meza, Qiang Wu, Sanjeev Kumar, and Onur Mutlu,
  "A Large-Scale Study of Flash Memory Errors in the Field"
  Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems ***(SIGMETRICS)***, Portland, OR, June 2015.
  [Slides (pptx) (pdf)] [Coverage at ZDNet] [Coverage on The Register] [Coverage on TechSpot] [Coverage on The Tech Report]

A Large-Scale Study of Flash Memory Failures in the Field

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Flash Memory Programming Vulnerabilities

- Yu Cai, Saugata Ghose, Yixin Luo, Ken Mai, Onur Mutlu, and Erich F. Haratsch,
"Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques"
Proceedings of the 23rd International Symposium on High-Performance Computer Architecture ***(HPCA)*** *Industrial Session*, Austin, TX, USA, February 2017.
[Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)]

Vulnerabilities in MLC NAND Flash Memory Programming: Experimental Analysis, Exploits, and Mitigation Techniques

Yu Cai[†] Saugata Ghose[†] Yixin Luo[‡†] Ken Mai[†] Onur Mutlu[§†] Erich F. Haratsch[‡]
[†]*Carnegie Mellon University* [‡]*Seagate Technology* [§]*ETH Zürich*

Accurate and Online Channel Modeling

- Yixin Luo, Saugata Ghose, Yu Cai, Erich F. Haratsch, and Onur Mutlu, **"Enabling Accurate and Practical Online Flash Channel Modeling for Modern MLC NAND Flash Memory"** *to appear in IEEE Journal on Selected Areas in Communications* ***(JSAC)***, 2016.

Enabling Accurate and Practical Online Flash Channel Modeling for Modern MLC NAND Flash Memory

Yixin Luo, Saugata Ghose, Yu Cai, Erich F. Haratsch, Onur Mutlu

3D NAND Flash Reliability I **[HPCA'18]**

- Yixin Luo, Saugata Ghose, Yu Cai, Erich F. Haratsch, and Onur Mutlu, **"HeatWatch: Improving 3D NAND Flash Memory Device Reliability by Exploiting Self-Recovery and Temperature-Awareness"** *Proceedings of the 24th International Symposium on High-Performance Computer Architecture* ***(HPCA)***, Vienna, Austria, February 2018. [Lightning Talk Video] [Slides (pptx) (pdf)] [Lightning Session Slides (pptx) (pdf)]

HeatWatch: Improving 3D NAND Flash Memory Device Reliability by Exploiting Self-Recovery and Temperature Awareness

Yixin Luo[†] Saugata Ghose[†] Yu Cai[‡] Erich F. Haratsch[‡] Onur Mutlu[§†]
[†]*Carnegie Mellon University* [‡]*Seagate Technology* [§]*ETH Zürich*

3D NAND Flash Reliability II [SIGMETRICS'18]

- Yixin Luo, Saugata Ghose, Yu Cai, Erich F. Haratsch, and Onur Mutlu, **"Improving 3D NAND Flash Memory Lifetime by Tolerating Early Retention Loss and Process Variation"** *Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems (**SIGMETRICS**)*, Irvine, CA, USA, June 2018. [Abstract]

Improving 3D NAND Flash Memory Lifetime by Tolerating Early Retention Loss and Process Variation

Yixin Luo[†] Saugata Ghose[†] Yu Cai[†] Erich F. Haratsch[‡] Onur Mutlu[§†]

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Thank you!

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